# **Version 12.1** Altera Product Catalog











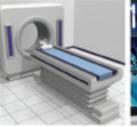






















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Altera delivers the broadest portfolio of custom logic devices—FPGAs, SoC FPGAs, ASICs, and CPLDs. This portfolio uniquely positions us to bring your great ideas to life faster, better, and more cost effectively. You can count on it.

#### **FPGAs**

Altera® FPGAs give you the best performance, the lowest power, and the widest range of densities. We have three classes of FPGAs to meet your needs, all optimized for value. Our flagship Stratix series delivers the industry's highest density and performance, while our Arria series is perfect for high-performance computation functionality and keeping costs down. Choose the Cyclone series for the lowest power and cost in high-volume, cost-sensitive applications.

#### SoC FPGAs

SoC FPGA devices, the newest members of the Cyclone V and Arria V families, consolidate two discrete devices into one, reducing system power, cost, and board size while increasing performance. SoC FPGAs integrate an ARM-based hard processor system (HPS) consisting of a dual-core ARM® processor, peripherals, and memory controllers with the FPGA fabric using a high-bandwidth interconnect backbone. We include a wide range of system peripherals, Altera intellectual property (IP), custom IP, and third-party IP that lets you quickly create a custom system using Altera design tools.



Highest performance designs, highest logic- and memory-density designs, and ASIC prototyping

Cost-sensitive applications that require high-performance computation functionality such as DSP

High-volume applications at the lowest cost and lowest power

### **ASICs**

If you are looking for an ASIC, stop here. Prototype your designs with our Stratix series FPGAs. Then take advantage of a seamless path to HardCopy series ASICs for volume production. You'll benefit from the shortest time to market, lowest risk, and lowest overall ASIC development costs.

#### **CPLDs**

For glue logic and any control functions, our non-volatile MAX series comprises the market's lowest cost CPLDs—a single-chip solution, great for interface bridging, level shifting, I/O expansion, and management of analog I/Os.

#### Productivity-Enhancing Design Software, Embedded Processing, IP, and Development Kits

With Altera, you get a complete design environment and a wide choice of design tools—all built to work together easily so your designs are up and running fast. You can try one of our training classes to get a jump start on your designs. Choose Altera and see how we enhance your productivity and make a difference to your bottom line.

Turn the page to get the specification overview of our latest FPGAs, ASICs, and CPLDs, as well as our extended line of products and services. Our broad product portfolio ensures you get the complete and best design solution.

# **Glossary**

Below is a glossary of helpful terms to bring you up to speed on Altera devices.

Term	Definition
Adaptive logic module (ALM)	Logic building block, used by some Altera devices, which provides advanced features with efficient logic utilization. Each ALM contains a variety of look-up table (LUT)-based resources that can be divided between two combinational adaptive LUTs (ALUTs).
Configuration via Protocol (CvP)	CvP is a configuration method that enables you to configure the FPGA using industry-standard protocols. Currently CvP supports the PCI Express® (PCIe®) protocol.
Embedded HardCopy Blocks	These metal-programmable hard IP blocks deliver up to 14M ASIC gates or up to 700K additional LEs to harden standard or logic-intensive applications.
Equivalent LE	Device density represented as a comparable amount of LEs, which uses the 4-input LUT as a basis.
Fractional phase-locked loops (fPLL)	A phase-locked loop (PLL) in the core fabric, fPLLs provide increased flexibility as an additional clocking source for the transceiver, replacing external voltage-controlled crystal oscillators (VCXOs).
Global clock networks	Global clocks can drive throughout the entire device, serving as low-skew clock sources for functional blocks such as ALMs, digital signal processing (DSP) blocks, TriMatrix memory blocks, and PLLs. See regional clocks and periphery clocks for more clock network information.
Hard processor system (HPS)	This processor system is a hardened component within the SoC FPGA, which comprises a dual-core ARM Cortex <sup>™</sup> -A9 MPCore <sup>™</sup> processor, a rich set of peripherals, and multiport memory controllers.
Logic element (LE)	This logic building block, used by some Altera devices, includes a 4-input LUT, a programmable register, and a carry chain connection. See device handbooks for more information.
Macrocells	Similar to LEs, this is the measure of density in MAX series CPLDs.
Memory logic array blocks (MLABs)	MLABs are dual-purpose blocks, configurable as regular logic array blocks or as memory blocks.
On-chip termination (OCT)	Support for driver impedance matching and series termination, which eliminates the need for external resistors, improves signal integrity, and simplifies board design. On-chip series, parallel, and differential termination resistors are configurable via Quartus II software.
Periphery clocks (PCLKs)	PCLKs are a collection of individual clock networks driven from the periphery of the device. PCLKs can be used instead of general-purpose routing to drive signals into and out of the device.
Plug & Play Signal Integrity	This capability, consisting of Altera's adaptive dispersion engine and hot socketing, lets you change the position of backplane cards on the fly, without having to manually configure your backplane equalization settings.
Programmable Power Technology	This feature automatically optimizes logic, DSP, and memory blocks for the lowest power at the required performance. Only the blocks with critical-path logic need to be in high-performance mode; all others are in low-power mode.
Real-time in-system programming (ISP)	This capability allows you to program a MAX II device while the device is still in operation. The new design only replaces the existing design when there is a power cycle to the device, so can perform in-field updates to the MAX II device at any time without affecting the operation of the whole system.
Regional clocks	Regional clocks are device quadrant-oriented and provide the lowest clock delay and skew for logic contained within a single device quadrant.
System on a chip (SoC)	An SoC is an embedded system that consists of a processor, peripherals, and custom hardware integrated on a single device.
Variable-precision blocks	These integrated blocks provide native support for signal processing of varying precisions—for example, 9x9, 27x27, and 18x36—in a sum or independent mode.

The following features, packages, and I/O matrices give you an overview of our devices. To get the full story, check out our online selector guide.

		Maximum Resource Count for	r Stratix V GT FPGAs (0.85 V) <sup>1</sup>			
		5SGTC5	5SGTC7			
	ALMs	160,400	234,720			
_	LEs (K)	425	622			
beed	Registers	641,600	938,880			
s pu	M20K memory blocks	2,304	2,560			
Density and Speed	M20K memory (Mb)	45	50			
Dens	MLAB memory (Mb)	4.9	7.16			
	Variable-precision DSP blocks	256	256			
	18 x 18 multipliers	512	512			
<u>_</u>	Global clock networks	16				
Architectural Features	Regional clock networks	92				
chite Feat	Design security	✓				
Ā _	HardCopy series device support	Contact	t Altera			
	I/O voltage levels supported (V)	1.2, 1.5, 1.5	8, 2.5, 3.3 <sup>2</sup>			
ıres	I/O standards supported	LVTTL, LVCMOS, PCI™, PCI-X™, LVDS, min Differential SSTL-18, Differential SSTL-2, Differential HSTL-18, SSTL-15 (I and II 1.2-V HSTL (I and II), 1.5-V HSTI	Differential HSTL-12, Differential HSTL-5, I), SSTL-18 (I and II), SSTL-2 (I and II),			
//O Features	LVDS channels, 1.4 Gbps (receive/transmit)	150	150			
/0 F	Embedded DPA circuitry		<i>'</i>			
_	ОСТ	Series, parallel,	and differential			
	Transceiver count (28.05 Gbps/14.1 Gbps)	4/32	4/32			
	PCIe hard IP blocks (Gen3)	1	1			
	Memory devices supported	DDR3, DDR2, QDR II, QDR II+, RLDRAM 2, RLDRAM 3				

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>&</sup>lt;sup>2</sup>3.3-V compliant, requires a 3-V power supply.

### **Stratix V GX FPGA Features**

			Maximum Resource Count for Stratix V GX FPGAs (0.85 V) <sup>1</sup>									
		5SGXA3	5SGXA4	5SGXA5	5SGXA7	5SGXA9	5SGXAB	5SGXB5	5SGXB6	5SGXB9	5SGXBB	
	ALMs	128,300	158,500	185,000	234,720	317,000	359,200	185,000	225,400	317,000	359,200	
	LEs (K)	340	420	490	622	840	952	490	597	840	952	
eed	Registers	513,200	634,000	740,000	938,880	1,268,000	1,436,800	740,000	901,600	1,268,000	1,436,800	
ds bi	M20K memory blocks	957	1,900	2,304	2,560	2,640	2,640	2,100	2,660	2,640	2,640	
Density and Speed	M20K memory (Mb)	19	37	45	50	52	52	41	52	52	52	
ensi	MLAB memory (Mb)	3.92	4.84	5.65	7.16	9.67	10.96	5.65	6.88	9.67	10.96	
Δ	Variable-precision DSP blocks	256	256	256	256	352	352	399	399	352	352	
	18 x 18 multipliers	512	512	512	512	704	704	798	798	704	704	
tural	Global clock networks		16									
Architectural Features	Regional clock networks	92										
₹	Design security		✓									
	I/O voltage levels supported (V)		1.2, 1.5, 1.8, 2.5, 3.3 <sup>2</sup>									
	I/O standards supported		SSTL-2,	Differential	HSTL-12, D	S, RSDS, LVPE ifferential HS 1.2-V HSTL (I	TL-5, Differe	ntial HSTL-1	18, SSTL-15	(I and II),		
//O Features	LVDS channels, 1.4 Gbps (receive/transmit)	174	174	210	210	210	210	150	150	150	150	
10	Embedded DPA circuitry					,	/					
	ОСТ				Se	ries, parallel,	and differer	ntial				
	Transceiver count (14.1 Gbps)	36	36	48	48	48	48	66	66	66	66	
	PCIe hard IP blocks (Gen3)	2	2	4	4	4	4	4	4	4	4	
	Memory devices supported			D	DR3, DDR2,	QDR II, QDR	II+, RLDRAN	/I 2, RLDRAI	M 3			

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

 $<sup>^2</sup>$  3.3-V compliant, requires a 3-V power supply.

## **Stratix V GS FPGA Features**

			Maximum Resource	Count for Stratix V	GS FPGAs (0.85 V) <sup>1</sup>			
		5SGSD3	5SGSD4	5SGSD5	5SGSD6	5SGSD8		
	ALMs	89,000	135,840	172,600	220,000	262,400		
	LEs (K)	236	360	457	583	695		
eed	Registers	356,000	543,360	690,400	880,000	1,049,600		
Density and Speed	M20K memory blocks	688	957	2,014	2,320	2,567		
	M20K memory (Mb)	13	19	39	45	50		
ensit	MLAB memory (Mb)	2.72	4.15	5.27	6.71	8.01		
Ω	Variable-precision DSP blocks	600	1,044	1,590	1,775	1,963		
	18 x 18 multipliers	1,200	2,088	3,180	3,550	3,926		
ural	Global clock networks	16						
Architectural Features	Regional clock networks	92						
Arch Fe	Design security	✓						
	I/O voltage levels supported (V)			1.2, 1.5, 1.8, 2.5, 3.3 <sup>2</sup>				
Ŋ	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-5, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II)						
I/O Features	LVDS channels, 1.4 Gbps (receive/transmit)	108	174	174	210	210		
0/	Embedded DPA circuitry			✓				
	ОСТ		Serie	s, parallel, and differen	itial			
	Transceiver count (14.1 Gbps)	24	36	36	48	48		
	PCIe hard IP blocks (Gen3)	1	1	1	2	2		
	Memory devices supported		DDR3, DDR2, DDR,	QDR II, QDR II+, RLDR	AM 2, RLDRAM 3			

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>&</sup>lt;sup>2</sup>3.3-V compliant, requires a 3-V power supply.

### **Stratix V E FPGA Features**

		Maximum Resource Count for Stratix V E FPGAs (0.85 V) <sup>1</sup>				
		5SEE9	5SEEB			
	ALMs	317,000	359,200			
	LEs (K)	840	952			
peed	Registers	1,268,000	1,436,800			
JS pu	M20K memory blocks	2,640	2,640			
ty ar	M20K memory (Mb)	52	52			
Density and Speed	MLAB memory (Mb)	9.67	10.96			
	Variable-precision DSP blocks	352	352			
	18 x 18 multipliers	704	704			
ıral	Global clock networks	16				
Architectural Features	Regional clock networks	92				
Arc	Design security		✓			
	I/O voltage levels supported (V)	1.2, 1.5, 1	.8, 2.5, 3.3 <sup>2</sup>			
I/O Features	I/O standards supported	Differential SSTL-18, Differential SSTL-2, Differ HSTL-18, SSTL-15 (I and II), SSTL-18 (I an	LVDS, RSDS, LVPECL, Differential SSTL-15, rential HSTL-12, Differential HSTL-5, Differential d II), SSTL-2 (I and II), 1.2-V HSTL (I and II), ), 1.8-V HSTL (I and II)			
I/0 F	LVDS channels, 1.4 Gbps (receive/transmit)	210	210			
	Embedded DPA circuitry		✓			
	ОСТ	Series, parallel	, and differential			
	Memory devices supported	DDR3, DDR2, QDR II, QDR	II+, RLDRAM 2, RLDRAM 3			

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>&</sup>lt;sup>2</sup>3.3-V compliant, requires a 3-V power supply.

### **Stratix IV GT FPGA Features**

			Maximum Re	source Count for	Stratix IV GT FP	GAs (0.95 V) <sup>1</sup>		
		EP4S40G2	EP4S40G5	EP4S100G2	EP4S100G3	EP4S100G4	EP4S100G5	
	ALMs	91,200	212,480	91,200	116,480	141,440	212,480	
	LEs (K)	228	531	228	291	354	531	
peed	Registers <sup>2</sup>	182,400	424,960	182,400	232,960	282,880	424,960	
od Sp	M9K memory blocks	1,235	1,280	1,235	936	1,248	1,280	
ty ar	M144K memory blocks	22	64	22	36	48	64	
Density and Speed	MLAB memory (Kb)	2,850	6,640	2,850	3,640	4,420	6,640	
	Embedded memory (Kb)	14,283	20,736	14,283	13,608	18,144	20,736	
	18 x 18 multipliers	1,288	1,024	1,288	832	1,024	1,024	
	Global clock networks			1	6			
es	Regional clock networks	64	88	64	88	88	88	
atur	Periphery clock networks	88	112	88	112	112	112	
Fe	PLLs	8	8	8	12	12	12	
Architectural Features	Design security	✓						
hite	HardCopy series device support	<del>-</del>						
Arc	Configuration file size (Mb)	95	172	95	172	172	172	
	Others		Plug & Play S	Signal Integrity, Pro	ogrammable Powe	r Technology		
	I/O voltage levels supported (V)			1.2, 1.5, 1.	8, 2.5, 3.3 <sup>3</sup>			
	I/O standards supported	Differential SS	TL-2, Differential H	5, mini-LVDS, RSDS, HSTL-12, Differenti d II), 1.2-V HSTL (I	al HSTL-15, Differe	ntial HSTL-18, SST	L-15 (I and II),	
S	Emulated LVDS channels, 1,100 Mbps	192	256	192	256	256	256	
Features	LVDS channels, 1,600 Mbps (receive/transmit)			46	/46			
10 F	Embedded DPA circuitry			•	/			
	ОСТ			Series, parallel,	and differential			
	Transceiver count <sup>4</sup> (11.3 Gbps/8.5 Gbps/6.5 Gbps)	12/12/12	12/12/12	24/0/12	24/8/16	24/8/16	32/0/16	
	PCIe hard IP blocks	2	2	2	4	4	4	
	Memory devices supported		DDR3, D	DDR2, DDR, QDR II,	QDR II+, RLDRAM	1 2, SDR		

<sup>&</sup>lt;sup>1</sup>Available in industrial temperatures only (0°C to 100°C).

<sup>&</sup>lt;sup>2</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which increases total register count by an additional 50 percent.

<sup>&</sup>lt;sup>3</sup> 3.3-V compliant, requires a 3-V power supply.

<sup>&</sup>lt;sup>4</sup>The total transceiver count is the sum of 11.3-Gbps plus 8.5-Gbps plus 6.5-Gbps transceivers.

### **Stratix IV GX FPGA Features**

			Maxim	ım Resource C	ount for Strati	x IV GX FPGAs	(0.9 V) <sup>1</sup>		
		EP4SGX70	EP4SGX110	EP4SGX180	EP4SGX230	EP4SGX290	EP4SGX360	EP4SGX530	
	ALMs	29,040	42,240	70,300	91,200	116,480	141,440	212,480	
	LEs (K)	73	106	176	228	291	354	531	
Density and Speed	Registers <sup>2</sup>	58,080	84,480	140,600	182,400	232,960	282,880	424,960	
nd S	M9K memory blocks	462	660	950	1,235	936	1,248	1,280	
ity a	M144K memory blocks	16	16	20	22	36	48	64	
Dens	MLAB memory (Kb)	908	1,320	2,197	2,850	3,640	4,420	6,640	
	Embedded memory (Kb)	6,462	8,244	11,430	14,283	13,608	18,144	20,736	
	18 x 18 multipliers	384	512	920	1,288	832	1,040³	1,024	
	Global clock networks				16				
es	Regional clock networks	64	64	64	64	88	88	88	
atur	Periphery clock networks	56	56	88	88	88	88	112	
al Fe	PLLs	4	4		8	12	12	12	
Architectural Features	Design security	✓							
chite	HardCopy series device support	<b>✓</b> <sup>4</sup>	<b>✓</b> <sup>4</sup>	<b>✓</b>	1	1	1	1	
₹	Configuration file size (Mb)	53	53	95	95	141	141	172	
	Others		Plug &	Play Signal Inte	grity, Programm	able Power Tech	nology		
	I/O voltage levels supported (V)			1.2	2, 1.5, 1.8, 2.5, 3	3.3 <sup>5</sup>			
	I/O standards supported	Differentia	l SSTL-2, Differe	ntial HSTL-12, D	ifferential HSTL-	15, Differential	TL-15, Differenti HSTL-18, SSTL-1 d II), 1.8-V HSTL	5 (I and II),	
	Emulated LVDS channels, 1,100 Mbps	128	128	192	192	256	256	256	
Features	LVDS channels, 1,600 Mbps (receive/transmit)	56/56	56/56	88/88	88/88	98/98	98/98	98/98	
/0 Fe	Embedded DPA circuitry								
_	ОСТ			Series, <sub> </sub>	parallel, and diff	erential			
	Transceiver count (8.5 Gbps/6.5 Gbps) <sup>6</sup>	16/8	16/8	24/12	24/12	32/16	32/16	32/16	
	PCIe hard IP blocks	2	2	2	2	4	4	4	
	Memory devices supported		DI	DR3, DDR2, DDR	, QDR II, QDR II-	+, RLDRAM 2, SI	DR		

<sup>&</sup>lt;sup>1</sup>Various packages and device options offer a variety of options to meet your design needs.

<sup>&</sup>lt;sup>2</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which increases the total register count by an additional 50 percent.

<sup>&</sup>lt;sup>3</sup> EP4SGX360N has 1,024 18x18 multipliers.

<sup>&</sup>lt;sup>4</sup> For EP4SGX70D and EP4SGX110D/F devices.

 $<sup>^{\</sup>scriptsize 5}$  3.3-V compliant, requires a 3-V power supply.

 $<sup>^6\</sup>mathrm{The}$  total transceiver count is the sum of 8.5-Gbps transceivers plus 6.5-Gbps transceivers.

### **Stratix IV E FPGA Features**

		Ma	ximum Resource Count fo	or Stratix IV E FPGAs (0.9	9 V)
		EP4SE230	EP4SE360	EP4SE530	EP4SE820
	ALMs	91,200	141,440	212,480	325,220
	LEs (K)	228	354	531	813
Density and Speed	Registers <sup>1</sup>	182,400	282,880	424,960	650,440
nd S	M9K memory blocks	1,235	1,248	1,280	1,610
ity a	M144K memory blocks	22	48	64	60
Dens	MLAB memory (Kb)	2,850	4,420	6,640	10,163
	Embedded memory (Kb)	14,283	18,144	20,736	23,130
	18 x 18 multipliers	1,288	1,040	1,024	960
	Global clock networks		1	6	
es	Regional clock networks	64	88	88	88
atur	Periphery clock networks	88	88	112	132
al Fe	PLLs	4	12	12	12
Architectural Features	Design security		<b>✓</b>	•	
chit	Configuration file size (Mb)	95	141	172	230
₹	HardCopy series device support		✓	•	
	Others		Programmable Po	ower Technology	
	I/O voltage levels supported (V)		1.2, 1.5, 1.	8, 2.5, 3.3²	
es	I/O standards supported	Differential SSTL-2, Diff	CI-X, LVDS, mini-LVDS, RSDS, erential HSTL-12, Differentia L-2 (I and II), 1.2-V HSTL (I	al HSTL-15, Differential HST	L-18, SSTL-15 (I and II),
//O Features	Emulated LVDS channels, 1,100 Mbps	128	256	256	288
0/I	LVDS channels, 1,600 Mbps (receive/transmit)	56/56	88/88	112/112	132/132
	Embedded DPA circuitry		<b>√</b>	•	
	ОСТ		Series, parallel,	and differential	
	Memory devices supported		DDR3, DDR2, DDR, QDR II,	QDR II+, RLDRAM 2, SDR	

<sup>&</sup>lt;sup>1</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which can increase the total register count by an additional 50 percent.

 $<sup>^{2}</sup>$  3.3-V compliant, requires a 3-V power supply.

### **Stratix III L FPGA Features**

			Maximum Res	ource Count for	Stratix III L FPGA	s (1.1 V, 0.9 V)	
		EP3SL50	EP3SL70	EP3SL110	EP3SL150	EP3SL200	EP3SL340
	ALMs	19,000	27,000	42,600	56,800	79,560	135,200
	LEs (K)	47.5	67.5	107.5	143	199	338
peed	Registers <sup>1</sup>	38,000	54,000	85,200	113,600	159,120	270,400
nd S	M9K memory blocks	108	150	275	355	468	1,040
ity a	M144K memory blocks	6	6	12	16	36	48
Density and Speed	MLAB memory (Kb) <sup>2</sup>	297	422	672	891	1,250	2,110
	Embedded memory (Kb)	1,836	2,214	4,203	5,499	9,396	16,272
	18 x 18 multipliers	216	288	288	384	576	576
	Global clock networks			1	6		
es	Regional clock networks	48	48	48	48	88	88
atur	Periphery clock networks	104	104	208	208	208	208
al Fe	PLLs	4	4	8	8	12	12
Architectural Features	Design security			•	/		
chit	Configuration file size (Mb)	22	22	47	47	66	120
₹	HardCopy series device support			•	/		
	Others			Programmable P	ower Technology		
	I/O voltage levels supported (V)			1.2, 1.5, 1.	.8, 2.5, 3.3		
Se	I/O standards supported		SSTL-18 (I and II), S	SSTL-15 (I and II), S	Differential SSTL-2, SSTL-2 (I and II), 1. PCI-X 1.0, LVTTL, L	5-V HSTL (I and II)	
//O Features	Emulated LVDS channels, 1,100 Mbps	56	56	88	88	112	137
0/I	LVDS channels, 1,600 Mbps (receive/transmit)	56/56	56/56	88/88	88/88	112/112	132/132
	Embedded DPA circuitry			•	/		
	ОСТ			Series, parallel,	and differential		
	Memory devices supported		DD	R3, DDR2, DDR, QI	DR II, RLDRAM 2, S	DR	

<sup>&</sup>lt;sup>1</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which increases the total register count by an additional 50 percent.

 $<sup>^2\</sup>mbox{The size}$  of the MLAB ROM is twice the size of the MLAB RAM.

### **Stratix III E FPGA Features**

		Max	ximum Resource Count f	or Stratix III E FPGAs (1.	1 V)
		EP3SE50	EP3SE80	EP3SE110	EP3SE260
	ALMs	19,000	32,000	42,600	101,760
	LEs (K)	47.5	80	107.5	254
Density and Speed	Registers <sup>1</sup>	38,000	64,000	85,200	203,520
ls pu	M9K memory blocks	400	495	639	864
ity a	M144K memory blocks	12	12	16	48
Dens	MLAB memory (Kb) <sup>2</sup>	297	500	672	1,594
	Embedded memory (Kb)	5,328	6,183	8,055	14,688
	18 x 18 multipliers	384	672	896	768
	Global clock networks		1	6	
es	Regional clock networks	48	48	48	88
atur	Periphery clock networks	104	208	208	208
Architectural Features	PLLs	4	8	8	12
sctur	Design security				
chite	Configuration file size (Mb)	26	48	48	93
Ā	HardCopy series device support				
	Others		Programmable P	ower Technology	
	I/O voltage levels supported (V)		1.2, 1.5, 1.	.8, 2.5, 3.3	
se	I/O standards supported		ECL, Differential SSTL-18, I and II), SSTL-15 (I and II), S 1.8-V HSTL (I and II), PCI,	SSTL-2 (I and II), 1.5-V HST	
Features	Emulated LVDS channels, 1,100 Mbps	56	88	88	112
0/I	LVDS channels, 1,600 Mbps (receive/transmit)	56/56	88/88	88/88	112/112
	Embedded DPA circuitry			/	
	ОСТ		Series, parallel,	and differential	
	Memory devices supported		DDR3, DDR2, DDR, QI	DR II, RLDRAM 2, SDR	

<sup>&</sup>lt;sup>1</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which increases the total register count by an additional 50 percent.

<sup>&</sup>lt;sup>2</sup>The size of the MLAB ROM is twice the size of the MLAB RAM.

### **Stratix II GX FPGA Features**

		Max	imum Resource Count fo	r Stratix II GX FPGAs (1.	2 V) <sup>1</sup>		
		EP2SGX30	EP2SGX60	EP2SGX90	EP2SGX130		
	ALMs	13,552	24,176	36,384	53,016		
	LEs (K)	34	60	91	132.5		
peed	Registers <sup>2</sup>	27,104	48,352	72,708	106,032		
Density and Speed	M512 memory blocks	202	329	488	699		
ity a	M4K memory blocks	144	255	408	609		
Dens	M512K memory blocks	1	2	4	6		
	Embedded memory (Kb)	1,338	2,485	4,415	6,590		
	18 x 18 multipliers	64	144	192	252		
	Global clock networks		4	8			
ures	Regional clock networks	48					
Architectural Features	PLLs	4	8	8	8		
ural	Design security			•			
itect	Configuration file size (Mb)	10	17	28	40		
Arch	HardCopy series device support	_	_	-	_		
	Others		Plug & Play Si	gnal Integrity			
	I/O voltage levels supported (V)		1.5, 1.8,	2.5, 3.3			
	I/O standards supported		perTransport <sup>™</sup> , Differential S (I and II), 1.5-V HSTL (I and II				
//O Features	LVDS channels, 1,000 Mbps (receive/transmit)	31/29	42/42	59/59	73/71		
1/0 F	Embedded DPA circuitry		✓	<b>,</b>			
	ОСТ		Series and	differential			
	Transceiver count (6.375 Gbps)	8	12	16	20		
	Memory devices supported		DDR2, DDR, QDR I	I, RLDRAM 2, SDR			

<sup>&</sup>lt;sup>1</sup> Various packages offer a variety of options to meet your design needs.

<sup>&</sup>lt;sup>2</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which increases the total register count by an additional 50 percent.

### **Stratix FPGA Series Package and I/O Matrices**

			Stratix V GS,	GX, GT, and E FPG	iAs (0.85 V)		
				FBGA (F)			
	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,517 pin</b> 40 x 40 (mm) 1.0-mm pitch	<b>1,517 pin</b> 40 x 40 (mm) 1.0-mm pitch	<b>1,760 pin</b> 42.5 x 42.5 (mm) 1.0-mm pitch	<b>1,932 pin</b> 45 x 45 (mm) 1.0-mm pitch
5SGSD3	360, 90, 12 <sup>1</sup>	432, 108, 24					
5SGSD4	360, 90, 12¹	432, 108, 24		696, 174, 36			
5SGSD5		552, 138, 24		696, 174, 36			
5SGSD6				696, 174, 36			840, 210, 48
5SGSD8				696, 174, 36			840, 210, 48
5SGXA3	360, 90, 12 <sup>1</sup>	432, 108, 24	432, 108, 36	696, 174, 36			
5SGXA4		552, 138, 24	432, 108, 36	696, 174, 36			
5SGXA5		552, 138, 24	432, 108, 36	696, 174, 36	600, 150, 48		840, 210, 48
5SGXA7		552, 138, 24	432, 108, 36	696, 174, 36	600, 150, 48		840, 210, 48
5SGXA9				696, 174, 36²			840, 210, 48
5SGXAB				696, 174, 36²			840, 210, 48
5SGXB5				432, 108, 66		600, 150, 66	
5SGXB6				432, 108, 66		600, 150, 66	
5SGXB9						600, 150, 66²	
5SGXBB						600, 150, 66²	
5SGTC5					600, 150, 36³		
5SGTC7					600, 150, 36 <sup>3</sup>		
5SEE9				696, 174, 0²			840, 210, 0
5SEEB				696, 174, 0²			840, 210, 0

<sup>&</sup>lt;sup>1</sup>Hybrid package (flip chip) FBGA: 33 x 33 (mm) 1.0-mm pitch.

264, 66, 24 Numbers indicate GPIO count, LVDS count, and transceiver count.

<sup>&</sup>lt;sup>2</sup>Hybrid package (flip chip) FBGA: 45 x 45 (mm) 1.0-mm pitch.

<sup>&</sup>lt;sup>3</sup> GX–GT migration. Unused transceiver channels connected to power/ground.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). User I/Os may be less than labelled for vertical migration.

Stratix series devices are offered in commercial and industrial temperatures and RoHS-compliant packages. Stratix IV GT devices are only offered in industrial temperatures (0°C to 100°C).

### **Stratix Series Package and I/O Matrices**

	Stratix IV GT I	FPGAs (0.95 V)
	FBGA	A (F) <sup>1</sup>
	<b>1,517 pin</b> 40 x 40 (mm) 1.0-mm pitch	<b>1,932 pin</b> 45 x 45 (mm) 1.0-mm pitch
EP4S40G2	646 12+12+12	
EP4S40G5	646 <sup>2</sup> 12+12+12	
EP4S100G2	646 24+0+12	
EP4S100G3		769 24+8+16
EP4S100G4		769 24+8+16
EP4S100G5	646 <sup>2</sup> 24+0+12	769 32+0+16

<sup>&</sup>lt;sup>1</sup>FineLine ball grid array.

Values on top indicate available user I/O pins; values on bottom indicate the 11.3-Gbps plus 8.5-Gbps plus 6.5-Gbps transceiver count.

🟅 Vertical migration (same Vcc, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table. Stratix series devices are offered in commercial and industrial temperatures and RoHS-compliant packages. Stratix IV GT devices are only offered in industrial temperatures (0°C to 100°C).

			Stratix IV GX	FPGAs (0.9 V) <sup>1</sup>			
	FBGA (F)						
	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	29 x 29 (mm) 35 x 35 (mm) 35 x 35 (mm) 40 x 40 (mm) 42.5 x 42.5 (mm)		42.5 x 42.5 (mm)	<b>1,932 pin</b> 45 x 45 (mm) 1.0-mm pitch		
EP4SGX70	368 8+0		480 16+8				
EP4SGX110	368 8+0	368 16+0	480 16+8				
EP4SGX180	368 8+0	560 16+0	560 16+8	736 24+12			
EP4SGX230	368 8+0	560 16+0	560 16+8	736 24+12			
EP4SGX290	288² 16+0	560 16+0	560 16+8	736 24+12	864 24+12	904 32+16	
EP4SGX360	288² 16+0	560 16+0	560 16+8	736 24+12	864 24+12	904 32+16	
EP4SGX530			560³ 16+8	736³ 24+12	864 24+12	904 32+16	

<sup>&</sup>lt;sup>1</sup> I/O count does not include dedicated clock inputs that can be used as data inputs.

Values on top indicate available user I/O pins; values at the bottom indicate the 8.5-Gbps plus 6.5-Gbps transceiver count.

I Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table. Stratix series devices are offered in commercial and industrial temperatures and RoHS-compliant packages. Stratix IV GT devices are only offered in industrial temperatures (0°C to 100°C).

<sup>&</sup>lt;sup>2</sup>Hybrid package (flip chip) FBGA: 42.5 x 42.5 (mm) 1.0-mm pitch.

<sup>&</sup>lt;sup>2</sup>Hybrid package (flip chip) FBGA: 35 x 35 (mm) 1.0-mm pitch.

<sup>&</sup>lt;sup>3</sup> Hybrid package (flip chip) FBGA: 42.5 x 42.5 (mm) 1.0-mm pitch.

### **Stratix Series Package and I/O Matrices**

				FBGA (F)		
		<b>484 pin</b> 23 x 23 (mm) 1.0-mm pitch	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch	) 40 x 40 (m	nm) 42.5 x 42.5 (mm)
	EP4SE820			736³	960³	1,104
Stratix IV E	EP4SE530			736³	960³	960
FPGAs	EP4SE360		480²	736		
	EP4SE230		480			
	EP3SE260 <sup>3</sup>		480²	736	960	
Stratix III E	EP3SE110		480	736		
FPGAs <sup>1</sup>	EP3SE80		480	736		
	EP3SE50	288	480			
	EP3SL340			736³	960	1,104
	EP3SL200		480²	736	960	1
Stratix III L	EP3SL150		480	736		
FPGAs <sup>1</sup>	EP3SL110		480	736		
	EP3SL70	288	480			
	EP3SL50	288	480			

<sup>&</sup>lt;sup>1</sup> I/O count does not include dedicated clock inputs that can be used as data inputs.

288 Number indicates available user I/O pins.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

Stratix series devices are offered in commercial and industrial temperatures and RoHS-compliant packages. Stratix IV GT devices are only offered in industrial temperatures (0°C to 100°C).

	Str	atix II GX FPGAs (1.2	V)¹
		FBGA (F)	
	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,508 pin</b> 40 x 40 (mm) 1.0-mm pitch
EP2SGX30	361 <b>-</b> 8		
EP2SGX60	364 8	534 12	
EP2SGX90		558 12	650 16
EP2SGX130			734 20

<sup>&</sup>lt;sup>1</sup> I/O count does not include dedicated clock inputs that can be used as data inputs.

<sup>&</sup>lt;sup>2</sup>Hybrid package (flip chip) FBGA: 35 x 35 (mm) 1.0-mm pitch.

<sup>&</sup>lt;sup>3</sup> Hybrid package (flip chip) FBGA: 42.5 x 42.5 (mm) 1.0-mm pitch.

Values on top indicate available user I/O pins; values on bottom indicate the 6.35-Gbps transceiver count.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

Stratix series devices are offered in commercial and industrial temperatures and RoHS-compliant packages. Stratix IV GT devices are only offered in industrial temperatures (0°C to 100°C).

# **HardCopy IV ASIC Features**

		ı	Maximum Resource	Count for HardCo	opy IV ASICs (0.9 V	")				
		HC4GX15	HC4GX25	HC4GX35	HC4E25	HC4E35				
	Usable ASIC gates	9.4M	11.5M	11.5M	9.4M	14.6M				
eq	LEs (K)	354	532	532	354	813				
Spe	M9K memory blocks	660	936	1,280	864	1,320				
' and	M144K memory blocks	24	36	64	32	48				
Density and Speed	MLAB memory	Implemented in HCells								
De	Embedded memory (Kb)	9,396	13,608	20,736	12,384	18,792				
	18 x 18 multipliers <sup>1</sup>	1,288	1,288	1,288	1,288	1,040				
	PLLs	3	6	8	4	12				
	Design security <sup>2</sup>			✓						
Architectural Features	Stratix series prototyping support	EP4SGX70 EP4SGX110 EP4SGX180 EP4SGX230 EP4SGX290 EP4SGX360	EP4SGX110 EP4SGX180 EP4SGX230 EP4SGX290 EP4SGX360 EP4SGX530	EP4SGX180 EP4SGX230 EP4SGX290 EP4SGX360 EP4SGX530	EP4SE360 EP4SE360	EP4SE360 EP4SE530 EP4SE820				
	I/O voltage levels supported (V)			1.2, 1.5, 1.8, 2.5, 3.3	3					
	I/O standards supported	Differentia Differe	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II)							
ures	Emulated LVDS channels, 1,100 Mbps	184	236	280	120	216				
I/O Features	LVDS channels, 1,250 Mbps (receive/transmit)	28/28	44/44	88/88	56/56	88/88				
_	Embedded DPA circuitry			✓						
	OCT			Series and differentia	l					
	Transceiver count (6.5 Gbps/6.5 Gbps, PMA only)	8/0	16/8	24/12	_	_				
	PCIe hard IP blocks	1	2	2	_	_				
External Memory Interfaces	Memory devices supported		DDR3, DDR	2, DDR, QDR II, RLDF	RAM 2, SDR					

<sup>&</sup>lt;sup>1</sup>Implemented in HCells.

<sup>&</sup>lt;sup>2</sup>Since all HardCopy ASICs contain hard-wired logic, they are inherently secure. <sup>3</sup>3.3-V compliant, requires a 3-V power supply.

# **HardCopy III ASIC Features**

		HardCopy III	ASICs (0.9 V)
		HC325	HC335
	Usable ASIC gates	7.0M	7.0M
eq	LEs (K)	338	338
Density and Speed	M9K memory blocks	864	1,040
, and	M144K memory blocks	32	48
nsity	MLAB memory	Implemente	ed in HCells
De	Embedded memory (Kb)	12,384	16,272
	18 x 18 multipliers <sup>1</sup>	896	1,040
S	PLLs	8	12
ature	Design security <sup>2</sup>		<b>,</b>
Architecural Features	Stratix series prototyping support	EP3SE110 EP3SL110 EP3SL150 EP3SL200 EP3SE260 EP3SL340	EP3SE110 EP3SL150 EP3SL200 EP3SE260 EP3SL340
	I/O voltage levels supported (V)	1.2, 1.5, 1.	EP3SL200 EP3SE260
I/O Features	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-L Differential SSTL-18, Differential SSTL-2, D Differential HSTL-18, SSTL-15 (I and II 1.2-V HSTL (I and II), 1.5-V HST	Differential HSTL-12, Differential HSTL-15, I), SSTL-18 (I and II), SSTL-2 (I and II),
0 Fe	Emulated LVDS channels, 1,100 Mbps	120	216
À	LVDS channels, 1,250 Mbps (receive/transmit)	56/56	88/88
	Embedded DPA circuitry	✓	✓
	ОСТ	Series and	differential
External Memory Interfaces	Memory devices supported	DDR3, DDR2, DDR, QI	DR II, RLDRAM 2, SDR

<sup>&</sup>lt;sup>1</sup>Implemented in HCells.

 $<sup>^2\</sup>mathrm{Since}$  all HardCopy ASICs contain hard-wired logic, they are inherently secure.

<sup>&</sup>lt;sup>3</sup>3.3-V compliant, requires a 3-V power supply.

# **HardCopy II ASIC Features**

				HardCopy II ASICs				
		HC210W	HC210	HC220	HC230	HC240		
	Usable ASIC gates	1.0M	1.0M	1.9M	2.9M	3.6M		
pa	LEs (K)	91	91	133	179	179		
Density and Speed	M512 memory blocks		Not av	railable in HardCopy II	ASICs			
/ and	M4K memory blocks	190	190	408	614	768		
ensity	M512K memory blocks	0	0	2	6	9		
Ď	Embedded memory (Kb)	855	855	2,988	6,219	8,640		
	18 x 18 multipliers <sup>1</sup>	192	192	252	384	384		
_	PLLs	4	4	4	8	12		
ctura	Design security <sup>2</sup>	✓						
Architectural Features	Stratix series prototyping support	EP2S30 EP2S60 EP2S90	EP2S30 EP2S60 EP2S90	EP2S60 EP2S90 EP2S130	EP2S90 EP2S130 EP2S180	EP2S180		
	I/O voltage levels supported (V)			1.5, 1.8, 2.5, 3.3				
I/O Features	I/O standards supported		Differenti Differential HS	10S, PCI, PCI-X 1.0, LV ial SSTL-18, Differentia IL SSTL-18 (I and II), S: II), 1.8-V HSTL (I and I	al SSTL-2, STL-2 (I and II),			
I/0 Fe	LVDS channels, 1,040 Mbps (receive/transmit)	17/13	21/19	30/29	46/44	116/116		
	Embedded DPA circuitry			✓				
	ОСТ			Series and differential				
External Memory Interfaces	Memory devices supported		DDR2,	DDR, QDR II, RLDRAM	2, SDR			

<sup>&</sup>lt;sup>1</sup>Implemented in HCells.

<sup>&</sup>lt;sup>2</sup>Since all HardCopy ASICs contain hard-wired logic, they are inherently secure.

## **HardCopy Series Package and I/O Matrices**

				HardCopy IV	ASICs (0.9 V)			
				FBG	A (F)			
	<b>484 (WF¹)</b> 23 x 23 (mm) 1.0-mm pitch	<b>484 (FF²)</b> 23 x 23 (mm) 1.0-mm pitch	<b>780 (WF)</b> 29 x 29 (mm) 1.0-mm pitch	<b>780 (LF³)</b> 29 x 29 (mm) 1.0-mm pitch	<b>780 (FF)</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,152 (LF)</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,152 (FF)</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,517 (FF)</b> 40 x 40 (mm) 1.0-mm pitch
HC4GX15				372 8+0				
HC4GX25				289 16+0		564 16+0	564 16+8	
HC4GX35							564 16+8	744 24+12
HC4E25	296	296	392		488			
HC4E35							744	880

<sup>&</sup>lt;sup>1</sup> WF = Wire bond.

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Values on top indicate available user I/O pins; values at the bottom indicate the 6.5-Gbps physical media attachment (PMA) and physical coding sublayer (PCS) plus the 6.5-Gbps PMA-only transceiver count.

All HardCopy series devices are offered in commercial, industrial, and extended temperature grades. Package options include leaded, RoHS-compliant, lidless, or lidded.

	HardCopy III ASICs (0.9 V)									
		FBGA (F)								
	<b>484 (WF)</b> 23 x 23 (mm) 1.0-mm pitch	<b>484 (FF)</b> 23 x 23 (mm) 1.0-mm pitch	<b>780 (WF)</b> 29 x 29 (mm) 1.0-mm pitch	<b>780 (FF)</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,152 (FF)</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,517 (FF)</b> 40 x 40 (mm) 1.0-mm pitch				
HC325	296	296	392	488						
HC335					744	880				

<sup>636</sup> Number indicates available user I/O pins.

All HardCopy series devices are offered in commercial, industrial, and extended temperature grades. Package options include leaded, RoHS-compliant, lidless, or lidded.

		HardCopy II ASICs (1.2 V)									
		FBGA (F)									
	<b>484 (WF)</b> 23 x 23 (mm) 1.0-mm pitch	<b>484 (F¹)</b> 23 x 23 (mm) 1.0-mm pitch	<b>672 (F)</b> 27 x 27 (mm) 1.0-mm pitch	<b>780 (F)</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,020 (F)</b> 33 x 33 (mm) 1.0-mm pitch	<b>1,508 (F)</b> 40 x 40 (mm) 1.0-mm pitch					
IC210W	308										
C210		334									
IC220			492	494							
IC230					698						
IC240					742	951					

F = Performance-optimized flip chip.

All HardCopy series devices are offered in commercial, industrial, and extended temperature grades. Package options include leaded, RoHS-compliant, lidless, or lidded.

<sup>&</sup>lt;sup>2</sup> FF = Performance-optimized flip chip.

<sup>&</sup>lt;sup>3</sup>LF = Cost-optimized flip chip.

<sup>636</sup> Number indicates available user I/O pins.

### **Arria V GX FPGA Features**

			Maxim	num Resourc	e Count for	Arria V GX F	PGAs (1.1 V,	1.15 V) <sup>1</sup>	
		5AGXA1	5AGXA3	5AGXA5	5AGXA7	5AGXB1	5AGXB3	5AGXB5	5AGXB7
	ALMs	28,302	58,900	71,698	91,680	113,208	136,880	158,491	190,240
	LEs (K)	75	156	190	242	300	362	420	504
Density and Speed	Registers	113,208	235,600	286,792	366,720	452,832	547,520	633,964	760,960
nd S	M10K memory blocks	800	1,051	1,180	1,366	1,510	1,726	2,054	2,414
ity a	M10K memory (Kb)	8,000	10,510	11,800	13,660	15,100	17,260	20,540	24,140
Oens	MLAB memory (Kb)	463	961	1,173	1,448	1,852	2,098	2,532	2,906
	Variable-precision DSP blocks	240	396	600	800	920	1,045	1,092	1,156
	18 x 18 multipliers	480	792	1,200	1,600	1,840	2,090	2,184	2,312
<del>-</del>	Global clock networks					16			
chitectur Features	PLLs <sup>2</sup>	10	10	12	12	12	12	16	16
Architectural Features	Configuration file size (Mb)	TBD	TBD	TBD	TBD	TBD	TBD	TBD	TBD
Ar	Design security	n security 🗸							
	I/O voltage levels supported (V)		1.2, 1.5, 1.8, 2.5, 3.0, 3.3						
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II)							
	LVDS transmitter (TX)	70	70	120	120	160	160	160	160
S	LVDS receiver (RX)	80	80	136	136	176	176	176	176
I/O Features	Embedded DPA circuitry					1			ı
I/0 Fe	ОСТ				Series and	d differential			
	Programmable drive strength					/			
	Transceiver count (6.5536 Gbps)	9	9	24	24	24	24	36	36
	PCIe hard IP blocks (Gen2 x4)	1	1	2	2	2	2	2	2
	Hard memory controllers <sup>3</sup>	2	2	4	4	4	4	4	4
External Memory Interfaces	Memory devices supported		DDR3,	DDR2, DDR II	+ <sup>4</sup> , QDR II, QE	DR II+, RLDRA	M 2, LPDDR <sup>4</sup> , I	LPDDR2⁴	

<sup>&</sup>lt;sup>1</sup>All data is preliminary. Various packages and device offerings offer a variety of options to meet your design needs.

 $<sup>^{2}\,\</sup>mbox{The PLL}$  count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit error correction code (ECC) support.

<sup>&</sup>lt;sup>4</sup>These memory interfaces are not available as Altera IP.

### **Arria V GT FPGA Features**

		Maxim	um Resource Count for A	Arria V GT FPGAs (1.1 V,	1.15 V) <sup>1</sup>			
		5AGTC3	5AGTC7	5AGTD3	5AGTD7			
	ALMs	58,900	91,680	136,880	190,240			
	LEs (K)	156	156 242 362		504			
Density and Speed	Registers	235,600	366,720	547,520	760,960			
	M10K memory blocks	1,051	1,366	1,726	2,414			
ity a	M10K memory (Kb)	10,510	13,660	17,260	24,140			
Dens	MLAB memory (Kb)	961	1,448	2,098	2,906			
٥	Variable-precision DSP blocks	396	800	1,045	1,156			
	18 x 18 multipliers	792	1,600	2,090	2,312			
Б	Global clock networks		1	6				
Architectural Features	PLLs <sup>2</sup>	10	12	12	16			
chite Feat	Configuration file size (Mb)	TBD	TBD	TBD	TBD			
Ā	Design security	/						
	I/O voltage levels supported (V)		1.2, 1.5, 1.8, 2.5, 3.0, 3.3					
	I/O standards supported	Differential SS Differentia	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II)					
	LVDS transmitter (TX)	70	120	160	160			
ıres	LVDS receiver (RX)	80	136	176	176			
I/O Features	Embedded DPA circuitry		•	/				
0/	ОСТ		Series and	differential				
	Programmable drive strength		,	/				
	Transceiver count (10.3125 Gbps/6.5536 Gbps) <sup>3</sup>	4/3	12/6	12/6	20/6			
	PCIe hard IP blocks (Gen2 x4)	1	2	2	2			
	Hard memory controllers <sup>4</sup>	2	4	4	4			
External Memory Interfaces	Memory devices supported	DDR3, [	DDR2, DDR II+5, QDR II, QD	R II+, RLDRAM 2, LPDDR⁵, I	.PDDR2 <sup>5</sup>			

<sup>&</sup>lt;sup>1</sup>All data is preliminary. Various packages and device options offer a variety of options to meet your design needs.

 $<sup>^2\</sup>mbox{The PLL}$  count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup>One pair of 10-Gbps transceiver channels can be configured as three 6-Gbps transceiver channels.

<sup>&</sup>lt;sup>4</sup>With 16- and 32-bit ECC support.

<sup>&</sup>lt;sup>5</sup>These memory interfaces are not available as Altera IP.

### **Arria V GZ FPGA Features**

		Max	imum Resource Count f	Maximum Resource Count for Arria V GZ FPGAs (0.85 V) <sup>1</sup>			
		5AGZE1	5AGZE3	5AGZE5	5AGZE7		
	ALMs	83,020	135,840	150,960	169,800		
	LEs (K)	220	360	400	450		
Density and Speed	Registers	332,080	543,360	603,840	679,200		
	M20K memory blocks	585	957	1,440	1,700		
ity aı	M20K memory (Kb)	11,700	19,140	28,800	34,000		
Sens	MLAB memory (Kb)	2,594	4,245	4,718	5,306		
_	Variable-precision DSP blocks	800	1,044	1,092	1,139		
	18 x 18 multipliers	1,600	2,088	2,184	2,278		
-B	Global clock networks		1	6			
Architectural Features	PLLs <sup>2</sup>	20	20	24	24		
chite Feat	Configuration file size (Mb)	TBD	TBD	TBD	TBD		
Ar	Design security	·					
	I/O voltage levels supported (V)		1.2, 1.5, 1.8,	2.5, 3.0, 3.3 <sup>3</sup>			
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II)					
es	LVDS transmitter (TX)	97	97	157	157		
I/O Features	LVDS receiver (RX)	102	102	161	161		
I/0 F	Embedded DPA circuitry		•	/			
	ОСТ		Series and	differential			
	Programmable drive strength		•	/			
	Transceiver count (12.5 Gbps)	24	24	36	36		
	PCIe hard IP blocks (Gen2 x4)	1	1	1	1		
External Memory Interfaces	Memory devices supported	DDR3, DDR2, QDR II, QDR II+, RLDRAM 2, RLDRAM 3					

<sup>&</sup>lt;sup>1</sup> All data is preliminary. Various packages and device options offer a variety of options to meet your design needs.

 $<sup>^2\,\</sup>mbox{The PLL}$  count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> 3.3-V compliant, requires a 3-V power supply.

### **Arria V SX SoC FPGA Features**

		Maximum Resource Count for	Arria V SX SoC FPGAs (1.1 V) <sup>1</sup>		
		5ASXB3	5ASXB5		
	ALMs	132,075	174,340		
	LEs (K)	350	462		
Density and Speed	Registers	528,300	697,360		
	M10K memory blocks	1,729	2,282		
ity a	M10K memory (Kb)	17,288	22,820		
Sens	MLAB memory (Kb)	2,014	2,658		
_	Variable-precision DSP blocks	809	1,068		
	18 x 18 multipliers	1,618	2,186		
	Processor cores (ARM Cortex-A9)	Dual	Dual		
la .	Global clock networks	16	5		
Architectural Features	PLLs <sup>2</sup> (FPGA)	10	14		
chite Feat	PLLs <sup>2</sup> (HPS)	3	3		
Ā	Configuration file size (Mb)	TBD	TBD		
	Design security	✓			
	I/O voltage levels supported (V)	1.2, 1.5, 1.8, 2.5, 3.0, 3.3			
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II)			
	LVDS transmitter (TX)	120	120		
	LVDS receiver (RX)	120	120		
res	Embedded DPA circuitry	<b>✓</b>			
eatu	ОСТ	Series and o	lifferential		
I/O Features	Programmable drive strength	✓			
_	Transceiver count (6.5536 Gbps)	30	30		
	PCIe hard IP blocks (Gen2 x4)	2	2		
	GPIOs (FPGA)	528	528		
	GPIOs (HPS)	216	216		
	Hard memory controllers <sup>3</sup> (FPGA)	3	3		
	Hard memory controllers <sup>3</sup> (HPS)	1	1		
External Memory Interfaces	Memory devices supported	DDR3, DDR2, DDR, QDR II, QDR	II+, RLDRAM 2, LPDDR2 <sup>4</sup> , SDR		

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

 $<sup>^{2}\,\</sup>mbox{The PLL}$  count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit ECC support.

<sup>&</sup>lt;sup>4</sup>These memory interfaces are not available as Altera IP.

### **Arria V ST SoC FPGA Features**

		Maximum Resource Count for	Arria V ST SoC FPGAs (1.1 V) <sup>1</sup>		
		5ASTD3	5ASTD5		
	ALMs	132,075	174,340		
70	LEs (K)	350	462		
pee	Registers	528,300	697,360		
Density and Speed	M10K memory blocks	1,729	2,282		
ity a	M10K memory (Kb)	17,288	22,820		
Dens	MLAB memory (Kb)	2,014	2,658		
	Variable-precision DSP blocks	809	1,068		
	18 x 18 multipliers	1,618	2,186		
	Processor cores (ARM Cortex-A9)	Dual	Dual		
<del>.</del>	Global clock networks	16	5		
Architectural Features	PLLs <sup>2</sup> (FPGA)	10	14		
hite eat	PLLs <sup>2</sup> (HPS)	3	3		
Arc	Configuration file size (Mb)	TBD	TBD		
	Design security	<b>✓</b>			
	I/O voltage levels supported (V)	1.2, 1.5, 1.8, 2.5, 3.0, 3.3			
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II)			
	LVDS transmitter (TX)	120	120		
	LVDS receiver (RX)	120	120		
res	Embedded DPA circuitry	/	•		
eatu	ОСТ	Series and o	differential		
I/O Features	Programmable drive strength	✓	•		
-	Transceiver count (10.3125 Gbps/6.5536 Gbps)	16/30	16/30		
	PCIe hard IP blocks (Gen2 x4)	2	2		
	GPIOs (FPGA)	528	528		
	GPIOs (HPS)	216	216		
	Hard memory controllers <sup>3</sup> (FPGA)	3	3		
	Hard memory controllers <sup>3</sup> (HPS)	1	1		
Memory Interfaces	Memory devices supported	DDR3, DDR2, DDR, QDR II, QDR	II+, RLDRAM 2, LPDDR2 <sup>4</sup> , SDR		

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>&</sup>lt;sup>2</sup>The PLL count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit ECC support.

 $<sup>^4{\</sup>mbox{These}}$  memory interfaces are not available as Altera IP.

### **Arria II GX FPGA Features**

			Maximum R	esource Count	for Arria II GX	FPGAs (0.9 V)			
		EP2AGX45	EP2AGX65	EP2AGX95	EP2AGX125	EP2AGX190	EP2AGX260		
Density and Speed	ALMs	18,050	25,300	37,470	49,640	76,120	102,600		
	LEs (K)	43	60	89	118	118	244		
	Registers <sup>1</sup>	36,100	50,600	74,940	99,280	152,240	205,200		
	M9K memory blocks	319	495	612	730	840	950		
nsity	MLAB memory (Kb)	564	791	1,171	1,551	2,379	3,206		
De	Embedded memory (Kb)	2,871	4,455	5,508	6,570	7,560	8,550		
	18 x 18 multipliers	232	312	448	576	656	736		
	Global clock networks				16				
ures	Regional clock networks	48							
Architectural Features	Periphery clock networks	50	50	59	59	84	84		
ural	PLLs	4	4	6	6	6	6		
itect	Configuration file size (Mb)	18	18	34	34	64	64		
Arch	Design security	✓							
	Others			Plug & Play	Signal Integrity				
	I/O voltage levels supported (V)			1.2, 1.5, 1.8	3, 2.5, 3.0, 3.3				
Sa	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, BLVDS, Differential SSTL-18, Differential SSTL-15, Differential SSTL-2, Differential HSTL-18, Differential HSTL-15, SSTL-18 (I and II), SSTL-15 (I), SSTL-2 (I and II), 1.8-V HSTL (I and II), 1.5-V HSTL (I and II), 1.2-V HSTL (I and II)							
atur	Emulated LVDS channels, 945 Mbps	56	56	64	64	96	96		
I/O Features	LVDS channels, 1,250 Mbps (receive/transmit)	85/84	85/84	105/104	105/104	145/144	145/144		
	Embedded DPA circuitry				✓				
	OCT			Series and	d differential				
	Transceiver count (6.375 Gbps)	8	8	12	12	16	16		
	PCIe hard IP block (Gen1)				1				
External Memory Interfaces	Memory devices supported			DDR3, DDR	2, DDR, QDR II				

<sup>&</sup>lt;sup>1</sup>This is the base core logic register count. The ALM can support three registers when used in LUTREG mode, which increases total register count by an additional 50 percent.

### **Arria II GZ FPGA Features**

		Maximum Re	source Count for Arria II GZ	FPGAs (0.9 V)		
		EP2AGZ225	EP2AGZ300	EP2AGZ350		
	ALMs	89,600	119,200	139,400		
	LEs (K)	224	298	349		
Density and Speed	Registers	179,200	238,400	278,800		
	M9K memory blocks	1,235	1,248	1,248		
ity a	M144K memory blocks	0	24	36		
Dens	MLAB memory (Kb)	2,850	4,420	4,420		
_	Embedded memory (Kb)	11,115	14,688	16,416		
	18 x 18 multipliers	800	920	1,040		
es	Global clock networks		16			
atur	Regional clock networks	64	88	88		
al Fe	Periphery clock networks		88			
ectur	PLLs	8	8	8		
Architectural Features	Configuration file size (Mb)	95	141	141		
Ā	Design security		✓			
	I/O voltage levels supported (V)		1.2, 1.5, 1.8, 2.5, 3.0			
<b>v</b>	I/O standards supported	Differential SSTL-18, Different Differential HSTL-18, SS	I-X, LVDS, mini-LVDS, RSDS, LVPE ial SSTL-2, Differential HSTL-12, STL-15 (I and II), SSTL-18 (I and I II), 1.5-V HSTL (I and II), 1.8-V I	Differential HSTL-15 (I and II), I), 1.2-V HSTL (I and II),		
ture	Emulated LVDS channels, 1,152 Mbps	184	184	184		
I/O Features	LVDS channels, 1,250 Mbps (receive/transmit)		Up to 86			
	Embedded DPA circuitry		✓			
	ост		Series and differential			
	Transceiver count (6.375 Gbps)	Up to 24				
	PCIe hard IP blocks (value as 1.1, 2.0, etc)		1			
External Memory Interfaces	Memory devices supported	DDR3	, DDR2, DDR, QDR II, RLDRAM 2	2, SDR		

## **Arria Series Package and I/O Matrices**

			Arria V GX,GT, and	GZ FPGAs (0.85 V) <sup>1</sup>		
	FBGA (F)	Hybrid FBGA (H)		FBGA	A (F)	
	<b>672 pin</b> 27 x 27 (mm) 1.0-mm pitch	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	<b>896</b> 31 x 3 <sup>1</sup> 1.0-mn	1 (mm)	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,517 pin</b> 40 x 40 (mm) 1.0-mm pitch
5AGXA1	336 9,0		416 9,0	320 9,0		
5AGXA3	336 9,0		416 9,0	320 9,0		
5AGXA5	336 9,0		384 18,0	320 9,0	544 24,0	
5AGXA7	336 9,0		384 18,0	320 9,0	544 24,0	
5AGXB1			384 18,0	320 9,0	544 24,0	704 24,0
5AGXB3			384 18,0	320 9,0	544 24,0	704 24,0
5AGXB5					544 24,0	704 36,0
5AGXB7					544 24,0	704 36,0
5AGTC3	336 3,4		416 3,4	320 3,4		
5AGTC7			384 6,8	320 3,4		
5AGTD3			384 6,8	320 3,4	544 6,12	704 6,12
5AGTD7					544 6,12	704 6,20
5AGZE1		333 12			405 24	
5AGZE3		333 <b>.</b> 12			405 24	
5AGZE5					524 24	649 36
5AGZE7					524 24	649 36

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>636 8.0</sup> For Arria V GX and GT devices, values on top indicate available user I/O pins; for Arria V GX and GT, values at the bottom indicate the 6.5536-Gbps and 10.3125-Gbps transceiver count.

One pair of 10-Gbps transceiver channels can be configured as three 6-Gbps transceiver channels. For Arria V GZ device, values on top indicate available user I/O pins; values at the bottom indicate the 12.5-Gbps transceiver count.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). I/O pins can be migrated across device variants indicated with vertical migration lines of the same color. For vertical migration, the number of user I/Os may be less than the number stated in the table.

## **Arria Series Package and I/O Matrices**

	Arria V SX and ST SoC FPGAs (1.1 V) <sup>1</sup>					
		FBGA (F)				
	<b>896 pin</b>	<b>1,152 pin</b>	<b>1,517 pin</b>			
	31 x 31 (mm)	35 x 35 (mm)	40 x 40 (mm)			
	1.0-mm pitch	1.0-mm pitch	1.0-mm pitch			
5ASXB3	178, 216	350, 216	528, 216			
	<sub>12+0</sub>	18+0	30+0			
5ASXB5	178, 216	350, 216	528, 216			
	12+0	18+0	30+0			
5ASTD3	178, 216	350, 216	528, 216			
	12+4	18+8	30+16			
5ASTD5	178, 216	350, 216	528, 216			
	12+4	18+8	30+16			

All data is preliminary.

636, 216 Values on top indicate available FPGA user I/O pins and HPS I/O pins; values at the bottom indicate the 6.5536-Gbps plus 10.3125-Gbps transceiver count.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

	Arria II GX FPGAs (0.9 V)					
	UBGA (U) <sup>1</sup>		FBGA (F)			
	<b>358 pin</b> 17 x 17 (mm) 0.8-mm pitch	<b>572 pin</b> 25 x 25 (mm) 1.0-mm pitch	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch		
EP2AGX45	156 4	252 8	364 8			
EP2AGX65	156 4	252 8	364 8			
EP2AGX95		260 8	372 12	452 12		
EP2AGX125		260 8	372 12	452 12		
EP2AGX190			372 12	612 16		
EP2AGX260			372 12	612 16		

<sup>&</sup>lt;sup>1</sup>Ultra FineLine ball grid array.

Values on top indicate available user I/O pins; values at the bottom indicate the 6.375-Gbps transceiver count.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

		Arria II GZ FPGAs (0.9 V)					
	Hybrid FBGA (H)	FBG	A (F)				
	<b>780 pin</b> 33 x 33 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch	<b>1,517 pin</b> 40 x 40 (mm) 1.0-mm pitch				
EP2AGZ225		554 16	734 24				
EP2AGZ300	281 16	554 16	734 24				
EP2AGZ350	281	554 16	734 24				

Values on top indicate available user I/O pins; values at the bottom indicate the 6.375-Gbps transceiver count.

T Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

# **Cyclone V E FPGA Features**

			Maximum Resourc	e Count for Cyclone	v E FPGAs (1.1 V)¹		
		5CEA2	5CEA4	5CEA5	5CEA7	5CEA9	
	ALMs	9,434	18,480	29,080	56,480	113,560	
	LEs (K)	25	49	77	149.5	301	
peed	Registers	37,736	73,920	116,320	225,920	454,240	
dS bι	M10K memory blocks	176	308	446	686	1,220	
Density and Speed	M10K memory (Kb)	1,760	3,080	4,460	6,860	12,200	
Dens	MLAB memory (Kb)	196	303	424	836	1,717	
	Variable-precision DSP blocks	25	66	150	156	342	
	18 x 18 multipliers	50	132	300	312	684	
_	Global clock networks		16				
chitectura Features	PLLs	4	4	6	6	6	
Architectural Features	Configuration file size (Mb)	TBD	TBD	TBD	TBD	TBD	
▼	Design security	<b>✓</b>					
	I/O voltage levels supported (V)		1	.1, 1.2, 1.5, 1.8, 2.5, 3	3		
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II), HiSpi, SLVS, Sub-LVDS					
I/O Features	LVDS channels, 875-Mbps receive, 840-Mbps transmit	56	56	60	120	120	
/0 Fe	Embedded DPA circuitry			-			
_	ОСТ			Series and differential			
	Programmable drive strength			✓			
	PCIe hard IP blocks			-			
	Hard memory controllers <sup>2</sup>	1	1	2	2	2	
External Memory Interfaces	Memory devices supported			DDR3, DDR2, LPDDR2			

<sup>&</sup>lt;sup>1</sup> All data is preliminary. Various packages offer a variety of options to meet your design needs.

<sup>&</sup>lt;sup>2</sup> With 16- and 32-bit ECC support.

# **Cyclone V GX FPGA Features**

		Maximum Resource Count for Cyclone V GX FPGAs (1.1 V) <sup>1</sup>					
		5CGXC3	5CGXC4	5CGXC5	5CGXC7	5CGXC9	
	ALMs	11,900	18,868	29,080	56,480	113,560	
	LEs (K)	31.5	50	77	149.5	301	
Density and Speed	Registers	47,600	75,472	116,320	225,920	454,240	
	M10K memory blocks	119	250	446	686	1,220	
ity aı	M10K memory (Kb)	1,190	2,500	4,460	6,860	12,200	
Dens	MLAB memory (Kb)	159	295	424	836	1,717	
	Variable-precision DSP blocks	51	70	150	156	342	
	18 x 18 multipliers	102	140	300	312	684	
_	Global clock networks			16			
ctura	PLLs <sup>2</sup>	4	6	6	7	8	
Architectural Features	Configuration file size (Mb)	TBD	TBD	TBD	TBD	TBD	
₹	Design security			✓			
	I/O voltage levels supported (V)	1.1, 1.2, 1.5, 1.8, 2.5, 3.3					
	I/O standards supported	Differential SSTL-	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II), HiSpi, SLVS, Sub-LVDS				
S.	LVDS channels, 875-Mbps receive, 840-Mbps transmit	52	84	84	120	140	
ature	Embedded DPA circuitry			-			
I/O Features	ОСТ			Series and differential			
_	Programmable drive strength			✓			
	Transceiver count (3.125 Gbps)	3	6	6	9	12	
	PCIe hard IP blocks (Gen1 x4)	1	2	2	2	2	
	Hard memory controllers <sup>3</sup>	1	2	2	2	2	
External Memory Interfaces	Memory devices supported			DDR3, DDR2, LPDDR2			

<sup>&</sup>lt;sup>1</sup> All data is preliminary. Various packages offer a variety of options to meet your design needs.

<sup>&</sup>lt;sup>2</sup>The PLL count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit ECC support.

# **Cyclone V GT FPGA Features**

		Maximum Resource Count for Cyclone V GT FPGAs (1.1 V) <sup>1</sup>			
		5CGTD5	5CGTD7	5CGTD9	
pəə	ALMs	29,080	56,480	113,560	
	LEs (K)	77	149.5	301	
	Registers	116,320	225,920	454,240	
dS br	M10K memory blocks	446	686	1,220	
Density and Speed	M10K memory (Kb)	4,460	6,860	12,200	
Dens	MLAB memory (Kb)	424	836	1,717	
	Variable-precision DSP blocks	150	156	342	
	18 x 18 multipliers	300	312	684	
_	Global clock networks	16			
ctura	PLLs <sup>2</sup>	6	7	8	
Architectural Features	Configuration file size (Mb)	TBD	TBD	TBD	
⋖	Design security	✓			
	I/O voltage levels supported (V)	1.1, 1.2, 1.5, 1.8, 2.5, 3.3			
	I/O standards supported	LLVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-16 (I and II), SSTL-18 (I and II), SSTL-18 (I and II), SSTL-18 (I and II), HISPI, SLVS, Sub-LVDS			
ıres	LVDS channels, 875-Mbps receive, 840-Mbps transmit	84	120	140	
I/O Features	Embedded DPA circuitry	<del>-</del>			
9	ОСТ	Series and differential			
	Programmable drive strength		✓		
	Transceiver count (5 Gbps)	6	9	12	
	PCIe hard IP blocks (Gen2 x1, x2, and x4, Gen1 x4)	2	2	2	
	Hard memory controllers <sup>3</sup>	2	2	2	
External Memory Interfaces	Memory devices supported	DDR3, DDR2, LPDDR2			

<sup>&</sup>lt;sup>1</sup>All data is preliminary. Various packages offer a variety of options to meet your design needs.

 $<sup>^{2}\,\</sup>mbox{The PLL}$  count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit ECC support.

# **Cyclone V SE SoC FPGA Features**

		Maximum Resource Count for Cyclone V SE SoC FPGAs (1.1 V) <sup>1</sup>			
		5CSEA2	5CSEA4	5CSEA5	5CSEA6
Density and Speed	ALMs	9,434	15,094	32,075	41,509
	LEs (K)	25	40	85	110
	Registers	37,736	60,376	128,300	166,036
	M10K memory blocks	140	224	397	514
	M10K memory (Kb)	1,400	2,240	3,972	5,140
Dens	MLAB memory (Kb)	138	220	480	621
_	Variable-precision DSP blocks	36	58	87	112
	18 x 18 multipliers	72	116	174	224
S	Processor cores (ARM Cortex-A9)	Single or dual	Single or dual	Single or dual	Single or dual
atur	Global clock networks	16			
al Fe	PLLs <sup>2</sup> (FPGA)	4	5	6	6
ctura	PLLs <sup>2</sup> (HPS)	3	3	3	3
Architectural Features	Configuration file size (Mb)	TBD	TBD	TBD	TBD
Ā	Design security	<b>√</b>			
	I/O voltage levels supported (V)	1.1, 1.2, 1.5, 1.8, 2.5, 3.3			
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-18 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II), HiSpi, SLVS, Sub-LVDS			
	LVDS channels, 875-Mbps receive, 840-Mbps transmit	31	31	72	72
ures	Embedded DPA circuitry	-			
'O Features	ОСТ	Series and differential			
)	Programmable drive strength	✓			
	PCIe hard IP blocks	-			
	GPIOs (FPGA)	145	145	288	288
	GPIOs (HPS)	188	188	188	188
	Hard memory controllers <sup>3</sup> (FPGA)	1	1	1	1
	Hard memory controllers <sup>3</sup> (HPS)	1	1	1	1
External Memory Interfaces	Memory devices supported	DDR3, DDR2, LPDDR2			

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

 $<sup>^2\</sup>mbox{The PLL}$  count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup>With 16- and 32-bit ECC support.

# **Cyclone V SX SoC FPGA Features**

		Maximum Resource Count for Cyclone V SX SoC FPGAs (1.1 V) <sup>1</sup>			
		5CSXC2	5CSXC4	5CSXC5	5CSXC6
Density and Speed	ALMs	9,434	15,094	32,075	41,509
	LEs (K)	25	40	85	110
	Registers	37,736	60,376	128,300	166,036
	M10K memory blocks	140	224	397	514
	M10K memory (Kb)	1,400	2,240	3,972	5,140
ens	MLAB memory (Kb)	138	220	480	621
	Variable-precision DSP blocks	36	58	87	112
	18 x 18 multipliers	72	116	174	224
es	Processor cores (ARM Cortex-A9)	Dual	Dual	Dual	Dual
atur	Global clock networks	16			
al Fe	PLLs <sup>2</sup> (FPGA)	4	5	6	6
cture	PLLs <sup>2</sup> (HPS)	3	3	3	3
Architectural Features	Configuration file size (Mb)	TBD	TBD	TBD	TBD
Ā	Design security	· ·			
	I/O voltage levels supported (V)	1.1, 1.2, 1.5, 1.8, 2.5, 3.3			
	I/O standards supported	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II), HiSpi, SLVS, Sub-LVDS			
	LVDS channels, 875-Mbps receive, 840-Mbps transmit	31	31	72	72
I/O Features	Embedded DPA circuitry	<u>-</u>			
Feat	ОСТ	Series and differential			
<u>9</u>	Programmable drive strength	Programmable drive strength			
	Transceiver count (3.125 Gbps)	6	6	9	9
	PCIe hard IP blocks (Gen1 x4)	2	2	2	2
	GPIOs (FPGA)	145	145	288	288
	GPIOs (HPS)	188	188	188	188
	Hard memory controllers <sup>3</sup> (FPGA)	1	1	1	1
	Hard memory controllers <sup>3</sup> (HPS)	1	1	1	1
External Memory Interfaces	Memory devices supported	DDR3, DDR2, LPDDR2			

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

 $<sup>^{\</sup>rm 2}$  The PLL count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit ECC support.

# **Cyclone V ST SoC FPGA Features**

		Maximum Resource Count for Cyclone V ST SoC FPGAs (1.1 V) <sup>1</sup>		
		5CSTD5	5CSTD6	
Density and Speed	ALMs	32,075	41,509	
	LEs (K)	85	110	
	Registers	128,300	166,036	
	M10K memory blocks	397	514	
	M10K memory (Kb)	3,972	5,140	
ensi	MLAB memory (Kb)	480	621	
Δ	Variable-precision DSP blocks	87	112	
	18 x 18 multipliers	174	224	
es	Processor cores (ARM Cortex-A9)	Dual	Dual	
Architectural Features	Global clock networks	16		
ral Fe	PLLs <sup>2</sup> (FPGA)	6	6	
ectui	PLLs <sup>2</sup> (HPS)	3	3	
chite	Configuration file size (Mb)	TBD	TBD	
⋖	Design security	√ ·		
	I/O voltage levels supported (V)  I/O standards supported	1.1, 1.2, 1.5, 1.8, 2.5, 3.3  LLVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15,  Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15,  Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II),  1.5-V HSTL (I and II), 1.8-V HSTL (I and II), HiSpi, SLVS, Sub-LVDS		
	LVDS channels, 875-Mbps receive, 840-Mbps transmit	72	72	
es	Embedded DPA circuitry	_		
//O Features	ОСТ	Series and differential		
/0 Fe	Programmable drive strength	✓		
_	Transceiver count (5 Gbps)	9	9	
	PCIe hard IP blocks (Gen2 x1,x2, and x4, Gen1 x4)	2	2	
	GPIOs (FPGA)	288	288	
	GPIOs (HPS)	188	188	
	Hard memory controllers <sup>3</sup> (FPGA)	1	1	
	Hard memory controllers <sup>3</sup> (HPS)	1	1	
External Memory Interfaces	Memory devices supported	DDR3, DDR2, LPDDR2		

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>&</sup>lt;sup>2</sup>The PLL count includes general-purpose fPLLs and transceiver fPLLs.

<sup>&</sup>lt;sup>3</sup> With 16- and 32-bit ECC support.

## **Cyclone IV GX FPGA Features**

			Maximu	m Resource C	ount for Cyclo	one IV GX FPG	As (1.2 V) <sup>1</sup>			
		EP4CGX15	EP4CGX22	EP4CGX30	EP4CGX50	EP4CGX75	EP4CGX110	EP4CGX150		
ъ	LEs (K)	14	21	29	50	74	109	150		
al Density Spee	M9K memory blocks	60	84	120	278	462	666	720		
ensit Spe	Embedded memory (Kb)	540	756	1,080	2,502	4,158	5,490	6,480		
	18 x 18 multipliers	0	40	80	140	198	280	360		
ural	Global clock networks	20	20	20	30	30	30	30		
chitectur Features	PLLs	3	4	4	8	8	8	8		
Arch	Configuration file size (Mb)	3.8	7.6	7.6	24.5	24.5	47.6	47.6		
	I/O voltage levels supported (V)	1.2, 1.5, 1.8, 2.5, 3.3								
	I/O standards supported	Differential	LVTTL, LVCMOS, PCI, PCI-X, LVDS, mini-LVDS, RSDS, LVPECL, Differential SSTL-15, Differential SSTL-18, Differential SSTL-2, Differential HSTL-12, Differential HSTL-15, Differential HSTL-18, SSTL-15 (I and II), SSTL-18 (I and II), SSTL-2 (I and II), 1.2-V HSTL (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II)							
tures	Emulated LVDS channels	9	40	40	73	73	139	139		
I/O Features	LVDS channels, 840 Mbps (receive/transmit)	7/7	14/14	14/14	49/49	49/49	59/59	59/59		
	Transceiver count <sup>2</sup> (2.5 Gbps/3.125 Gbps)	2/0	2,0/4,0	4, 0 / 0, 4 <sup>3</sup>	0, 8	0, 8	0, 8	0, 8		
	PCIe hard IP blocks (Gen1)	1								
External Memory Interfaces	Memory devices supported	DDR2, DDR, QDR II, RLDRAM 2, SDR								

<sup>&</sup>lt;sup>1</sup> Various packages offer a variety options to meet your design needs.

<sup>&</sup>lt;sup>2</sup>Transceiver performance varies by product line and package offering.

<sup>&</sup>lt;sup>3</sup>EP4CGX30 supports 3.125 Gbps only in F484 package option.

# **Cyclone IV E FPGA Features**

			Maximum Resource Count for Cyclone IV E FPGAs								
		EP4CE6	EP4CE10	EP4CE15	EP4CE22	EP4CE30	EP4CE40	EP4CE55	EP4CE75	EP4CE115	
ed	LEs (K)	6	10	15	22	29	40	56	75	114	
spe k	M9K memory blocks	30	46	56	66	66	126	260	305	432	
Density and Speed	Embedded memory (Kb)	270	414	504	594	594	1,134	2,340	2,745	3,888	
Den	18 x 18 multipliers	15	23	56	66	66	116	154	200	266	
la .	Global clock networks	10	10	20	20	20	20	20	20	20	
chitectur Features	PLLs	2	2	4	4	4	4	4	4	4	
Architectural Features	Configuration file size (Mb)	2.8	2.8	3.9	5.5	9.1	9.1	14.2	19	27.2	
es	I/O voltage levels supported (V)	1.2, 1.5, 1.8, 2.5, 3.3									
I/O Features	I/O standards supported	Diff	erential SSTL	-2, Differentia	'DS, mini-LVD! Il HSTL-12, Di and II), 1.2-V I	fferential HST	L-15, Differen	tial HSTL-18,	SSTL-15 (I an	d II),	
	LVDS channels	66	66	137	52	224	224	160	178	230	
External Memory Interfaces	Memory devices supported	DDR2, DDR, QDR II, RLDRAM 2, SDR									

# **Cyclone III FPGA Features**

			M	aximum Reso	ource Count f	for Cyclone II	I FPGAs (1.2	V)			
		EP3C5	EP3C10	EP3C16	EP3C25	EP3C40	EP3C55	EP3C80	EP3C120		
ъ	LEs (K)	5	10	15	25	40	56	81	119		
Density Spee	M9K memory blocks	46	46	56	66	126	260	305	432		
ensit Spe	Embedded memory (Kb)	414	414	504	594	1,134	2,340	2,745	3,888		
	18 x 18 multipliers	23	23	56	66	126	156	244	288		
_	Global clock networks	10	10	20	20	20	20	20	20		
ctura	PLLs	2	2	4	4	4	4	4	4		
Architectural Features	Configuration file size (Mb)	2.8	2.8	3.9	5.5	9.1	14.2	19	27.2		
	Design security	-									
	I/O voltage levels supported (V)	1.2, 1.5, 1.8, 2.5, 3.3									
//O Features	I/O standards supported	LVDS, LVPECL, Differential SSTL-18, Differential SSTL-2, Differential HSTL, SSTL-18 (I and II), SSTL-2 (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II), PCI, PCI-X 1.0, LVTTL, LVCMOS									
I/0 Fe	Emulated LVDS channels, 840 Mbps	66	66	136	79	223	159	177	229		
	ОСТ				Series and	differential					
External Memory Interfaces	Memory device supported		QDR II, DDR2, DDR, SDR								

# **Cyclone III LS FPGA Features**

		Max	imum Resource Count for	Cyclone III LS FPGAs (1.2	V)						
		EP3CLS70	EP3CLS100	EP3CLS150	EP3CLS200						
-5	LEs (K)	70	100	151	198						
Density and Speed	M9K memory blocks	333	483	666	891						
ensit Spe	Embedded memory (Kb)	2,997	4,347	5,994	8,019						
	18 x 18 multipliers	200	200 276 320 396								
_	Global clock networks		20								
ctura	PLLs		4								
Architectural Features	Configuration file size (Mb)	26.8	26.8	50.6	50.6						
	Design security		✓								
	I/O voltage levels supported (V)	1.2, 1.5, 1.8, 2.5, 3.3									
I/O Features	I/O standards supported	LVDS, LVPECL, Differential SSTL-18, Differential SSTL-2, Differential HSTL, SSTL-18 (I and II), SSTL-2 (I and II), 1.5-V HSTL (I and II), 1.8-V HSTL (I and II), PCI, PCI-X 1.0, LVTTL, LVCMOS									
I/0 Fe	LVDS channels, 840 Mbps		169								
	ОСТ		Series and di	fferential							
External Memory Interfaces	Memory device supported		QDR II, DDR2, DDR, SDR								

				Cyclon	e V E, GX, a	nd GT FPGAs (	(1.1 V) <sup>1</sup>					
		MBGA (M)		UBG	A (U)		FBGA (F)					
	281 pin 11 x 11 (mm) 0.5-mm pitch	<b>385 pin</b> 13 x 13 (mm) 0.5-mm pitch	<b>484 pin</b> 15 x 15 (mm) 0.5-mm pitch	<b>324 pin</b> 15 x 15 (mm) 0.8-mm pitch	<b>484 pin</b> 19 x 19 (mm) 0.8-mm pitch	256 pin 17 x 17 (mm) 1.0-mm pitch	<b>484 pin</b> 23 x 23 (mm) 1.0-mm pitch	<b>672 pin</b> 27 x 27 (mm) 1.0-mm pitch	<b>896 pin</b> 31 x 31 (mm) 1.0-mm pitch	<b>1,152 pin</b> 35 x 35 (mm) 1.0-mm pitch		
5CEA2		208		176	224	128	224					
5CEA4		208		176	224	128	224					
5CEA5		208			224		240					
5CEA7			224		240		240	336	480			
5CEA9					224		224	336	480			
5CGXC3				144 3	208		208					
5CGXC4	128	176 6			224 6		240 6	336				
5CGXC5	128	176 6			224 6		240 6	336 6				
5CGXC7			224 3		240 6		240 6	336 9	480 9			
5CGXC9					224 5		224 6	336 9	480 12	560 12		
5CGTD5	128 3	176 6			224 6		240 6	336				
5CGTD7			224 3		240 6		240 6	336 9	480 9			
5CGTD9					224 5		224 6	336 9	480 12	560 12		

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

Values on top indicate available user I/O pins; values at the bottom indicate the 3.125-Gbps or 5-Gbps transceiver count.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

	Су	clone V SE, SX, and ST SoC FPGAs (1.1 V)	1
	UBGA	(U)	FBGA (F)
	<b>484 pin</b> 19 x 19 (mm) 0.8-mm pitch	<b>672 pin</b> 23 x 23 (mm) 0.8-mm pitch	<b>896 pin</b> 31 x 31 (mm) 1.0-mm pitch
5CSEA2	66, 161 0	145, 188 0	
5CSEA4	66, 161 0	145, 188 0	
5CSEA5	66, 161 0	145, 188 0	288, 188
5CSEA6	66, 161 <b>.</b> 0	145, 188 0	288, 188 0
5CSXC2		145, 188 6	
5CSXC4		145, 188 6	
5CSXC5		145, 188 9	288, 188 9
5CSXC6		145, 188 9	288, 188 9
5CSTD5			288, 188
5CSTD6			288, 188 9

<sup>&</sup>lt;sup>1</sup>All data is preliminary.

<sup>[636, 161]</sup> Values on top indicate available FPGA user I/O pins and HPS I/O pins; values at the bottom indicate the 3.125-Gbps or 5-Gbps transceiver count.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

		Cyclone IV GX FPGAs (1.2 V)								
	QFN (N) <sup>1</sup>		FBGA (F)							
	<b>148 pin</b> 11 x 11 (mm) 0.5-mm pitch	<b>169 pin</b> 14 x 14 (mm) 1.0-mm pitch	<b>324 pin</b> 19 x 19 (mm) 1.0-mm pitch	<b>484 pin</b> 23 x 23 (mm) 1.0-mm pitch	<b>672 pin</b> 27 x 27 (mm) 1.0-mm pitch	<b>896 pin</b> 31 x 31 (mm) 1.0-mm pitch				
EP4CGX15	72 2	72 2								
EP4CGX22		72 2	150 4							
EP4CGX30		72 2	150 4	290 4						
EP4CGX50				290 4	310 8					
EP4CGX75				290 4	310 8					
EP4CGX110				270 4	393 8	475 8 •				
EP4CGX150				270 4	393 8	475 8				

<sup>1</sup> Quad flat pack no lead.

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 $Values \ on \ top \ indicate \ available \ user \ I/O \ pins; values \ at \ the \ bottom \ indicate \ the \ 2.5-Gbps \ or \ 3.125-Gbps \ transceiver \ count.$ 

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

			Cyclone I	/ E FPGAs (1.0 V	and 1.2 V)		
	EQFP (E) <sup>1</sup>		FBGA (F)		MBGA (M)	UBC	GA (U)
	144 pin 22 x 22 (mm) 0.5-mm pitch	<b>256 pin</b> 17 x 17 (mm) 1.0-mm pitch	<b>484 pin</b> 23 x 23 (mm) 1.0-mm pitch	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	164 pin 8 x 8 (mm) 0.5-mm pitch	256 pin 14 x 14 (mm) 0.8-mm pitch	<b>484 pin</b> 19 x 19 (mm) 0.8-mm pitch
EP4CE6	91	179				179	
EP4CE10	91	179				179	
EP4CE15	81	165	343		74	165	
EP4CE22	79	153				153	
EP4CE30			328	532			_
EP4CE40			328	532			328
EP4CE55			324	374			324
EP4CE75			292	426			292
EP4CE115			280	528			

<sup>&</sup>lt;sup>1</sup> Enhanced thin quad flat pack.

<sup>636</sup> Number indicates available user I/O pins.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

				Cyclon	e III FPGAs (	(1.2 V)			
	EQFP (E)	MBGA (M) <sup>1</sup>	PQFP (Q) <sup>2</sup>		FBG	GA (F)		UBG	A (U)
	144 pin 22 x 22 (mm) 0.5-mm pitch	164 pin 8 x 8 (mm) 0.5-mm pitch	<b>240 pin</b> 34.6 x 34.6 (mm) 0.5-mm pitch	256 pin 17 x 17 (mm) 1.0-mm pitch	<b>324 pin</b> 19 x 19 (mm) 1.0-mm pitch	<b>484 pin</b> 23 x 23 (mm) 1.0-mm pitch	<b>780 pin</b> 29 x 29 (mm) 1.0-mm pitch	256 pin 14 x 14 (mm) 0.8-mm pitch	<b>484 pin</b> 19 x 19 (mm) 0.8-mm pitch
EP3C5	94	106		182				182	
EP3C10	94	106		182				182	
EP3C16	84	92	160	168		346		168	346
EP3C25	82		148	156	215			156	
EP3C40			128		195	331	535		331
EP3C55						327	377		327
EP3C80						295	429		295
EP3C120						283	531		
EP3CLS70						294	429		294
EP3CLS100						294	429		294
EP3CLS150						226	429		
EP3CLS200						226	429		

<sup>&</sup>lt;sup>1</sup> Micro FineLine BGA.

636 Number indicates available user I/O pins.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

<sup>&</sup>lt;sup>2</sup>Plastic quad flat pack.

### **MAX V CPLD Features**

			MAX V CPLDs (1.8 V)						
		5M40Z	5M80Z	5M160Z	5M240Z	5M570Z	5M1270Z	5M2210Z	
р	LEs	40	80	160	240	570	1270	2210	
Density and S	Equivalent macrocells <sup>1</sup>	32	64	128	192	440	980	1700	
	Pin-to-pin delay (ns)	7.5	7.5	7.5	7.5	9.0	6.2	7.0	
nsity	User flash memory (Kb)				8				
De	Total on-chip memory (bits) <sup>2</sup>	Yes	Yes	Yes	Yes	Yes	Yes	Yes	
	Internal oscillator				✓				
	Digital PLL <sup>3</sup>				✓				
ures	Fast power on reset				✓				
Architectural Features	Boundary scan JTAG				✓				
tural	JTAG ISP				✓				
ited	Fast input registers				✓				
Arch	Programmable register power up				✓				
	JTAG translator				✓				
	Real-time ISP				✓				
	MultiVolt I/Os (V)		1.2	, 1.5, 1.8, 2.5, 3	.3		1.2, 1.5, 1.8,	2.5, 3.3, 5.04	
	I/O power banks	2	2	2	2	2	4	4	
	Maximum output enables	54	54	79	114	159	271	271	
	LVTTL/LVCMOS				✓				
Se	LVDS outputs	Yes	Yes	Yes	Yes	Yes	Yes	Yes	
//O Features	32-bit, 66-MHz PCI compliant	-	-	-	-	-	<b>√</b> <sup>4</sup>	<b>√</b> <sup>4</sup>	
	Schmitt triggers				✓				
	Programmable slew rate				✓				
	Programmable pull-up resistors				✓				
	Programmable ground pins				✓				
	Open-drain outputs				✓				
	Bus hold				✓				

<sup>&</sup>lt;sup>1</sup>Typical equivalent macrocells.

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<sup>&</sup>lt;sup>2</sup>Unused LEs can be converted to memory. The total number of available LE RAM bits depends on the memory mode, depth, and width configurations of the instantiated memory.

<sup>&</sup>lt;sup>3</sup> Optional IP core. Contact your Altera sales representative for availability.

<sup>&</sup>lt;sup>4</sup>An external resistor must be used for 5-V tolerance.

### **MAX II CPLD Features**

			MAX II CPLDs (3	.3 V, 2.5 V, 1.8 V)	
		EPM240/Z	EPM570/Z	EPM1270	EPM2210
ity	Equivalent macrocells <sup>1</sup>	192	440	980	1,700
Density and Speed	Pin-to-pin delay (ns)	4.7, 7.5	5.4, 9.0	6.2	7.0
	User flash memory (Kb)			8	
res	Boundary scan JTAG		•	/	
eatu	JTAG ISP		•	/	
ıral F	Fast input registers		•	/	
Architectural Features	Programmable register power up		•	/	
Arc	JTAG translator		•	/	
	Real-time ISP		•	/	
	MultiVolt I/Os (V)	1.5, 1.8, 2.5, 3.3	1.5, 1.8, 2.5, 3.3	1.5, 1.8, 2.5, 3.3, 5.0 <sup>2</sup>	1.5, 1.8, 2.5, 3.3, 5.0 <sup>2</sup>
	I/O power banks	2	2	4	4
	Maximum output enables	80	160	212	272
	LVTTL/LVCMOS		•	/	
ures	32-bit, 66-MHz PCI compliant	-	-	<b>√</b> <sup>2</sup>	✓²
//O Features	Schmitt triggers		•	/	
2	Programmable slew rate		•	/	
	Programmable pull-up resistors		•	/	
	Programmable ground pins		•	/	
	Open-drain outputs		·	/	
	Bus hold		•	/	

<sup>&</sup>lt;sup>1</sup>Typical equivalent macrocells.

<sup>&</sup>lt;sup>2</sup>An external resistor must be used for 5-V tolerance.

### **MAX 3000A CPLD Features**

			MA	XX 3000A CPLDs (3.3	3 V)					
		EPM3032A	EPM3064A	EPM3128A	EPM3256A	EPM3512A				
y. Sed	Macrocells	32	64	128	256	512				
ဗို ဗ	Equivalent LEs	40	80	160	320	640				
D	Pin-to-pin delay (ns)	4.5, 7.5, 10	4.5, 7.5, 10	5.0, 7.5, 10	7.5, 10	7.5, 10				
_	Boundary scan JTAG			✓						
Architectural Features	JTAG ISP			✓						
chitectur Features	Fast input registers	✓								
Arc	Programmable register power up	✓								
	MultiVolt I/Os (V)			2.5, 3.3, 5.0						
S	I/O power banks			1						
Features	Maximum output enables	6	6	6	6	10				
I/0 Fe	LVTTL/LVCMOS			✓						
_	Programmable slew rate			✓						
	Open-drain outputs			✓						

### **MAX Series Package and I/O Matrices**

	MAX V CPLDs (1.8 V) <sup>1</sup>							
	EQFP (E) <sup>2</sup>	TQFI	P (T) <sup>3</sup>		MBGA (M) <sup>4</sup>	FBGA (F)		
	<b>64 pin</b> 7 x 7 (mm) 0.4-mm pitch	<b>100 pin</b> 14 x 14 (mm) 0.5-mm pitch	144 pin 20 x 20 (mm) 0.5-mm pitch	<b>64 pin</b> 4.5 x 4.5 (mm) 0.5-mm pitch	<b>68 pin</b> 5 x 5 (mm) 0.5-mm pitch	100 pin 6 x 6 (mm) 0.5-mm pitch	<b>256 pin</b> 17 x 17 (mm) 1.0-mm pitch	<b>324 pin</b> 19 x 19 (mm) 1.0-mm pitch
5M40Z	54			30				
5M80Z	54	79		30	52			
5M160Z	54	79			52	79		
5M240Z		79	114		52	79		
5M570Z		74	114			74	159	
5M1270Z			114				211	271
5M2210Z							203	271

	MAX II CPLDs (3.3 V, 2.5 V, 1.8 V) <sup>1</sup>								
	TQF	P (T)		FBGA (F)			MBGA (M)		
	<b>100 pin</b> 16 x 16 (mm) 0.5-mm pitch	144 pin 22 x 22 (mm) 0.5-mm pitch	<b>100 pin</b> 11 x 11 (mm) 1.0-mm pitch	<b>256 pin</b> 17 x 17 (mm) 1.0-mm pitch	<b>324 pin</b> 16 x 16 (mm) 0.5-mm pitch	68 pin 5 x 5 (mm) 0.5-mm pitch	<b>100 pin</b> 6 x 6 (mm) 0.5-mm pitch	<b>144 pin</b> 7 x 7 (mm) 0.5-mm pitch	<b>256 pin</b> 11 x 11 (mm) 0.5-mm pitch
EPM240Z						54	80		
EPM570Z							76	116	160
EPM240	80		80				80		
EPM570	76	116	76	160			76		160
EPM1270		116		212					212
EPM2210				204	272				

	MAX 3000A CPLDs (3.3 V)							
	PLCC (L) <sup>5</sup>		TQFP (T)		PQFP (Q) <sup>6</sup>	FBGA (F)		
	<b>44 pin</b> 17.5 x 17.5 (mm) 1.27-mm pitch	<b>44 pin</b> 12 x 12 (mm) 0.5-mm pitch	<b>100 pin</b> 16 x 16 (mm) 0.5-mm pitch	<b>144 pin</b> 22 x 22 (mm) 0.5-mm pitch	<b>208 pin</b> 28 x 28 (mm) 0.5-mm pitch	<b>256 pin</b> 17 x 17 (mm) 1.0-mm pitch		
EPM3032A	34 -	34 📮						
EPM3064A	34	34	66 -					
EPM3128A			80	96		98		
EPM3256A				116	158	161		
EPM3512A					172	208		

<sup>&</sup>lt;sup>1</sup>For temperature grades of specific packages (commercial, industrial, or extended temperatures), refer to Altera's online selector guide.

<sup>&</sup>lt;sup>2</sup>Enhanced quad flat pack.

<sup>&</sup>lt;sup>3</sup>Thin quad flat pack.

<sup>&</sup>lt;sup>4</sup>Micro FineLine BGA (0.5 mm).

<sup>&</sup>lt;sup>5</sup> Plastic J-lead chip carrier.

<sup>&</sup>lt;sup>6</sup> Plastic quad flat pack.

<sup>636</sup> Number indicates available user I/O pins.

Vertical migration (same V<sub>CC</sub>, GND, ISP, and input pins). For vertical migration, the number of user I/Os may be less than the number stated in the table.

Quartus II software is number one in performance and productivity for CPLD, FPGA, SoC FPGA, and HardCopy ASIC designs, providing the fastest path to convert your concept into reality. Quartus II software also supports many third-party tools in synthesis, static timing analysis, board-level simulation, signal integrity analysis, and formal verification.

	Quartus II Software Design Flow					
		Avail	ability			
	Quartus II Software Key Features	Subscription Edition	Web Edition (Free)			
	Cyclone FPGA and MAX CPLD device support	✓	✓			
	Arria and Stratix FPGA device support	✓				
	HardCopy ASIC device support	1				
	Multiprocessor support (faster compile time support)	✓				
Design Entry	IP Base Suite (includes licenses for 15 popular IP cores)	✓				
	Qsys (next-generation system—integration tool)	✓	✓			
	SOPC Builder (legacy system development tool)	✓	✓			
	Rapid Recompile (faster compile for small design changes)	✓				
	Incremental compile (performance preservation and team-based design)					
Functional Simulation	ModelSim®-Altera Starter Edition software	✓	✓			
runctional Simulation	ModelSim-Altera Edition software	<b>√</b> ¹	<b>√</b> ¹			
Synthesis	Quartus Integrated Synthesis (synthesis tool)	<b>✓</b>	✓			
Placement and Routing	Fitter (placement and routing tool)	<b>✓</b>	✓			
Timing and	TimeQuest tool (static timing analysis)	✓	✓			
Power Verification	PowerPlay tool and optimization (power analysis)	✓	✓			
	SignalTap™ II logic analyzer (embedded logic analyzer)²	1				
In-System Debug	Transceiver Toolkit (transceiver interface and verification tool)	1				
		Avail	ability			
	Operating System Support	Subscription Edition	Web Edition (Free)			
	Windows/Linux 32-bit support	✓	✓			
	Windows/Linux 64-bit support	<b>✓</b>				

<sup>&</sup>lt;sup>1</sup> Requires additional license.

<sup>&</sup>lt;sup>2</sup> Available with TalkBack feature enabled in Web Edition.

### **Quartus II Design Software**

		Quartus II Design Software Features Summary
	Incremental compilation <sup>1</sup>	Improves design timing closure and reduces design compilation times up to 70 percent. Supports team-based design.
Design Flow Methodology	Pin planner	Eases the process of assigning and managing pin assignments for high-density and high pin-count designs.
	Qsys (replaces SOPC Builder)	Automates system development by integrating IP functions and subsystems (collection of IP functions) using a hierarchical approach and a high-performance interconnect (based on a network-on-a-chip architecture).
×	Off-the-shelf IP cores	Lets you construct your system-level design using IP cores from Altera and from Altera's third-party IP partners.
sign Flo	Parallel development in ASICs <sup>1</sup>	Allows for FPGA prototypes and HardCopy ASICs to be designed in parallel using the same design software and IP.
Des	Scripting support	Supports command-line operation and Tcl scripting, as well as GUI design.
	Rapid Recompile <sup>1</sup>	Maximizes your productivity by reducing your compilation time by 50 percent on average (for a small design change after a full compile). Improves design timing preservation.
ng y	Physical synthesis	Uses post placement and routing delay knowledge of a design to improve performance.
Performance and Timing Closure Methodology	Design space explorer (DSE)	Increases performance by automatically iterating through combinations of Quartus II software settings to find optimal results.
ice ai Meth	Extensive cross-probing	Provides support for cross-probing between verification tools and design source files.
man ure l	Optimization advisors	Provides design-specific advice to improve performance, resource usage, and power consumption.
Perfor Clos	Chip planner	Reduces verification time (while maintaining timing closure) by enabling small, post placement and routing design changes to be implemented in minutes.
	TimeQuest timing analyzer	Provides native Synopsys Design Constraint (SDC) support and allows you to create, manage, and analyze complex timing constraints and quickly perform advanced timing verification.
Verification	SignalTap II embedded logic analyzer <sup>2</sup>	Supports the most channels, fastest clock speeds, largest sample depths, and most advanced triggering capabilities available in an embedded logic analyzer.
Veri	System Console	Enables you to easily debug your FPGA in real time using read and write transactions. It also enables you to quickly create a GUI to help monitor and send data into your FPGA.
	PowerPlay technology	Enables you to accurately analyze and optimize both dynamic and static power consumption.
Third-Party Support	EDA partners	Offers EDA software support for synthesis, functional and timing simulation, static timing analysis, board-level simulation, signal integrity analysis, and formal verification. To see a complete list of partners, visit www.altera.com/products/software/partners/eda_partners/eda-index.html.

<sup>&</sup>lt;sup>1</sup> Included in Subscription Edition only.

### **Getting Started Steps**

### Step 1: Download free Web Edition

www.altera.com/download

### Step 2: Get oriented with Quartus II Software interactive tutorial

After installation, open the interactive tutorial on the welcome screen.

### Step 3: Sign up for training

www.altera.com/training

<sup>&</sup>lt;sup>2</sup> Available with talkback feature enabled in Web Edition.

## **Quartus II Design Software**

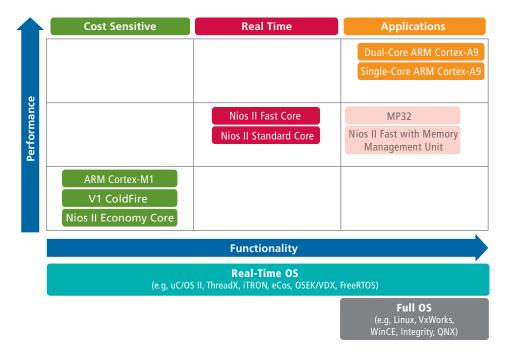
## Purchase Quartus II software and increase your productivity today.

Pricing	Description
\$2,995 (SW-QUARTUS-SE-FIX) Renewal \$2,495 (SWR-QUARTUS-SE-FIX)	Fixed-node license: subscription for one year—Windows only.
\$3,995 (SW-QUARTUS-SE-FLT) Renewal \$2,495 (SWR-QUARTUS-SE-FLT) Add seat \$3,995 (SW-QUARTUS-SE-ADD)	Floating-node license: subscription for one year—Windows/Linux.

ModelSim-Altera Edition Software					
\$945 (SW-MODELSIM-AE) Renewal \$945 (SWR-MODELSIM-AE)	ModelSim-Altera Edition software is available as a \$945 option for both Quartus II software Subscription Edition and Web Edition. It's 33 percent faster than Starter Edition with no line limitation.				
ModelSim-Altera Starter Edition Software	ModelSim-Altera Starter Edition Software				
Free	Free for both Quartus II software Subscription Edition and Web Edition softwares with a 10,000 executable line limitation, ModelSim-Altera Starter Edition software is recommended for simulating small FPGA designs.				

### **Altera's Customizable Processor Portfolio**

Altera's processor portfolio comprises SoC FPGAs, which feature single- or dual-core ARM Cortex-A9 MPCore hard processor systems as well as soft processors that can be used in any FPGA, SoC FPGA, or HardCopy device.



Summary of Processors					
Category	Processor	Vendor	Description		
Hard Processors for SoC FPG	GA				
Applications processing	Dual-core ARM Cortex-A9	Altera	Altera's Cyclone V and Arria V SoC FPGA families offer integrated ARM-based HPS, comprising peripherals, memory, and interfaces, with an FPGA fabric.		
Soft Core Processors					
Power and cost optimized processing	Nios II economy core	Altera	With unique, real-time hardware features, such as custom instructions (ability to use FPGA hardware to accelerate a function), vector interrupt controller, and tightly coupled memory, as well as support for industry-leading real-time OSs, the Nios II processor meets both your hard and soft real-time requirements.		
Real-time processing	Nios II standard and fast core	Altera	With unique, real-time hardware features, such as custom instructions (ability to use FPGA hardware to accelerate a function), vector interrupt controller, and tightly coupled memory, as well as support for industry-leading real-time OSs, the Nios II processor offers a versatile solution for real-time processing.		
Applications processing	Nios II fast core	Altera	A simple configuration option enables the Nios II fast core to use a memory management unit to run embedded Linux. Both open source and commercially supported versions of Linux for Nios II processors are available.		
Applications processing	MP32	SLS	MP32 brings the vast MIPS ecosystem to Altera's FPGAs, such as the VxWorks OS, to enable customizable MIPS-based solutions for video, DSP, and networking.		
Safety-critical processing	Nios II SC	H-Cell	Certify your design for DO-254 compliance by using the Nios II Safety Critical core along with the DO-254 compliance design services offered by H-Cell.		
ASIC-optimized processing	Nios II DesignWare IP	Synopsys	Take your embedded design to standard-cell ASIC through Synopsys using the Synopsys Nios II DesignWare IP core.		

### **Altera's Customizable Processor Portfolio**

Comparative Summary of Altera's Soft Processors by Performance and Feature Set							
Category	Cost-and Po	wer-Sensitive P	rocessors	Real-Time	Processor	Applicatio	ns Processors
Features	ARM Cortex-M1	V1 ColdFire	Nios II Economy	Nios II Standard	Nios II Fast	MP32	ARM Cortex-A9
Maximum frequency (MHz)	200	145	330	270	290	290	800
Maximum performance (MIPS <sup>2</sup> at MHz) Stratix Series	160 at 200	135 at 145	50 at 330	170 at 270	340 at 290	300 at 290	-
Maximum performance (MIPS <sup>2</sup> at MHz) Arria Series	-	84 at 90	45 at 300	115 at 180	270 at 240	300 at 290	2,000 MIPS per core at 800 MHz <sup>1</sup>
Maximum performance (MIPS <sup>2</sup> at MHz) Cyclone Series	80 at 100	84 at 90	30 at 175	90 at 145	195 at 175	140 at 145	2,000 MIPS per core at 800 MHz <sup>1</sup>
Maximum performance efficiency (MIPS <sup>2</sup> per MHz)	0.8	0.93	0.15	0.64	1.13	1.15	2.5
16-/32-bit instruction set support	16 and 32	16, 32, and 48	32	32	32	32	32
Level 1 instruction cache	-	_	-	Configurable	Configurable	Configurable	32 KB
Level 1 data cache	-	-	-	_	Configurable	64 KB	32 KB
Level 2 cache	-	_	-	_	-	_	512 KB
Memory management unit	-	_	-	_	✓	1	✓
Floating-point unit	-	-	-	FPCI <sup>3</sup>	FPCI <sup>3</sup>	-	Dual precision
Vector interrupt controller	1	-	-	1	1	_	_
Tightly coupled memory	Up to 64K	_	-	Configurable	Configurable	_	_
Custom instruction interface	-	-	Up to 256	Up to 256	Up to 256	-	-
Equivalent LEs	2,500	6,800	600	1,200	1,800 – 3,200	5,500	HPS

<sup>&</sup>lt;sup>1</sup> Per processor

<sup>&</sup>lt;sup>2</sup>Dhrystone 2.1 benchmark

<sup>&</sup>lt;sup>3</sup> Floating-point custom instructions

### **Altera's Customizable Processor Portfolio**

Available Board Support Package for OS						
Features BSP and OS Supplier		Nios II Processor	MP32			
eCOs	eCosCentric	<b>√</b>	_			
eCos (Zylin)	Zylin	✓	_			
embOS	Segger	<b>✓</b>	_			
Erika Enterprise	Evidence	✓	_			
EUROS RTOS	Euros	✓	_			
Linux	Wind River	✓	_			
Linux	Timesys	✓	_			
Linux	SLS	✓	_			
Linux	Open Source	✓	_			
MicroC/OS-II	Micrium	✓	-			
oSCAN	Vector	✓	_			
ThreadX	Express Logic	✓	_			
uCLinux	Open Source	✓	_			
VxWorks	Wind River	_	✓			
RTX RTOS	ARM KEIL	_	_			
Toppers RTOS	Open Source	✓	_			

### **Getting Started**

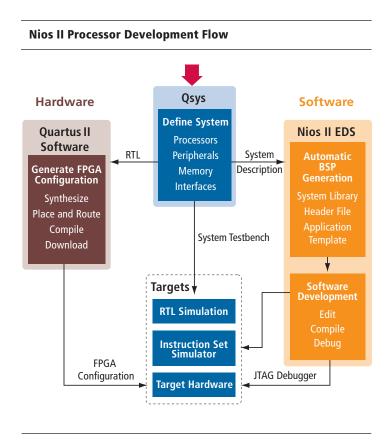
Learn more about Altera's portfolio of customizable processors and how you can get started by visiting www.altera.com/embedded

Altera's Nios II processor, the world's most versatile processor according to Gartner Research, is the most widely used soft processor in the FPGA industry. This soft processor delivers unprecedented flexibility for your cost-sensitive, real-time, safety-critical (DO-254), ASIC-optimized, and applications processing needs. The Nios II processor supports all Altera FPGA and HardCopy device families and is also available for standard cell ASICs through Synopsys.

The Nios II processor in any one of Altera's FPGA and HardCopy devices offers a custom SoC solution that has the flexibility of software and the performance of hardware. Through its innovative design, the Nios II processor leverages the logic resources of the device to provide unprecedented hard and soft real-time capabilities.

#### You can:

- · Lower overall system cost, complexity, and power consumption by integrating the processor with the FPGA.
- Scale performance with multiple processors, custom instructions (hardware acceleration of an instruction) or coprocessing (hardware accelerator next to the soft processor).
- Target any Stratix, Arria, or Cyclone series FPGA or HardCopy series ASIC.
- Eliminate the risk of processor and ASSP obsolescence.
- Take advantage of the free Nios II economy core, the free Nios II Embedded Design Suite (EDS), and the NicheStack TCP/IP Network Stack, Nios II Edition software to get started today.



#### **Nios II Processor**

#### **Nios II EDS Contents**

Code Development Tool: Nios II Software Build Tools for Eclipse

- New project wizards
- Software templates
- Source navigator and editor
- Compiler for C and C++ (GNU)
- Based on industry-standard Eclipse

Source Debugger/Profiler

Flash Programmer

**Embedded Software** 

- Hardware Abstration Layer (HAL)
- MicroC/OS-II real-time operating system
- NicheStack TCP/IP Network Stack—Nios II Edition
- Newlib ANSI-C standard library
- Simple file system

Other Altera Command-Line Tools and Utilities

**Design Examples** 

#### **Hardware Development Tools**

- Quartus II design software
- Qsys system integration tool
- SignalTap II embedded logic analyzer plug-in for Nios II processor
- System Console for low-level debug of Qsys systems

#### Licensing

Getting started with the Nios II processor is now easier than ever. Not only is the Nios II EDS free, but the Nios II economy core IP is also free.

As for the Nios II standard and fast core IP, licenses are available for stand-alone IP or as part of the Embedded IP Suite(IPS-EMBED-DED). These royalty-free licenses never expire and allow you to target your processor design on any Altera FPGA. The Embedded IP Suite is a value bundle that contains licenses of the Nios II processor IP core, DDR1/2 Memory Controller IP core, Triple-Speed Ethernet MAC IP core, and the NicheStack TCP/IP Network Stack, Nios II Edition software.

#### **Development Kits**

Go to page 59 for information about embedded development kits.

#### **Nios II EDS: What You Get for Free!**

The Nios II Embedded Design Suite (EDS) provides all the tools and software you need to develop code for the Nios II processor.

With the Nios II EDS you can:

- Develop software with Nios II Software Build Tools for Eclipse: Based on industry standard Eclipse, the Nios II Software Build Tool (SBT) is an integrated development environment for editing, compiling, debugging software code, and flash programming.
- Manage board support package (BSP): The Nios II EDS makes management of BSP easier than ever.
   Nios II EDS will automatically add device drivers for Altera-provided IP to your BSP. The BSP Editor provides full control over your build options.
- Get free Network Stack software:
   The Nios II EDS includes NicheStack TCP/IP
   Network Stack, Nios II Edition—a commercial grade network stack software—for free.
- Evaluate a real-time operating system (RTOS): The Nios II EDS contains an evaluation version of the popular Micrium MicroS/OS-II RTOS. Product licenses are sold separately by Micrium.

#### Join The Nios II Community!

Be part of the thousands of Nios II developers of the Nios II Community by visiting Altera Wiki and Altera Forum. The Altera Wiki has hundreds of design examples and design tips from Nios II developers all over the world. Join ongoing dialogue and activities on the Nios II section of the Altera Forum to know more about Nios II Linux, hardware, and software development.

Visit www.altreawiki.com and www.alteraforum.com.

The following is a partial list of IP functions from Altera and its partners. To get the full story, check out our online selector guide.

	Product Name	Vendor Name					
	Error Detection/	Correction					
	Reed-Solomon Compiler Decoder	Altera					
	Reed-Solomon Compiler Encoder	Altera					
	Reed-Solomon Encoder/Decoder II <sup>1</sup>	Altera					
	Viterbi Compiler, High-Speed Parallel Decoder	Altera					
	Viterbi Compiler, Low-Speed/ Hybrid Serial Decoder	Altera					
	DVB-RCS CTC Turbo Decoder	TurboConcept					
	WiMAX CTC Decoder	TurboConcept					
	3GPP/LTE CTC Decoder	TurboConcept					
	Turbo Product Code Decoder	TurboConcept					
	Filters and Tra	insforms					
	Fast Fourier Transform (FFT)/ Inverse FFT (IFFT)	Altera					
	Cascaded Integrator Comb (CIC) Compiler	Altera					
	Finite Impulse Response (FIR) Compiler	Altera					
DSP	FIR Compiler II	Altera					
Q	2D Forward/Inverse Discrete Cosine Transform	CAST, Inc.					
	2D Inverse Discrete Cosine Transform (IDCT)	CAST, Inc.					
	Forward Discrete Cosine Transform (DCT)	CAST, Inc.					
	Modulation/Demodulation						
	Numerically Controlled Oscillator Compiler	Altera					
	DVB-C/J.83 (QAM) Modulator	Commsonic					
	DVB/H T/H Modulator	Commsonic					
	DVB-S2 Modulator	Commsonic					
	Video and Image	Processing					
	Video and Image Processing Suite <sup>1</sup>	Altera					
	JPEG Decoder and Encoder	Barco Silex					
	JPEG 2000 Sub-Frame Latency Encoder and Decoder	Barco Silex					
	Multi-channel JPEG 2000 Encoder and Decoder cores	Barco Silex					

Product Name	Vendor Name		
JPEG CODEC	CAST, Inc.		
JPEG Encoders and Decoders	CAST, Inc.		
Lossless JPEG Encoder and Decoder	CAST, Inc.		
H.264 AVC High-Definition (HD) and Extended Definition (ED) Video Encoder	CAST, Inc.		
H.264 Encoders	Jointwave Group LLC		
Arithme	tic		
Floating-Point Addition/ Subtraction	Altera		
Floating-Point Multiplication	Altera		
Floating-Point Division	Altera		
Floating-Point Square Root	Altera		
Floating-Point Compare	Altera		
Floating Point Arithmetic Unit	Digital Core Design		
Floating Point Mathematics Unit	Digital Core Design		
Floating Point Pipelined Divider Unit	Digital Core Design		
Floating Point to Integer Pipelined Converter	Digital Core Design		
Integer to Floating Point Pipelined Converter	Digital Core Design		
Additional Fu	nctions		
AES Engine	Barco Silex		
DES/3DES	Barco Silex		
Hashing	Barco Silex		
Public Key	Barco Silex		
SHA-1	CAST, Inc.		
SHA-256	CAST, Inc.		
AES CODEC	CAST, Inc.		
D/AVE 2D Graphics Hardware Accelerator	TES Electronic Solutions		

<sup>&</sup>lt;sup>1</sup>Qsys-compliant licensed core.

# **Altera and Partner Functions**

	Product Name	Vendor Name			
	32 bit/16	bit			
	Nios II Embedded Processor <sup>1</sup>	Altera			
	ARM Cortex-A9 MPCore Processor	Altera			
	ARM Cortex-M1 <sup>1</sup>	ARM			
	C68000 AHB Microprocessor	CAST, Inc.			
	C68000 Microprocessor	CAST, Inc.			
	C80186EC Microprocessor	CAST, Inc.			
sors	C80186XL Microprocessor	CAST, Inc.			
oces	V1 ColdFire <sup>1</sup>	Freescale			
Embedded Processors	8 bit				
edde	CZ80CPU Processor	CAST, Inc.			
Emb	T8051	CAST, Inc.			
	8051XC2 Microcontroller	CAST, Inc.			
	DP8051 8 bit Microcontroller	Digital Core Design			
	DP8051XP Pipelined, High Performance 8 bit Microcontroller	Digital Core Design			
	DF6811E 8 bit Fast Microcontroller	Digital Core Design			
	DFPIC1655X 8 bit RISC Microcontroller	Digital Core Design			
	Communication				
	8B/10B Encoder/Decoder	Altera			
	POS-PHY Level 4	Altera			
	CRC Compiler	Altera			
	OTN Framer/Deframer	Altera			
Interface and Protocols	SFI-5.1	Altera			
Proto	SONET/SDH Deframer	Aliathon			
and	SONET/SDH Demapper	Aliathon			
face	SONET/SDH Framer	Aliathon			
nter	SONET/SDH Mapper	Aliathon			
_	SDLC Controller	CAST, Inc.			
	Ethernet				
	10-Gbps Ethernet MAC <sup>1</sup>	Altera			
	Triple Speed Ethernet (10/100/1000 Mbps) MAC and PHY <sup>1</sup>	Altera			

Product Name	Vendor Name
10G Base-R PHY	Altera
10G Base-X (XAUI) PHY	Altera
40G Ethernet MAC and PHY	Altera
100G Ethernet MAC and PHY	Altera
MAC-1G/1G PCS GbE MAC and PCS	CAST, Inc.
Ethernet MAC Controller with PCI Host Interface (MAC-PCI)	CAST, Inc.
GbE MAC <sup>1</sup>	IFI
Advanced GbE MAC <sup>1</sup>	IFI
EtherCAT (Software Stack)	IXXAT
Ethernet Powerlink	IXXAT
EtherNET/IP	IXXAT
Fast XAUI	Macnica Americas
10G MAC Lite	Macnica Americas
40G/100G Ethernet	MorethanIP
10GbE MAC and PCS	MorethanIP
RXAUI PCS	MorethanIP
SPAUI MAC	MorethanIP
DXAUI PCS	MorethanIP
QSGMII PCS	MorethanIP
2.5-Gbps Ethernet MAC	MorethanIP
10/100Mbps Ethernet MAC <sup>1</sup>	SLS Corp
EtherNET/IP	Softing AG
EtherCAT (Software Stack)	Softing AG
High Spe	ed
Serial RapidIO®1	Altera
CPRI	Altera
Interlaken	Altera
SerialLite II	Altera
HyperTransport 16 bit	GDA Technologies
SATA 1.0/SATA 2.0	Intelliprop, Inc.
QPI	Intel Corporation
HyperTransport 3.0	University of Heidelberg
	10G Base-R PHY  10G Base-X (XAUI) PHY  40G Ethernet MAC and PHY  100G Ethernet MAC and PHY  MAC-1G/1G PCS GbE MAC and PCS  Ethernet MAC Controller with PCI Host Interface (MAC-PCI)  GbE MAC¹  Advanced GbE MAC¹  EtherCAT (Software Stack)  EtherNET/IP  Fast XAUI  10G MAC Lite  40G/100G Ethernet  10GbE MAC and PCS  RXAUI PCS  SPAUI MAC  DXAUI PCS  QSGMII PCS  2.5-Gbps Ethernet MAC  10/100Mbps Ethernet MAC

<sup>&</sup>lt;sup>1</sup>Qsys-compliant licensed core.

### **Altera and Partner Functions**

	Product Name	Vendor Name
	PCI	
	PCIe Gen1 x1 <sup>1</sup> , x4 <sup>1</sup> , x8 Controller (Soft IP)	Altera
	PCle Gen1 and Gen2 x1, x4, and x8 Lane (Hard IP)	Altera
	PCI Compiler, 32 bit Master/Target	Altera
	PCI Compiler, 32 bit Target	Altera
	PCI Compiler, 64 bit Master/Target	Altera
	PCI Compiler, 64 bit Target	Altera
	PCIe Controller	CAST, Inc.
	PCIe x8 Controller	CAST, Inc.
<del>-</del>	PCI 32/64 bit PCI Master/ Target 33-/66-MHz Controllers	CAST, Inc.
Interface and Protocols (Continued)	PCI Multifunction Target Interface	CAST, Inc.
ocols (C	32 bit PCI Bus Master/ Target Interface	Eureka Technology, Inc.
nd Proto	64 bit PCI Bus Master/ Target Interface	Eureka Technology, Inc.
ice ar	PCIe Gen1 x1, x4, x8 Controller	Northwest Logic, Inc.
Interfa	PCle Complete Core x1, x4, x8	Northwest Logic, Inc.
	PCI-X Controller	Northwest Logic, Inc.
	Integrated PCI Core	Northwest Logic, Inc.
	PCI Interface	Northwest Logic, Inc.
	PCle, Gen1 and Gen2	PLDA
	PCI-X Master/Target Core 32/64 bit	PLDA
	Serial	
	SPI <sup>2</sup>	Altera
	SPI/Avalon® Master Bridge²	Altera
	UART <sup>2</sup>	Altera
	JTAG UART <sup>2</sup>	Altera

<sup>&</sup>lt;sup>1</sup>Qsys-compliant licensed core.

	Product Name	Vendor Name
	JTAG/Avalon Master Bridge <sup>2</sup>	Altera
	C_CAN <sup>1</sup>	Bosch
	I <sup>2</sup> C Bus Controller <sup>1</sup>	CAST, Inc.
	I <sup>2</sup> C Bus Controller Slave	CAST, Inc.
	CAN <sup>1</sup>	CAST, Inc.
	CUSB USB Function Controller	CAST, Inc.
	CUSB2 USB High-Speed Function Controller	CAST, Inc.
	USB High-Speed OTG Multi-point	CAST, Inc.
	Local Interconnect Network (LIN) Controller	CAST, Inc.
	SPI Master/Slave	CAST, Inc.
(pa	H16450S UART	CAST, Inc.
tinu	H16550S UART	CAST, Inc.
(Con	H16750S UART	CAST, Inc.
ocols	MD5	CAST, Inc.
Prote	Smart Card Reader	CAST, Inc.
and	DI2CM I <sup>2</sup> C Bus Interface-Master	Digital Core Design
Interface and Protocols (Continued)	DI2CSB I <sup>2</sup> C Bus Interface-Slave	Digital Core Design
	D16550 UART with 16-Byte FIFO	Digital Core Design
	DSPI Serial Peripheral Interface Master/Slave	Digital Core Design
	SD/MMC SPI	El Camino GmbH
	SDIO/SD Memory/ Slave Controller	Eureka Technology, Inc.
	UART	Eureka Technology, Inc.
	SDIO/SD Memory/ MMC Host Controller	Eureka Technology, Inc.
	Nios_CAN¹	IFI
	Nios II Advanced CAN <sup>1</sup>	IFI
	MediaLB Device Interface <sup>1</sup>	IFI
	I <sup>2</sup> C Master/Slave/PIO Controller	Microtronix, Inc.
	USB 1.1 Host/Device	Microtronix, Inc.
	ATA-4 Host Controller	Nuvation

<sup>&</sup>lt;sup>2</sup>Qsys component (no license required).

### **Altera and Partner Functions**

	Product Name	Vendor Name			
	ATA-5 Host Controller	Nuvation			
	I <sup>2</sup> C Master and Slave	SLS			
	PS2 Interface	SLS			
	USB High-Speed Function Controller <sup>1</sup>	SLS			
(þa	USB Full/Low-Speed Function Controller <sup>1</sup>	SLS			
inue	SD Host Controller <sup>1</sup>	SLS			
Interface and Protocols (Continued)	USB 3.0 SuperSpeed Device Controller	SLS			
ocol	Audio and	Video			
Prot	Character LCD <sup>2</sup>	Altera			
and	Pixel Converter (BGR0 -> BGR) <sup>2</sup>	Altera			
асе	Video Sync Generator <sup>2</sup>	Altera			
ıterf	ASI	Altera			
=	SD/HD/3G-HD SDI	Altera			
	Display Port Receiver	Bitec			
	V-by-One HS	Bitec			
	Video LVDS SERDES Transmitter/Receiver	Microtronic, Inc			
	I2S Audio CODEC <sup>1</sup>	SLS			
	DMA				
	Scatter Gather DMA Controller <sup>2</sup>	Altera			
	DMA Controller <sup>2</sup>	Altera			
ers	DMA for Hard PCIe (EZDMA2)	PLDA			
Controllers	Flash				
Cor	CompactFlash (True IDE) <sup>2</sup>	Altera			
mory	EPCS Serial Flash Controller <sup>2</sup>	Altera			
Mei	Flash Memory <sup>2</sup>	Altera			
Memories and Memory	NFlashCtrl NAND Flash Memory Controller	CAST, Inc.			
mor	NAND Flash Controller	Eureka Technology, Inc.			
Ă	ISA/PC Card/PCMCIA/ CompactFlash Host Adapter	Eureka Technology, Inc.			
	ONFI Controller	Octera			
	CompactFlash Interface <sup>1</sup>	SLS			
		1			

<sup>1</sup> Qsys-compliant	licensed	core.
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<sup>&</sup>lt;sup>2</sup>Qsys component (no license required).

	Product Name	Vendor Name			
	SDRAM				
	DDR SDRAM Controller <sup>1</sup>	Altera			
	DDR2 SDRAM Controller <sup>1</sup>	Altera			
	DDR3 SDRAM Controller <sup>1</sup>	Altera			
	LPDDR2 SDRAM Controller	Altera			
	SDR SDRAM <sup>2</sup>	Altera			
<u> </u>	RLDRAM 2 Controller	Altera			
tinue	DDR SDRAM Controller	CAST, Inc.			
s (Con	SDR SDRAM Controller	CAST, Inc.			
ntrollers	Streaming Multi-Port SDRAM Memory Controller	Microtronix, Inc.			
mory Co	HyperDrive Multi-Port DDR2 Memory Controller	Microtronix, Inc.			
Memories and Memory Controllers (Continued)	Avalon Multi-Port SDRAM Memory Controller <sup>1</sup>	Microtronix, Inc.			
ries	DDR SDRAM Controller	Northwest Logic, Inc.			
lemo	DDR2 SDRAM Controller	Northwest Logic, Inc.			
2	Mobile DDR SDRAM Controller	Northwest Logic, Inc.			
	Mobile SDR SDRAM Controller	Northwest Logic, Inc.			
	SDR SDRAM Controller	Northwest Logic, Inc.			
	RLDRAM 2 Controller	Northwest Logic, Inc.			
	SRAM				
	SSRAM (Cypress CY7C1380C) <sup>2</sup>	Altera			
	QDR II / II+ SRAM Controller	Altera			

The following is a list of Altera and partner development kits. To get the full story, check out our online selector guide.

	Product and Vendor Name	Device	Description
	DSP Development Kit, Cyclone III Edition <sup>1</sup> <b>Altera</b>	Cyclone III EP3C120N	This kit is for general DSP or wireless design engineers, regardless of whether you need pre-processing, DSP plus FPGA coprocessing, or post-processing. This kit includes complete 16-bit high-speed analog-to-digital (A/D) and digital-to-analog (D/A) converters (operating at up to 200 MSPS), as well as interfaces to TI DSP processors (DM642 and DaVinci). Altera's DSP Builder GUI simplifies the information flow between the FPGA toolset and MATLAB/Simulink (30-day evaluation copy included).
	Cyclone III Video and Image Processing Development Kit <sup>1</sup> <b>Bitec</b>	Cyclone III EP3C120N	This kit is designed to help you start developing complex video applications. It supports various video I/O interfaces, allowing you to get your video data in and out of the Cyclone III FPGA. Different video interfaces are supported using the different daughtercards included in this kit: cards supporting ASI/SDI, composite, component, and digital video interfaces (DVIs).
	Software Programmable Reconfiguration (SPR) Development System <b>BittWare</b>	Cyclone III FPGA	This development system provides a system platform to explore software reconfiguration of waveform functionality for high-end signal processing applications such as software-defined radio. The platform provides a flexible, portable, low-cost environment for software-defined radio development in an Advanced Mezzanine Card (AdvancedMC) and Micro Telecommunications Computing Architecture (MicroTCA) environment, enabling you to quickly and cost-effectively bring your waveform designs to life.
	Audio Video Development Kit, Stratix IV GX Edition Altera	Stratix IV GX EP4SGX230	This kit provides a complete video and image processing development environment for design engineers. It features the Stratix IV GX FPGA development board along with an SDI high-speed mezzanine card (HSMC) and associated reference designs.
DSP	DSP Development Kit, Stratix III Edition Altera	Stratix III EP3SL150	This kit comprises a Stratix III development board with a HSMC equipped with 16-bit A/D and D/A converters (operating at up to 200 MSPS). The HSMC also has interfaces to TI DSP processors, allowing the designs that use Stratix III FPGAs to be created both as stand-alone devices and as companion devices. The kit also contains Altera's Quartus II development software, DSP Builder software, and a 30-day trial of MATLAB/ Simulink.
	SC DVI Output Module Bitec	Daughtercard	This module supports all Altera development kits with Altera DVI expansion slots.
	THDB-ADA Terasic Technologies, Inc.	Daughtercard	This card provides dual A/D channels with 14-bit resolution with data rates up to 65 MSPS and dual D/A channels with 14-bit resolution with data rates up to 125 MSPS. It supports both Altera HSMC and Terasic DE-style connectors.
	HSMC Dual-Link DVI Board Bitec	Daughtercard	This daughtercard is a two-channel, dual-link DVI output board for Altera FPGA development kits with HSMC expansion port.
	SDI HSMC Terasic Technologies, Inc.	Daughtercard	This SDI HSMC card is for the development of SDI and AES systems based on transceiver-based host boards with HSMC connectors.
	DE3 Stratix III High Speed Rapid Prototyping System Terasic Technologies, Inc.	Stratix III EP3SL150F1152C2N EP3SE260F1152C2N EP3SL340F1152C2N	This board is the perfect platform for creating your design in programmable logic. DE3 boards are available with either the EP3SL150, the EP3SL340, or the EP3SL260 (DE3-260) devices that are optimized with the extra on-chip multipliers needed for DSP research and development. All of the DE3 boards can be stacked and all feature the same connector for expanding the base functionality with daughtercards.
	OmniTek Audio Video OmniTek	Arria II GX EP2AGX125EF35	This Arria II GX audio and video development kit combines Altera's proven FPGA-based development hardware and associated IP with OmniTek's expertise in video algorithm IP and PCIe interface design to offer a PCIe Gen1 image processing environment.

<sup>&</sup>lt;sup>1</sup> RoHS compliant.

	Product and Vendor Name	Device	Description
	Cyclone IV GX FPGA Development Kit <b>Altera</b>	Cyclone IV GX EP4CGX150DF31C7N	This kit provides a comprehensive design environment that allows you to quickly develop low-cost and low-power FPGA system-level designs. This kit includes the PCIe short card form factor, two HSMC connectors, and a 10/100/1000-Mbps Ethernet interface. Onboard memory includes 128-MB DDR2 SDRAM, 64-MB flash, and 4-MB SSRAM. This kit also includes SMA connectors, 50-,100-, and 125-MHz clock oscillators, as well as user interfaces including push buttons, LEDs, and a 7-segment LCD display.
	Arria II GX FPGA Development Kit, 6G Edition Altera	Arria II GX EP2AGX125F1152	This kit provides a full-featured hardware development platform for prototyping and testing high-speed serial interfaces to an Arria II GX FPGA up to 6G. This kit includes PCIe x8 form factor, one HSMC connector, 128-MB 16-bit DDR3 device, 1-GB 64-bit DDR2 SODIMM, 2-MB SSRAM, and 64-MB flash.
	Arria II GX FPGA Development Kit Altera	Arria II GX EP2AGX125F1152	This kit provides a full-featured hardware development platform for prototyping and testing high-speed serial interfaces to an Arria II GX FPGA. This kit includes PCIe x8 form factor, one HSMC connector, 128-MB 16-bit DDR3 device, 1-GB 64-bit DDR2 SODIMM, 2-MB SSRAM, and 64-MB flash.
onnect	Arria V GX FPGA Development Kit, Arria V GX Edition <b>Altera</b>	Arria V GX 5AGXFB3H6F40C6N	This kit provides a full-featured hardware development platform for prototyping and testing high-speed serial interfaces to an Arria V GX FPGA. This kit includes two Arria V 5AGXFB3H6F40C6N FPGAs, PCIe x8 form factor, two HSMC connectors, one FMC connector, 1,152-MB 72-bit DDR3 SDRAM, 4-MB 36-bit QDR II+ SRAM, flash memory, and two additional 32-bit DDR3 SDRAM devices. This kit also includes SMA connectors and a bull's-eye connector for differential transceiver I/Os.
I/O Interconnect	Arria V GX Starter Kit, Arria V GX Edition <b>Altera</b>	Arria V GX 5AGXFB3H4F35C4	This kit provides a low-cost platform for developing transceiver I/O-based Arria V GX FPGA designs. This kit includes PCIe x8 form factor, one HSMC connector, a 32-bit DDR3 SDRAM device, 1-channel high-speed transceiver input and output connected to SMAs, HDMI output, SDI input and output, 16x2 LCD display, and flash memory.
	Transceiver Signal Integrity Kit, Stratix IV GX Edition Altera	Stratix IV GX EP4SGX230F1517	This kit features eight full-duplex transceiver channels with SMA connectors, 156.25-, 155.52-, 125-, 100-, and 50-MHz clock oscillators, six user push buttons, eight dual in-line package (DIP) switches, eight user LEDs, a 7-segment LCD display, power and temperature measurement circuitry, and Ethernet, USB, and JTAG ports.
	Transceiver Signal Integrity Kit, Stratix V GX Edition <b>Altera</b>	Stratix V GX 5SGXEA7N2F40C2N	This kit enables a thorough evaluation of transceiver signal integrity and device interoperability. Features include seven full-duplex transceiver channels with SMA connectors, two 14G backplane connectors (from Amphenol and Molex), four programmable clock oscillators, four user push buttons, eight DIP switches, eight user LEDs, a 7-segment LCD display, power and temperature measurement circuitry, and Ethernet, embedded USB Blaster™, and JTAG interfaces.
	100G Development Kit, Stratix IV GT Edition <b>Altera</b>	Stratix IV GT EP4S100G5F45I1N	This kit enables a thorough evaluation of 100G designs. It supports 10G/40G line interfaces through optical modules, and applications requiring external memory interfaces through four x18 QDR II and four x32 DDR3 memory banks. With this kit, you can evaluate transceiver performance up to 11.3 Gbps, verify PMA compliance to standards, such as 10G/40G/100G Ethernet, Interlaken, CEI-6G/11G, Serial RapidlO, PCIe (Gen1, Gen2, and Gen3), and other major standards. This kit can also validate interoperability between optical modules, such as SFP, SFP+, QSFP, and CFP.

	Product and Vendor Name	Device	Description
I/O Interconnect (Continued)	100G Development Kit, Stratix V GX Edition <b>Altera</b>	Stratix V GX 5SGXEA7N2F45C2N	This kit enables a thorough evaluation of 100G designs. It supports 10G/40G line interfaces through optical modules, and applications requiring external memory interfaces through four x18 QDR II and four x32 DDR3 memory banks. With this kit, you can evaluate transceiver performance up to 11.3 Gbps, verify PMA compliance to standards, such as 10G/40G/100G Ethernet, Interlaken, CEI-6G/11G, Serial RapidIO, PCIe (Gen1, Gen2, and Gen3), and other major standards. This kit can also validate interoperability between optical modules, such as SFP, SFP+, QSFP, and CFP.
	Stratix IV GX FPGA Development Kit Altera	Stratix IV GX EP4SGX230F1517	This kit provides a full-featured hardware development platform for prototyping and testing high-speed serial interfaces to a Stratix IV GX FPGA. This kit includes PCIe x8 form factor, two HSMC connectors for expandability, and Ethernet, USB, SDI, and HDMI interfaces. Memory includes one x64 DDR3 SDRAM, one x16 DDR3 SDRAM, two x18 QDR II+ SRAM, flash, and SSRAM. This kit also includes two SMA connectors for a differential transceiver output. Several oscillators are available at 156.25-,155.52-, 125-, 100-, and 50-MHz. Other user interfaces include six user push buttons, eight DIP switches, eight user LEDs, 7-segment LCD display, and power and temperature measurement circuitry.
	Stratix IV GX FPGA Development Kit, 530 Edition Altera	Stratix IV GX EP4SGX530F1517	This kit provides a full-featured hardware development platform for prototyping and testing high-speed serial interfaces to a Stratix IV GX FPGA. This kit includes PCle x8 form factor, two HSMC connectors for expandability, and Ethernet, USB, SDI, and HDMI interfaces. Memory includes one x64 DDR3 SDRAM, one x16 DDR3 SDRAM, two x18 QDR II+ SRAM, flash, and SSRAM. This kit also includes two SMA connectors for a differential transceiver output. Several oscillators are available at 156.25-,155.52-, 125-, 100-, and 50-MHz. Other user interfaces include six user push buttons, eight DIP switches, eight user LEDs, 7-segment LCD display, and power and temperature measurement circuitry.
	Stratix V GX FPGA Development Kit <b>Altera</b>	Stratix V GX 5SGXEA7K2F40C2N	This kit provides a full-featured hardware development platform for prototyping and testing high-speed serial interfaces to a Stratix V GX FPGA. This kit includes PCIe x8 form factor, two HSMC connectors for expandability, and Ethernet, USB, and SDI interfaces. Memory includes one x72 DDR3 SDRAM, one x18 QDR II+ SRAM, and flash. This kit also includes two SMA connectors for a differential transceiver output. Several programmable oscillators are available and other user interfaces include three user push buttons, eight DIP switches, eight bi-color user LEDs, an LCD display, and power and temperature measurement circuitry.
	S5-6U-VPX (S56X) BittWare	Stratix V GX/GS	This rugged 6U VPX card is based on Altera's Stratix V GX/GS FPGAs and when combined with BittWare's Anemone FPGA coprocessor, the ARM Cortex-A8 control processor, and the ATLANTIS FrameWork FPGA development kit, it creates a flexible and efficient solution for high-performance signal processing and data acquisition. The board provides a configurable 48-port multi-gigabit transceiver interface supporting a variety of protocols, including Serial RapidlO, PCIe, and 10-Gbps Ethernet (10GbE). Additional I/O interfaces include Ethernet, RS-232, JTAG, and LVDS. The board features up to 8 GB of DDR3 SDRAM as well as flash memory for booting the FPGAs. Two VITA 57 FPGA mezzanine card (FMC) sites provide additional flexibility for enhancing the board's I/O and processing capabilities.
	S4-3U-VPX (S43X) BittWare	Stratix IV GX	This commercial or rugged 3U VPX card is based on Altera's Stratix IV GX FPGA that is designed specifically for serial I/O-based applications, creating a completely flexible, reconfigurable VPX board. BittWare's ATLANTIS FrameWork and the FINe Host/Control Bridge greatly simplify application development and integration of this powerful board. The board provides a configurable 25-port SERDES interface supporting a variety of protocols, including Serial RapidlO, PCIe, and 10GbE. The board also features 10/100/1000 Ethernet, and up to 4 GB of DDR3 SDRAM. The VITA 57-compliant FMC site provides enhanced flexibility, which supports 10 SERDES, 60 LVDS pairs, and six clocks.

	Product and Vendor Name	Device	Description
	GT-3U-VPX BittWare	Stratix II GX EP2SGX90FF1508I4	This ruggedized 3U CompactPCI board is designed for demanding multiprocessor applications requiring complete flexibility and adaptability. It features an Altera Stratix II GX FPGA, a front panel interface supplying four channels of high-speed SERDES tranceivers, and a back panel interface providing RS-232/RS-422 and 10/100 Ethernet. Simultaneous onboard and offboard data transfers can be achieved at a rate of 2 Gbps. It also provides 1 GB of DDR2 SDRAM and 64 MB of flash memory for booting the FPGA and DSP devices.
	GT-3U-cPCI Compact PCI Board BittWare	Stratix II GX EP2SGX90	This ruggedized hybrid signal processing board features a Stratix II FPGA, a TigerSHARC DSP cluster, DDR2 SRAM/QDR SDRAM, flash memory, and an external I/O throughput of 2 Gbps achieved via BittWare's ATLANTIS FrameWork.
I/O Interconnect (Continued)	GT-6U-VME BittWare	Stratix II GX EP2SGX90FF1508I4	This ruggedized 6U VME/VXS (VITA 41) board is designed for demanding multiprocessor-based applications. The hybrid processing architecture takes advantage of both FPGA and DSP technology to provide a complete solution for applications requiring flexibility and adaptability along with high-end signal processing. The board features two high-density Stratix II GX FPGAs, a front panel interface supplying four channels of high-speed SERDES tranceivers, and an extensive back panel interface including VXS. The board can achieve simultaneous onboard and offboard data transfers at a rate of 5 Gbps. It also provides up to 3 GB of DDR2 SDRAM, as well as 128 MB of flash memory for booting the FPGAs and DSP devices.
	S5-PCle-HQ (S5PH-Q) BittWare	Stratix V GX/GS	This half-length PCIe x8 card is based on Altera's Stratix V GX or GS FPGA and is a versatile and efficient solution for high-performance network processing, signal processing, and data acquisition. Combining it with BittWare's Anemone coprocessor and ATLANTIS FrameWork, enhances productivity and portability, and allows even greater processing efficiency. Over 16 GB of on-board memory includes DDR3 SDRAM and QDR II/ II+ SRAM. Two front-panel QSFP+ cages provide additional flexibility for serial I/O, allowing two 40GbE interfaces (or eight 10GbE), direct to the FPGA for reduced latency, making it ideal for high frequency trading and networking applications.
	S5-PCle-DR (S5PE-DR) BittWare	Stratix V GX/GS	This PCIe x16 card features two high-bandwidth, power-efficient Altera Stratix V GX or GS FPGAs and is a flexible and efficient solution for high-performance network processing, signal processing, and data acquisition. Combining it with BittWare's Anemone coprocessor and ATLANTIS FrameWork enhances productivity and portability and allows even greater processing efficiency. The board provides up to 64 GB of DDR3 SDRAM and 576 MB of RLDRAM 3. Four front-panel QSFP+ cages provides additional flexibility, allowing four 40GbE interfaces (or twelve 10GbE), direct to the FPGAs for reduced latency, making it ideal for high frequency trading and networking applications.
	S5-PCle (S5PE) BittWare	Stratix V GX/GS	This PCIe x8 card is based on Altera's Stratix V GX or GS FPGA and is designed for high-performance network processing, signal processing, and data acquisition. Combining it with BittWare's Anemone coprocessor and ATLANTIS FrameWork enhances productivity and portability and allows even greater processing efficiency. The board provides up to 32 GB of DDR3 SDRAM with optional ECC. An optional VITA 57 FMC site provides additional flexibility for enhancing the board's I/O and processing capabilities, making it ideal for analog I/O and processing. The board also has the option of two front-panel QSFP+ cages for serial I/O, which support 10G per lane direct to the FPGA for reduced latency, making it ideal for high frequency trading and networking applications. It is also available with A/D and D/A conversion options.

	Product and Vendor Name	Device	Description
	SP/D4-AMC (D4AM) BittWare	Stratix IV	This board features the I/O processing power of two Altera's Stratix IV FPGA and is a mid- or full-size, single wide AdvancedMC that can be attached to AdvancedTCA carriers or other cards equipped with AMC bays, and used in MicroTCA systems. An Altera Stratix IV GX FPGA paired with a Stratix IV E FPGA makes the D4AM an extremely high-density, flexible board. The FPGAs are connected by two full-duplex 2 GB per second lanes of parallel I/O for data sharing. Each FPGA supports BittWare's ATLANTIS FrameWork to greatly simplify application development and integration. A VITA 57-compliant FMC site provides enhanced flexibility, which connects directly to the Stratix IV E FPGA for LVDS and to the Stratix IV GX FPGA for SERDES. The board also provides an IPMI system management interface and a configurable 18-port AMC SERDES interface supporting a variety of protocols. On-board memory includes up to 1 GB of DDR3 SDRAM and 128 MB of flash memory, and Ethernet is available via the AMC front and rear panels. It is also available with A/D and D/A conversion options.
ontinued)	SP/S4-AMC (S4AM) BittWare	Stratix IV GX	This board is based on Altera's Stratix IV FPGA and is a mid- or full-size, single wide AdvancedMC that can be attached to AdvancedTCA carriers or other cards equipped with AMC bays, and used in MicroTCA systems. The S4AM features a high-density, low-power Altera Stratix IV GX FPGA designed specifically for serial I/O-based applications, creating a completely flexible, reconfigurable AMC. Providing enhanced flexibility is the VITA 57-compliant FMC site, which features eight SERDES, 80 LVDS pairs, and six clocks directly to the FPGA. BittWare's ATLANTIS FrameWork, in conjunction with the FINe III Host/Control Bridge, greatly simplifies application development and integration of this powerful board. The board also provides an IPMI system management interface, a configurable 15-port AMC SERDES interface supporting a variety of protocols, and a front panel 4x SERDES interface supporting CPRI and OBSAI. Additionally, the board features 10/100 Ethernet, GbE, two banks of DDR3 SDRAM, two banks of QDR II+ SRAM, and flash memory for booting the FPGAs and FINe. It is also available with A/D and D/A conversion options.
I/O Interconnect (Continued)	GX-AMC BittWare	Stratix II GX FPGA	This mid-size, single-width AdvancedMC can be attached to Advanced Telecommunications Computing Architecture (AdvancedTCA) carriers or other cards equipped with AdvancedMC bays, and used in MicroTCA systems. The GXAM features a high-density Altera Stratix II GX FPGA, BittWare's ATLANTIS FrameWork (implemented in the FPGA), a front-panel I/O interface, a control plane interface via BittWare's FINe interface bridge, an IPMI system management interface, and a configurable x8 SERDES interface supporting a variety of protocols. It also provides 10/100 Ethernet, GbE, two banks of DDR2 SDRAM, one bank of QDR II SRAM, and flash memory for booting the FPGA and FINe.
	B2-AMC BittWare	Stratix II EP2S90F1020C3	This board supports universal baseband processing for wireless communication infrastructures such as 2G, 2.5G, 3G, WiMAX, and software-defined radio. It attaches to AdvancedTCA carriers or other cards equipped with AdvancedMC bays, and is completely hot-swappable. It uses an Altera Stratix II FPGA, and provides a 10/100/1000 Ethernet interface for command, control, and reprogramming, as well as flash memory for booting the DSP devices and FPGAs.
	4S-XMC (4SXM) BittWare	Stratix IV GX	This is a single-width switched mezzanine card (XMC), designed to provide powerful FPGA processing and high-speed serial I/O capabilities to VME, VXS, VPX, cPCI, AdvancedTCA, or PCIe carrier boards. The 4SXM features a high-density, low-power Altera Stratix IV GX FPGA, which was designed specifically for serial I/O-based applications and is PCI-SIG compliant for PCIe Gen1 and Gen2. Four SFP compact optical transceivers are available on the front panel. Eight multi-gigabit serial lanes supporting PCIe, Serial RapidIO, and 10GbE are available via the board's rear panel as well as 44 general purpose digital I/O signals. The 4SXM also provides QDR II+ SRAM and flash memory.
	S4GX-AMC BittWare	Stratix IV GX EP4SGX230F1517	This board is based on Altera's Stratix IV GX FPGA and is a mid size, single-width AdvancedMC that can be attached to AdvancedTCA carriers or other cards equipped with AdvancedMC bays, and used in MicroTCA systems. This board has two banks of DDR3 SDRAM (up to 1 GB each), and two banks of QDR II SRAM (up to 9 MB). Includes IP support for Serial RapidIO, PCIe, GbE, 10G Ethernet (XAUI), CPRI, and OBSAI interfaces.

	Product and Vendor Name	Device	Description
	SF/GX-AMC BittWare	Stratix II GX EP2SGX130	This board is based on Altera's Stratix II GX FPGA and is a full-size, single-width AdvancedMC that can be attached to AdvancedTCA carriers or other cards equipped with AdvancedMC bays, and used in MicroTCA systems. The SF/GX-AMC has all the features of the GX-AMC card and includes four small form factor pluggable-plus (SFP/SFP+) compact optical transceiver connectors.
	Ethernet USB Expansion Kit Microtronix Inc.	Daughtercard	This kit includes a wireless 802.11b CompactFlash card and a Microtronix CompactFlash board.
	I <sup>2</sup> C Design Kit <b>Microtronix Inc.</b>	Daughtercard	This kit provides an easy way to design, develop, and test the Microtronix I <sup>2</sup> C IP core.
	10/100/1000 Ethernet PHY Daughter Board with Marvell PHY MorethanIP	Daughtercard	This kit provides the ability to implement high-speed Ethernet PHY solutions for prototyping and evaluation and embedded software development.
	10/100/1000 Ethernet PHY Daughter Board with National Semiconductor PHY <b>MorethanlP</b>	Daughtercard	This kit provides the ability to implement fast Ethernet solutions for prototyping and evaluation and embedded software development.
	SFP HSMC Terasic Technologies, Inc.	Daughtercard	This SFP HSMC card is for the development of SGMII Ethernet, Fiber Channel, CPRI/OBSAI, and SONET designs based on transceiver-based host boards with HSMC connectors.
ntinued)	Xpress GX4 Kit PLDA	Stratix IV GX EP4SGX230KF40C2N	This kit provides a complete hardware and software environment for Altera Stratix IV GX FPGAs. It is built around a PCI form factor card compliant with PCI-SIG® and targets the development of designs using PCIe Gen1 or Gen2.
I/O Interconnect (Continued)	PCI-X Development Board Terasic Technologies, Inc.	Cyclone III FPGA	This board provides a hardware platform for developing and prototyping low-power, high-performance, logic-intensive PCI-based designs on an Altera Cyclone III FPGA. External memory is provided to facilitate the development of designs that need extra storage capacity or higher bandwidth memory. It also includes a LVDS interface using high-speed Terasic connectors (HSTCs) for high-speed interface applications.
0/I	Xpress AGX2 Kit PLDA	Arria II GX EP2AGX125EF35	This kit provides a complete hardware and software environment for Altera Arria II GX FPGAs. It is built around a PCI form factor card compliant with PCI-SIG and targets the development of designs using PCIe Gen1.
	Xpress AGX Kit PLDA	Arria GX EP1AGX60DF780C6	This kit provides a complete hardware and software environment for Altera Arria GX FPGAs. It is built around a PCI form factor card compliant with PCI-SIG and targets the development of designs using PCIe Gen1.
	Cyclone IV GX Transceiver Starter Kit Altera	Cyclone IV GX EP4CGX15	This kit provides a low-cost platform for developing transceiver I/O-based FPGA designs. It includes the complete hardware and software you need to develop your FPGA design for cost-sensitive applications. You can measure the FPGA's power consumption, test the signal quality of the FPGA transceiver I/Os (up to 2.5 Gbps), and develop and test PCIe Gen1 designs.
	Transceiver Signal Integrity Development Kit, Stratix IV GT Edition Altera	Stratix IV EP4S100G2F40I1N	This kit enables a thorough evaluation of transceiver interoperability and SERDES signal integrity by allowing you to evaluate transceiver performance up to 11.3 Gbps. You can generate and check pseudo-random binary sequence (PRBS) patterns via a simple-to-use GUI, change differential output voltage ( $V_{00}$ ), pre-emphasis, and equalization settings to optimize transceiver performance for your channel, perform jitter analysis, verify PMA compliance to 40G/100G Ethernet, Interlaken, CEI-6G/11G, PCIe (Gen1, Gen2, and Gen3), Serial RapidIO, and other major standards, and validate interoperability between optical modules.
	TREX S2 Prototyping System Terasic Technologies, Inc.	Stratix II FPGA	This Stratix II FPGA prototyping system provides almost 700 user I/Os and high-speed I/O connections. This board is flexible and configurable, and it provides default motherboards for free—with schematic and design libraries for you to develop your own motherboards.

	Product and Vendor Name	Device	Description
	QuickUSB Starter Kit Bitwise Systems	Cyclone II EP2C20F256C7	This kit includes one QuickUSB module and one QuickUSB Cyclone II Evaluation Board. The evaluation board has a QuickUSB module site on headers that provide access to the signals. The EP2C20F256C7 FPGA connects to nearly every pin of the QuickUSB module, and extra I/O pins go to the headers so you can wire in your circuitry. The kit gets its power from the USB bus, but if you need more power, there is a power connector and a 5V/2A power supply included in the kit.
	C3 Digital Radio Kit CEPD	Cyclone III EP3C16	This kit aids the development and testing of algorithms and signal processing applications including digital radio, modulator/demodulator development, software-defined radio, high-speed data acquisition and signal processing, and audio data acquisition and signal processing. The acquired signals are sampled and then digitally processed by a Cyclone III FPGA. The FPGA card comes with a JTAG programming connector and a configuration PROM to retain the FPGA settings. The PCI card provides interfaces for the FPGA card to a computer PCI bus, RS232 interface, and user push buttons and includes a digital radio reference design example and full documentation.
	Cyclone III FPGA/ PCI Development Board CEPD	Cyclone III EP3C16F484C8N	This board provides a platform for fast and easy prototyping and design verification with the Cyclone III EP3C16F484C8N FPGA. It can be accessed either through the PCI bus or powered as a stand-alone system and accessed through an RS232 port. It comes with an onboard configuration PROM to retain the FPGA settings, an RS232 level shifter, voltage monitor, oscillator, buttons, and LEDs. There is a prototyping area on the board for user circuits and all FPGA pins are accessible through connectors and clearly labeled test points. The connectors are designed to mate with other CEPD daughterboards.
inued)	XpressGXII Kit System Level Solutions	Stratix II GX EP2S- GX130FF1508C3	This kit provides a complete hardware and software environment for Altera Stratix II GX FPGAs. It is built around a PCI form factor card compliant with PCI-SIG and targets the development of designs using PCIe Gen1.
I/O Interconnect (Continued)	SuperUSBC3-55 PLDA	Cyclone III EP3C55U484C6N	This kit provides a low-cost hardware and software environment for prototyping and deploying SuperSpeed USB applications. It targets the Altera Cyclone III FPGA (EP3C55F484C6N) and includes everything you need to implement a complete USB 3.0 subsystem.
I/O Interco	A01 LVDSS FPGA AMC Dallas Logic	Arria GX EP1AGX60	This LVDS transceiver card features the Arria GX FPGA in the F780 BGA package. The backplane interface is user configurable to support several interface standards including PCIe, Serial RapidIO, and GbE. The front panel VHDCI connector supports 28 transmit and 28 receive LVDS links sourced from the FPGA (and 2 clock signals for each transmit and receive connector). Additional features include two 512-Kb x36 synchronous SRAMs, an IPMI 1.5-compliant Module Management Controller (MMC), a 32-Mb serial flash memory, two onboard temperature sensors, USB communication and debug interface, and a 32-bit Mictor debug connector.
	Stratix IV GX/GT 40G/ 100G Interlaken HiTech Global	Stratix IV EP4S100G5 EP4SGX530	This board integrates the most fundamental electrical and optical interfaces for building 200G subsystems. It implements CAUI and Interlaken high-speed serial interfaces, industry-leading, high-speed DDR3 and QDR II+ interfaces, and high-speed parallel interconnect for NetLogic knowledge-based processors (KBPs). The modular design enables expansion to support legacy and emerging optical modules.
	HD FIFO Modules Averlogic	Daughtercard	This board is designed for evaluating the AL460A HD-FIFO. It has two embedded AL460A-7-PBF (or AL460A-13-PBF) devices operating in parallel, expanding the bus width to 32 bits. Control signals and data bus signals are available on two 50-pin connectors. A separate adaptor board (HSMC interface) is available for connecting the module directly to a Cyclone III FPGA Starter Kit.
	Broadcast Video Card Bitec	Daughtercard	This card is designed for professional video equipment developers. The dual ASI/SD-SDI interfaces allow access to industry-standard video transport signals. Based on the latest adaptive cable equalizers and drivers, the ASI/SDI interfaces provide excellent noise immunity up to cable lengths of 350 meters. A VCXO allows precise synchronization to incoming ASI signals. A DVB-T reference design using the Bitec BVDC daughtercard and a Cyclone III FPGA Development Kit is available.

	Product and Vendor Name	Device	Description
I/O Interconnect (Continued)	Quad Video Board Bitec	Daughtercard	This board is based on the Texas Instruments TVP5154 quad video decoder. The analog video inputs include composite video and S-video. Video output is based on the Chrontel CH7010B device, enabling single-link DVI, component analog, and composite analog outputs. The device accepts digital, parallel video data, and clocking from the host FPGA via the HSMC connector, which configures and monitors the device over an I <sup>2</sup> C link. A DVI output connector and mini-DIN output connector are provided.
	HDMI Receiver/Transmitter Microtronix	Daughtercard	This daughtercard interfaces a HDMI receiver and transmitter to your Altera FPGA development kit using the HSMC expansion connector. The receiver also supports an analog component video (YCbCr) interface. The card uses the Analog Device AD9889 HDMI Transmitter and AD9880 HDMI Receiver to support HDTV formats up to 1080p at 60 Hz. The receiver offers the flexibility of both an analog interface and an HDMI receiver integrated on a single chip.
	Quad Link LVDS Interface Microtronix	Daughtercard	This daughtercard supports receive and transmit LVDS links, each consisting of five data channels and one clock for a total of 48 LVDS channels. The standard configuration of 20 TX + 4 clk and 20 RX + 2 clk, is capable of supporting LCD display panels up to 1080p at 100/120 Hz. Onboard LVDS termination resistors can be removed to convert receiver channels into transmitters as required to support 12- or 14-bit color applications. It is used for capturing LVDS video data, connecting to a camera link interface, or for connecting to LCD panels using LVDS, mini-LVDS, RSDS, and PPDS low-voltage panel interface signaling.
	CX4 to HSMC Adapter MorethanIP	Daughtercard	This passive daughtercard for 10GbE CX-4 copper interconnect prototyping features a four-lane differential 3.125-Gbps connector (CX-4) for 10GbE IEEE 802.3ak, a 160-pin HSMC to the main board, and compatibility with Stratix II GX mother boards that use HSMC connectors.
Embedded	Industrial Networking Kit Terasic Technologies, Inc.	Cyclone IV E EP4CE115	The Industrial Networking Kit (INK) offers a comprehensive development platform for industrial automation and applications. The kit consists of the DE2-115 board featuring the Altera Cyclone IV device and dual 10/100/1000-Mbps Ethernet, 128-MB SDRAM, 8-MB flash memory, 2-MB SRAM, HSMC and GPIO connectors, USB 2.0, an SD card slot, switches and buttons, LEDs, 16x2 display, audio and video, and VGA-out. The kit also includes an Industrial Communications Board (ICB-HSMC) that supports RS-485, RS-232, CAN, and additional I/O expansion.
	Nios II Embedded Evaluation Kit, Cyclone III Edition <sup>1</sup> <b>Altera</b>	Cyclone III EP3C25N	This kit includes a complete hardware and software design environment for a 32-bit microcontroller plus FPGA evaluation. Beginners can check out the pre-built, eye-catching demos displayed on the LCD touch screen or do some lightweight development. Advanced microcontroller designers can learn about the "hottest" techniques, multiprocessor systems, hardware acceleration using Nios II C2H Compiler, or about designing a complete system in 30 minutes.
	Cyclone III FPGA Development Kit <b>Altera</b>	Cyclone III EP3C120N	This kit contains 8-MB SSRAM, 256-MB DDR2 SDRAM, 64-MB flash, configuration via USB, 10/100/1000 Ethernet and USB ports, onboard oscillators and SMAs, graphics LCD and character LC displays, two HSMC expansion connectors, three HSMC debug cards, and onboard power measurement circuitry. Complete documentation including reference designs: <i>Create Your First FPGA Design in an Hour</i> and <i>Measure Cyclone III FPGA Power.</i> This kit also includes Quartus II Web Edition design software, an evaluation edition of Nios II processor plus related design suite, and the Altera IP library.
	Nios II Development Kit, Cyclone III Edition <sup>1</sup> <b>Altera</b>	Cyclone III EP3C120N	This development kit has been outfitted with the latest in cutting-edge hardware and software technology. The unique combination of high-performance embedded processor power and easy-to-use integrated design software has been updated to take advantage of Cyclone III devices, the industry's lowest cost, first-to-market 65-nm FPGA family. This development kit provides an ideal environment for developing and prototyping a wide range of price-sensitive, high-performance embedded applications.
	Lancelot VGA IP Design Kit Microtronix Inc.	Daughtercard	This kit includes a small hardware board with a 24-bit RAMDAC, VGA connector, stereo audio connector, and two PS/2 connectors.
	Compact Flash Expansion Kit Microtronix Inc.	Daughtercard	This inexpensive module allows the addition of compact flash cards to the Microtronix Product Starter Kit development board system.

<sup>&</sup>lt;sup>1</sup> RoHS compliant.

	Product and Vendor Name	Device	Description
ntniued)	Low Power Reference Platform Arrow	Cyclone III EP3C25 MAX IIG EPM240T100	This platform uses the low-power Altera Cyclone III FPGAs and MAX II G CPLDs. It demonstrates how to minimize power consumption in portable and battery-powered embedded systems and gives you the flexibility to create application-specific low-power solutions.
	MotionFire Arrow	Cyclone III EP3C40F484	This kit contains all you need for developing complex motor control applications based on Cyclone III FPGAs. It includes a Nios II reference design, advanced regulators implemented in hardware, generic current, speed, and position regulators with feedback from incremental encoders or hall sensors, a trajectory generator with linear acceleration and velocity feed-forward implemented in software, and much more.
	BeMicro SDK Arrow	Cyclone IV E EP4CE22F17C7N	This Arrow BeMicro SDK enables a quick and easy evaluation of soft core processors for both embedded software developers and hardware engineers. The kit builds on the success of the original BeMicro evaluation kit by adding features such as Mobile DDR memory, Ethernet, and even the option of using a file system by slotting in a micro-SD card. The BeMicro SDK connects to a PC via a USB connection, which is used for power, programming, and debug. Arrow has a number of reference designs and pre-built software templates that can be downloaded for this kit that highlight the benefits of building embedded systems in FPGAs.
Embedded (Contniued)	MimoKit Comsis	Stratix II EP2S180F1020C5 x2	This kit is designed for extensively networked embedded applications that require wireless LAN connectivity and GbE. It provides the multiple-input multiple-output (MIMO) RF and analog front end consisting of two major sub-blocks. The analog block is made of three IQ CODECs that perform the conversions between the digital and analog domains. The radio block consists of three 2.4-GHz/5-GHz dual-band radio transceivers.
	ARM-MPS Gleichmann Electronics	Stratix III	This platform offers total flexibility for prototyping your ARM Cortex-M3-based designs. It allows unrestricted access to the latest ARM Cortex-M-class processors. It is delivered with a comprehensive range of tools that allow fast and easy system design—drag and drop the supplied IP components to configure the system, or implement your own system blocks. Then synthesize the design and update the board with a single mouse-click. The tool suite also includes system configuration utilities and a JTAG signal monitor together with software development tools and a JTAG debug probe.
	CMCS002M Controller FPGA Module Dallas Logic	Cyclone III EP3C25	This module allows you to implement general logic functions and Nios II processor operations in a compact form factor module. The module uses the Cyclone EP3C25 FPGA, 512K x8 SRAM, EP1S16 FPGA serial loader (FPGA and Nios II boot), and a USB 2.0 peripheral port (low-/full-speed operation). This module also supports the Cardstac specification (master or slave standard card, 128 pins), and can interface with other modules designed to that specification.
	DN7020k10 The Dini Group	Stratix III Stratix IV	This complete logic prototyping system gives ASIC and IP designers a vehicle to prototype logic and memory designs using up to 20 Stratix III or Stratix IV devices.
ASIC Prototyping	DN7006K10PCle-8T The Dini Group	Stratix III Stratix IV	This complete logic prototyping system with a dedicated PCIe interface gives ASIC and IP designers a vehicle to prototype logic and memory designs using up to six Stratix III or Stratix IV devices.
ASIC Pro	DIGILAB SX III El Camino GmbH	Stratix III	This universal FPGA prototyping platform based on Altera's largest Stratix III devices supports 2-MB flash, 2-MB SRAM, four Samtec expansion connectors, two Mictor connectors, user LEDs, and push buttons along with RS-232, SPI, and USB interfaces.
	PROC30M , PROC9M GIDEL	Stratix III	This system is for the debug and verification of SoC ASIC designs from 3 to over 100 million gates in size, with the ability to run at system clock speeds up to 300 MHz.
	PROCStar II, ProcStar III GiDEL	Stratix II Stratix III	This system provides high-capacity, high-speed, multi-FPGA-based prototyping and end system platforms.

	Product and Vendor Name	Device	Description
	DNMEG S2GX Stratix II GX-Based ASIC Prototyping Kit <b>The Dini Group</b>	Stratix II GX	This logic emulation daughtercard enables ASIC or IP designers to cost-effectively prototype logic and memory designs. The DNMEGS2GX is hosted on any DN7000 or DN8000 series ASIC Dini Group product, but can also be used alone.
	Single-FPGA (Tile) Prototyping Solution Polaris Design Systems	Stratix IV	This single-FPGA prototyping board can accommodate up to 15M gate designs. It has a single Stratix IV FPGA and 18 Mb of SRAM. The board can be used either in a rack-mountable system or as a stand-alone unit.
	Multi-FPGA (Logic) Prototyping Solution <b>Polaris Design Systems</b>	Stratix IV	This multi-FPGA prototyping board can accommodate up to 30M gate designs. The board has three Stratix IV FPGAs, SRAM, and 2 GB of DDR3 (expandable to 8 GB). The board can be used either in a rack-mountable system or as a stand-alone unit.
	DN7002k10MEG The Dini Group	Stratix IV EP4SE820F43CxN EP4SE530F43CxN	This complete logic emulation system allows you to prototype SoC logic and memory designs. It can operate as a stand-alone system, or be hosted via a USB interface. A single system, configured with two Stratix IV EP4SE820 FPGAs, can emulate up to 13 million gates. All FPGA resources are available for the target application. Each FPGA position can use any available speed grade.
ASIC Prototyping (Contniued)	DN7406k10PCle-8T The Dini Group	Stratix IV EP4SE820F43CxN EP4SE530F43CxN	This complete logic prototyping system allows you to prototype logic and memory designs. The DN7406k10PCle-8T is hosted in an eight-lane PCle Gen1 bus, but can be used as a stand-alone system configured via USB or CompactFlash. A single board configured with six Altera Stratix IV EP4SE820 FPGAs can emulate up to 31 million gates. All of the FPGA resources are available for your application, and any combination of speed grades can be used.
ASIC Proto	DNMEG S2GX The Dini Group	Stratix II GX EP2SGX90EF1152C3N	This daughtercard enables you to prototype logic and memory designs. It is hosted on any DN8000- or DN7000-series ASIC emulation products from the Dini Group, but can be used as a stand-alone system It contains the Stratix II GX EP2SGX90 (speed grades -5, -4, or -3) and can emulate over 600K gates. One DDR2 SDRAM SODIMM is provided, allowing the FPGA to address up to 2 GB of memory.
	Stratix IV E FPGA Development Kit Altera	Stratix IV E EP4SE530	This kit allows rapid and early development of designs for high-performance Stratix IV FPGAs. The development board provides general I/Os that connect to onboard switches and indicators, and to the included two-line LCD and 128 x 64 graphics display. The board also has non-volatile and volatile memories (64-MB flash, 4-MB pseudo-SRAM, 36-Mb QDR II SRAM, 128-MB DDR2 DIMM, and 16-MB DDR2 device), HSMC, and 10/100/1000 Ethernet interfaces. The kit is delivered with Quartus II software and all of the cabling required to start using the board straight out of the box.
	Stratix III FPGA Development Kit Altera	Stratix III EP3SL150	This kit allows rapid and early development of designs for high-performance Stratix III FPGAs. The development board provides general I/Os that connect to onboard switches and indicators, and to the included two-line LCD and 128 x 64 graphics display. The board also has non-volatile and volatile memories (64-MB flash, 4-MB pseudo-SRAM, 36-Mb QDR II SRAM, 128-MB DDR2 DIMM, and 16-MB DDR2 device), HSMC, and 10/100/1000 Ethernet interfaces. The kit is delivered with Quartus II software and all of the cabling required to start using the board straight out of the box.
nrpose	Stratix V Advanced Systems Development Kit <b>Altera</b>	Stratix V 2x 5SGXEA7N2F45C2N	This kit is a complete systems design environment that includes both the hardware and software needed to begin architecture development and system design using Stratix V FPGA designs. The PCle-based form-factor utilizes a x16 edge connector, and includes high memory bandwidth to DDR3, QDR II+, and serial memory. Multiple high-speed protocols are accessible through FMC and HMSC connections.
General Purpose	Cyclone III FPGA Starter Kit <sup>1</sup> <b>Altera</b>	Cyclone III EP3C25N	This kit contains 1-MB SSRAM, 16-MB DDR SDRAM, 16-MB parallel flash, configuration via USB, four user push buttons, four user LEDs, and power measurement circuitry. Complete documentation including reference designs: Create Your First FPGA Design in a Hour, Measure Cyclone III FPGA Power, and Create Your First Nios II Design. This kit also includes Quartus II Web Edition design software, the evaluation edition of Nios II processor plus related design suite, and Altera IP library.

<sup>&</sup>lt;sup>1</sup> RoHS compliant.

	Product and Vendor Name	Device	Description
	Video Development Kit Bitec	Cyclone III FPGA	This kit contains the Cyclone III FPGA Development Kit and two HSMC video interface cards together with a collection of IP cores and reference designs. The kit provides a variety of video interface standards including both digital and analog up to HD resolutions.
	ViClaro III HD Video Enhancement Development Platform <b>Microtronix</b>	Cyclone III FPGA	This video enhancement development platform supports 100/120-Hz HDTV that is 1080p bandwidth-capable and features 32-bit DDR2 SDRAM memory, a HDMI transmitter, an analog/HDMI receiver, and dual LVDS links.
	MAX II Micro Terasic Technologies, Inc.	MAX II CPLD	This kit, equipped with an Altera MAX II EPM2210F324C3 device (largest CPLD in the MAX II series) and an onboard USB-Blaster cable, functions as a development and education board for CPLD designs. This kit also includes reference designs with source code.
	DIGILAB picoMAX Prototyping Board and Starter Kit El Camino GmbH	MAX EPM3032A to EPM7160S	This MAX 3000/MAX 7000 starter kit includes downloading and programming hardware.
	DB3128 <b>EBV</b>	MAX EPM3128A	This low-cost MAX 3000A CPLD development board with 128 macrocells provides an easy entry point into Altera's CPLD technology.
	DB3256 <b>EBV</b>	MAX EPM3256A	This 5.2-megapixel camera daughtercard provides selectable frame rates and resolutions.
(pən	PM410 StarFabric Compact PCI Carrier Board Parsec	MAX EPM3256A	This board consists of two 3.3-V PMC sites, 32-/64-bit 33-/66-MHz PCI buses, 2.5-Gbps StarFabric links on J3, and supports full PCI bandwidth.
General Purpose (Continued)	TRDB_DC2 1.3 Megapixel Camera Module Terasic Technologies, Inc.	Daughtercard	This module consists of complete digital camera reference designs with source code in Verilog HDL and a user manual with live demo examples. It supports exposure, light control, and motion capture.
ral Purpo	TRDB_LCM Digital Panel Daughtercard Terasic Technologies, Inc.	Daughtercard	This 3.6" digital panel development kit consists of reference designs (TV player and color pattern generator) with source code in Verilog HDL.
Gene	HSMC DVI Input/Output Module Bitec	Daughtercard	This DVI transmitter/receiver module for the HSMC interface enables you to interface FPGA projects to real-world DVI signals.
	SC DVI Input Module Bitec	Daughtercard	This DVI module for the Santa Cruz interface enables you to interface FPGA projects to real-world DVI signals.
	SC DVI Output Module Bitec	Daughtercard	This DVI module for the Santa Cruz interface enables you to drive high-resolution displays with digital clarity.
	SC Camera Bitec	Daughtercard	This board features a 5.2-megapixel camera daughtercard with selectable frame rates and resolutions.
	SC Proto Bitec	Daughtercard	This prototyping board for the Santa Cruz interface has convenient access points to power and ground with connector break-out.
	Hpe-midiv2 Gleichmann Electronics	Stratix III EP3SL150	This complete development environment provides a large number of onboard PHY and a range of child boards with various auxiliary functions for developing large and complex systems. It consists of a motherboard with the latest Stratix III modules and all of the latest interfaces on a single platform. It comes with a GUI for access to a set of free tools including system configuration utilities, JTAG debugger and scanner, and clock factory programmer.
	DEO Development Board Terasic Technologies, Inc.	Cyclone III EP3C16F484C6N	This board provides all the essential tools for you to learn about digital logic and FPGAs. It is equipped with an Altera Cyclone III EP3C16 FPGA, which offers 15,408 LEs. The board provides 346 user I/O pins and is loaded with a rich set of features. It is suitable for advanced university and college courses as well as the development of sophisticated digital systems, and includes software, reference designs, and accessories.

	Product and Vendor Name	Device	Description
	DE1 Development Board Terasic Technologies, Inc.	Cyclone II EP2C20 FPGA	This board is a smaller version of the DE2 board. It is useful for learning about digital logic and FPGAs. Featuring an Altera Cyclone II EP2C20 FPGA, it is designed for university and college laboratory use, and is suitable for a wide range of exercises in courses on digital logic and computer organization.
	DE2 Development Board Terasic Technologies, Inc.	Cyclone II EP2C35 FPGA	This board was designed by professors, for professors. It is an ideal vehicle for learning about digital logic and FPGAs. Featuring an Altera Cyclone II EP2C35 FPGA, the DE2 board is designed for university and college laboratory use. It is suitable for a wide range of exercises in courses on digital logic and computer organization.
	DE2-70 Digital Camera and Multimedia Development Platform Terasic Technologies, Inc.	Cyclone II EP2C70F896C6N	This board is a modified version of the Altera DE2 board with a larger FPGA and more memory. It is an excellent vehicle for learning about digital logic and FPGAs. Featuring an Altera Cyclone II EP2C70 FPGA, the DE2 board is designed for university and college laboratory use.
	DE2-115 Development and Education Board Terasic Technologies, Inc.	Cyclone IV E EP4CE115	This board is part of the DE2 educational development board series and features the Cyclone IV E EP4CE115 FPGA. The DE2-115 offers an optimal balance of low cost, low power and a rich supply of logic, memory and DSP capabilities, as well as interfaces to support mainstream protocols including GbE. A HSMC connector is provided to support additional functionality and connectivity via HSMC daughtercards and cables.
(pai	MAX II/MAX IIZ Development Kit System Level Solutions	MAX II EPM240 EPM240Z	This board provides a hardware platform for designing and developing simple and low-end systems based on Altera MAX II/MAX IIZ devices. The board features a MAX II/MAX IIZ EPM240T100Cx/EPM240ZM100Cx device with 240 LEs and 8,192 bits of user flash memory (UFM). The board also supports vertical migration into EPM570T100Cx devices with 570 LEs and 8,192 bits of UFM.
e (Continu	MAX V CPLD Development Kit <b>Altera</b>	MAX V 5M570Z	This low-cost platform will help you quickly begin developing low-cost, low-power CPLD designs. Use this kit as a stand-alone board or combined with a wide variety of daughtercards that are available from third parties.
General Purpose (Continued)	CoreCommander Development Kit System Level Solutions	Cyclone III EP3C25F256C8	This kit features the Altera Cyclone III FPGA that provides more than enough room for almost any embedded design. This flexible board comes with a suite of SLS IP Cores, drivers, and application software. Delivered as a complete package, this kit ensures quick and easy implementation of industry-leading cores with reduced risk, at a very low cost.
9	Cyclone III LS FPGA Development Kit <b>Altera</b>	Cyclone III LS EP3CLS200F780C7N	This kit combines a high-density, low-power Cyclone III LS FPGA with a complete suite of security features implemented at the silicon, software, and IP levels. These security features provide passive and active protection of your IP from tampering, reverse engineering, and counterfeiting. It uses the EP3CLS200 FPGA—200K LEs at less than 0.25-W static power.
	DB Start 3C10 EBV Elektronik GmbH and Co. KG	Cyclone III EP3C10E144C8N	This starter kit is ideal for starting your first experiments based on Cyclone III FPGAs. It is designed for ease of use, with embedded USB-Blaster cable and pin header for peripherals. It can be powered via USB, and it features a Linux BSP, a PCI solution for high data throughput, a local bus solution for low-latency data transmission including a local bus IP core, and several industry-standard interfaces such as CAN and RS485.
	DB1270-144 EBV Elektronik GmbH and Co. KG	MAX II DB1270T144C5N	This kit enables you to evaluate the MAX II feature set or begin prototyping a design prior to receiving custom hardware. It includes all software, cables, and accessories needed to ensure an easy and productive evaluation of the MAX II CPLD. It includes the MAX II EPM1270T144C5ES CPLD, eight LEDs, four push buttons, a 7-segment display, serial I/O connectors (RS-232 DB9 port), and an 8-bit DIP switch.
	HSMC Prototyping Board Bitec	Daughtercard	This board provides a solution for prototyping circuits and testing them together with the latest Altera FPGA development kits. This board provides access to the complete set of HSMC signals via a footprint of standard 0.1" pitch headers. The HSMC power pins are accessed via fuses for added security. The main prototype matrix comprises a 0.1" grid interleaved with +3.3-V and GND access points. Footprints for commonly used 25-way and 9-way D-type connectors are included on the board.

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# Altera Instructor-Led and Virtual Classroom Courses Virtual Classroom Courses Denoted with a \*

(All Courses Are One Day in Length Unless Otherwise Noted)

	(All Courses Are One Day in Length Unle	ss Otherwise Noted)
Course Category	General Description	Course Titles
Productivity	Learn the recommended design methodology to maximize productivity and minimize design cycle time	Best Practices for Maximizing FPGA Design Productivity*     (course length: two days)
Design languages	Attain the skills needed to design with Verilog HDL and VHDL for programmable logic	<ul> <li>Introduction to VHDL*</li> <li>Advanced VHDL Design Techniques*</li> <li>Introduction to Verilog HDL*</li> <li>Advanced Verilog HDL Design Techniques*</li> </ul>
Software	Acquire design entry, compilation, programming, verification, and optimization skills by learning how to use both basic and advanced features of Quartus II software	<ul> <li>The Quartus II Software Design Series: Foundation*</li> <li>The Quartus II Software Debug and Analysis Tools</li> <li>The Quartus II Software Design Series: Timing Analysis*</li> <li>Timing Closure with the Quartus II Software*</li> <li>Advanced Timing Analysis with TimeQuest*</li> <li>Design Optimization Using Quartus II Incremental Compilation*</li> </ul>
System integration	Build hierarchical systems by integrating IP and custom logic	<ul> <li>Introduction to the Qsys System Integration Tool</li> <li>Advanced Qsys System Integration Tool Methodologies</li> </ul>
Embedded Design	Learn to design a Nios II soft-core microprocessor system in an Altera FPGA	<ul> <li>Designing with the Nios II Processor</li> <li>Developing Software for the Nios II Processor (2-day course)</li> </ul>
Memory interfaces	Implement interfaces to external memory	Implementing, Simulating, and Debugging External Memory Interfaces
System Design	Solve DSP and video system design challenges using Altera technology	<ul> <li>Designing with DSP Builder Standard Blockset</li> <li>Designing with DSP Builder Advanced Blockset*</li> <li>Video Design Framework Workshop</li> </ul>
Design security	Create secure, reliable designs using the Quartus II software design separation flow	• Cyclone III LS Design Separation Flow*
Transceivers	Build high-speed, gigabit interfaces using embedded transceivers found in leading-edge FPGA families	Building Gigabit Interfaces in Altera Transceiver Devices

### **Online Training**

	Altera Free Online Training Courses (Courses Are Approximately One Hour in Le	ngth)
Course Category	Course Titles	Languages
	Read Me First!	English, Chinese, and Japanese
Getting started	Basics of Programmable Logic	English, Chinese, and Japanese
	How to Begin a Simple FPGA Design	English, Chinese, and Japanese
	VHDL Basics	English and Chinese
	Verilog HDL Basics	English and Chinese
Design languages	Read Me First!  Basics of Programmable Logic  Basics of Programmable Logic  How to Begin a Simple FPGA Design  VHDL Basics  Verilog HDL Basics  Verilog HDL Basics  SystemVerilog with the Quartus II Software  Best HDL Design Practices for Timing Closure  Using the Quartus II Software: An Introduction  The Quartus II Software Interactive Tutorial  The Quartus II Software Design Series: Foundation (note: this training is equivalent to the instructor-led course of the same name)  What's New in the Quartus II Software Version 12.0  English only  Setting Up Floating Licenses  English only  English only	
	Best HDL Design Practices for Timing Closure	
	Using the Quartus II Software: An Introduction	
	Using the Quartus II Software: An Introduction  The Quartus II Software Interactive Tutorial  The Quartus II Software Design Series: Foundation (note: this training is equivalent to the instructor-led course of the same name)  What's New in the Quartus II Software Version 12.0  English and Chinese  English and Chinese  English only  English only  Setting Up Floating Licenses  Synplify Pro Tips and Tricks  English only  English only	
		English and Chinese
	What's New in the Quartus II Software Version 12.0	and Japanese  English only  English and Chinese  English only  English only  English only  English only  English and Chinese  Japanese only  English, Chinese,
	Setting Up Floating Licenses	English only
	Synplify Pro Tips and Tricks	English only
	Using Quartus II Software: Schematic Design	English and Chinese
	Quartus II Settings and Assignments	Japanese only
	Introduction to Incremental Compilation	
	I/O System Design	
	Advanced I/O System Design	English and Chinese
	Managing Metastability with the Quartus II Software	English only
	Synplify Synthesis Techniques with the Quartus II Software	English only
	Overview of Mentor Graphics ModelSim Software	English and Japanese
	SignalTap II Embedded Logic Analyzer: Getting Started	
Varification	Using Quartus II Software: Chip Planner	English only
and debugging	Debugging and Communicating with an FPGA Using the Virtual JTAG Megafunction	English only
(note: this training is equivalent to the instructor-led course of the same name)  What's New in the Quartus II Software Version 12.0  Setting Up Floating Licenses  Software overview and design entry  Synplify Pro Tips and Tricks  Using Quartus II Software: Schematic Design  Quartus II Settings and Assignments  Introduction to Incremental Compilation  Introduction to Incremental Compilation  Introduction to Incremental Compilation  I/O System Design  Advanced I/O System Design  English and Chinese, and Japanese  English only  Synplify Synthesis Techniques with the Quartus II Software  SignalTap II Embedded Logic Analyzer: Getting Started  Using Quartus II Software: Chip Planner  Debugging and Communicating with an FPGA Using the Virtual JTAG Megafunction  English and Chinese  English only  English only	English and Chinese	
	English only	
	English only	

# **Online Training**

Course Category	Course Titles	Languages				
course category	Course rities					
	TimeQuest Timing Analyzer	English, Chinese, and Japanese				
	Timing Closure Using Quartus II Advisors and Design Space Explorer	English and Chinese				
Timing analysis and closure  Memory interfaces	Timing Closure Using Quartus II Physical Synthesis Optimizations	English and Chinese				
	Timing Closure Using TimeQuest Custom Reporting	English only				
	Design Evaluation for Timing Closure	English only				
	Good High-Speed Design Practices	English only				
	Using High-Performance Memory Interfaces in Altera FPGAs	English only				
	External Memory Solutions Overview	English only				
	Transceiver Basics	English, Chinese, and Japanese				
Transceiver-based design and high-speed protocols	Transceiver Toolkit	English only				
	Transceiver Reconfiguration in Altera 28-nm Devices	English only				
	Decision Feedback Equalization and Adaptive Equalization in Stratix IV GX/GT Devices	English only				
	Advanced Signal Conditioning for Stratix IV and Stratix V Receivers	English only				
	Getting Started with Altera's 28-nm PCI Express Solutions	English only				
	Getting Started with PCI Express Designs in Altera Transceiver Devices	English only				
	Custom Protocol Design in Altera 28-nm Devices	English only				
	Serial RapidIO Design with Altera 40-nm Devices	English only				
	Introduction to Altera's 10/100/1000 Mb Ethernet Solutions	English only				
	Introduction to Altera's 10-Gb Ethernet Solutions	English only				
	High-Speed Serial Protocol Design with Altera Transceiver Devices	English and Chinese				
	Dynamic Reconfiguration in Altera Transceiver Devices	English and Chinese				
	Triple-Rate SDI	English only				
	Introduction to Qsys	English and Japanese				
	Advanced System Design Using Qsys	English only				
	Qsys Custom Components	English only				
	Designing with DSP Builder Advanced Blockset: An Overview	English only				
	DSP Builder Standard Blockset: An Overview	English only				
ystem Design	Building Video Systems	English and Chinese				
	Variable-Precision DSP Blocks in Altera 28-nm FPGAs	English only				
	Viterbi Decoder	English only				
	High Performance Floating Point Processing with FPGAs	English only				
	Implementing Video Systems	English only				

### **Online Training**

	Altera Free Online Training Courses (Courses Are Approximately One Hour in Leng	th)				
Course Category	Course Titles	Languages				
	Creating Reusable Design Blocks	English only				
	Using Cascaded-Integrator-Comb Filter in Multirate Digital Systems	English only				
ystem Design Continued)	FIR Compiler II	English only				
Ava Indi	Avalon Verification Suite	English only				
	Industrial Ethernet Solutions	English and Chinese				
Embedded systems	Designing with the Nios II Processor and Qsys - Day 1 (Online Training)	English and Japanese				
	Developing Software for the Nios II Processor: Tools Overview	English, Chinese, and Japanese				
	Developing Software for the Nios II Processor: Design Flow	English and Chinese				
	SoC Hardware Overview - (Part 1)	English only				
	SoC Hardware Overview - (Part 2)	English only				
	Using the Nios II Processor	English, Chinese, and Japanese				
	Developing Software for the Nios II Processor: Nios II Software Build Tools for Eclipse	English and Japanese				
	Nios II Software Build Tools for Eclipse and BSP Editor (Quartus II Software 10.0 Update)	English only				
	Developing Software for the Nios II Processor: HAL Primer	English, Chinese, and Japanese				
	Developing Software for the Nios II Processor: Software Build Flow - (Part 1)	English only				
	Developing Software for the Nios II Processor: Software Build Flow - (Part 2)	English only				
	Developing Software for the Nios II Processor: C2H Fundamentals	English and Japanese				
	Nios II Floating-Point Custom Instructions	English, Chinese, and Japanese				
	Developing Software for the Nios II Processor: MMU and MPU	English and Chinese				
	Lauterbach Debug Tools	English only				
	Introduction to Graphics	English only				
	Introduction to D/AVE GPU	English only				
Device-specific training	Power Distribution Network Design for Stratix III and Stratix IV FPGAs	English and Chinese				
	Power Distribution Network Design Using Altera PDN Design Tools	English only				
	Configuring Altera FPGAs	English and Chinese				
	The Quartus II Software Design Flow for HardCopy ASICs	English only				
	Command-Line Scripting	English only				
cripting	Introduction to Tcl	English only				
	Quartus II Software Tcl Scripting	English and Japanese				

Altera device transceivers support the protocols and data rates listed in the following table.

		Protocols	, Devices, and Data	Rates		
Protocol	Stratix V GX/GS Data Rates (Gbps per Lane)	Stratix V GT Data Rates (Gbps per Lane)	Stratix IV GX Data Rates (Gbps per Lane)	Stratix IV GT Data Rates (Gbps per Lane)	Stratix II GX Data Rates (Gbps per Lane)	HardCopy IV GX Data Rates (Gbps per Lane)
SDI SD/HD/3G	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97
ASI	0.27	0.27	0.27	0.27	0.27	0.27
Basic (proprietary)	0.6 – 14.1	0.6 – 12.5, 19.6 – 28.05	0.6 – 8.5	0.6 – 11.3	0.6 – 6.375	0.6 – 6.5
CEI-6G/SR/LR	4.976 – 6.375	4.976 – 6.375	4.976 – 6.375	4.976 – 6.375	4.976 – 6.375	4.976 – 6.375
CEI-11G/SR	9.95 – 11.1	9.95 – 11.1	-	9.95 – 11.1	-	-
CEI-28G/VSR	-	19.9 – 28.05	-	-	-	-
CPRI	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144, 9.8304	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144, 9.8304	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144	3.072, 2.4576, 3.072, 0.6142	
Display Port	1.6 / 2.7 / 5.4	1.6 / 2.7 / 5.4	1.6 / 2.7 / 5.4	1.6 / 2.7 / 5.4 1.6 / 2.7 / 5.		1.6 / 2.7 / 5.4
XAUI (10BASE-X)	3.125	3.125	3.125	3.125	3.125	3.125
XFI	10.3125	10.3125	-	10.3125	-	-
CAUI/XLAUI	10.3125	10.3125	-	10.3125	-	-
1000BASE-X (GbE)	1.25	1.25	1.25	1.25	1.25	1.25
10GBASE-R	10.3125	10.3125	-	10.3125	-	-
Fibre Channel	1.0625, 2.125, 4.25, 8.5, 10.52, 14.025	1.0625, 2.125, 4.25, 8.5, 10.52	1.0625, 2.125, 4.25, 8.5	1.0625, 2.125, 4.25, 8.5, 10.52		
GPON	1.244 uplink/ 2.488 downlink, 2.488 uplink/ 9.953 downlink	1.244 uplink/ 2.488 downlink, 2.488 uplink/ 9.953 downlink	1.244 uplink, 2.488 downlink	1.244 uplink, 2.488 downlink		1.244 uplink, 2.488 downlink
G.709 OTU-2	10.7	10.7	-	10.7	-	-
OTN with FEC	11.1, 11.3	11.1, 11.3	-	11.1, 11.3	-	-
HiGig+	3.75	3.75	3.75	3.75	3.75	3.75
HiGig2	4.0625	4.0625	4.0625	4.0625	4.0625	4.0625
HDMI	1.65, 3.4	1.65, 3.4	1.65, 3.4	1.65, 3.4	1.65, 3.4	1.65, 3.4
JESD204A	3.125	3.125	3.125	3.125	3.125	3.125
JESD204B	12.5	12.5	6.375	6.375	6.375	6.375

		Pro	otocols, Devices,	and Data Rates				
Protocol	Arria V GZ Data Rates (Gbps per Lane)	Arria V GX Data Rates (Gbps per Lane)	Arria V GT Data Rates (Gbps per Lane)	Arria II GX/GZ Data Rates (Gbps per Lane)	Cyclone V GX Data Rates (Gbps per Lane)	Cyclone V GT Data Rates (Gbps per Lane)	Cyclone IV GX Data Rates (Gbps per Lane)	
SDI SD/HD/3G	0.270 / 1.485 / 2.970	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	0.27 / 1.485 / 2.97	
10G SDI	10.6921	-	-	-	-	-	-	
ASI	-	0.27	0.27	0.27			-	
Basic (proprietary)	0.6 – 12.5	0.6 – 6.5	0.6 – 10.3125	0.6 – 6.375	0.6 – 3.125	0.6 – 5.0	0.6 – 3.125	
CEI-6G/SR/LR	4.976 – 6.375	4.976 – 6.375	4.976 – 6.375	-	-	-	-	
CPRI	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144,	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144, 9.8304	0.6144, 1.2288, 2.4576, 3.072, 4.9152, 6.144 0.6144, 1.2288, 2.4576, 3.072 2.4576, 3.072 4.915		4576, 3.072, 2.4576, 3.072, 0.6144, 1.2288, 2.4576, 3.072, 2.4576, 3.072, 2.4576, 3.072		0.6144, 1.2288, 2.4576, 3.072
Display Port	1.62, 2.7, 5.4	1.62, 2.7, 5.4	1.62, 2.7, 5.4	-	1.62, 2.7	1.62, 2.7	1.62, 2.7	
XAUI (10BASE-X)	3.125	3.125	3.125	3.125	3.125	3.125	3.125	
XFI	-	-	10.3125	-	-	-	-	
1000BASE-X (GbE)	1.25	1.25	1.25	1.25	1.25	1.25	1.25	
10GBASE-R	10.3125	-	10.3125	-	-	-	-	
Fibre Channel	1.0625, 2.125, 4.25	1.0625, 2.125, 4.25	1.0625, 2.125, 4.25	5, 1.0625, 2.125, 4.25 1.0625, 2.125 1.0625, 2.		1.0625, 2.125, 4.25	-	
GPON	0.155, 0.622, 1.244, 2.488	1.244 uplink, 2.488 downlink	1.244 uplink, 2.488 downlink	1.244 uplink, 2.488 downlink	-	-	-	
HiGig+	3.725	3.75	3.75	3.75	3.75 -		-	
HiGig2	6.25	4.0625	4.0625	-	-	-	-	
HDMI	1.65, 3.4	1.65, 3.4	1.65, 3.4	1.65, 3.4	1.65	1.65, 3.4	1.65	
JESD204A	3.125	3.125	3.125	3.125	3.125	3.125	3.125	
JESD204B	-	6.375	6.375	6.375	-	-	-	

		Protocols,	Devices, and Data	Rates		
Protocol	Stratix V GX/GS Data Rates (Gbps per Lane)	Stratix V GT Data Rates (Gbps per Lane)	Stratix IV GX Data Rates (Gbps per Lane)	Stratix IV GT Data Rates (Gbps per Lane)	Stratix II GX Data Rates (Gbps per Lane)	HardCopy IV GX Data Rates (Gbps per Lane)
HyperTransport 3.0	0.4, 2.4, 2.8, 3.2	0.4, 2.4, 2.8, 3.2	0.4, 2.4, 2.8, 3.2	0.4, 2.4, 2.8, 3.2	-	0.4, 2.4, 2.8, 3.2
10GBASE-KR	10.3125	10.3125	-	-	-	-
Interlaken	3.125 – 12.5	3.125 – 12.5	3.125 – 8.5	3.125 – 11.3	3.125 – 6.375	3.125 – 6.375
OBSAI	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144
PCle Gen1, Gen2, Gen3	2.5, 5, 8	2.5, 5, 8	2.5, 5, N/A	2.5, 5, N/A	2.5, 5, N/A	2.5, 5, N/A
SGMII / QSGMII	1.25 / 4 x 1.25	1.25 / 4 x 1.25	1.25 / 4 x 1.25	1.25 / 4 x 1.25	1.25 / 4 x 1.25	1.25 / 4 x 1.25
RXAUI / DXAUI	6.25 / 4 x 6.25	6.25 / 4 x 6.25	6.25 / 4 x 6.25	6.25 / 4 x 6.25	6.25 / 4 x 6.25	6.25 / 4 x 6.25
SPAUI	3.125, 6.25	3.125, 6.25	3.125, 6.25	3.125, 6.25	3.125, 6.25	3.125, 6.25
QDR Infiniband	10	10	-	-	-	-
QPI	6.4	6.4	-	-	-	-
SAS	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	-	1.5, 3, 6
SATA	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	-	1.5, 3, 6
SerialLite II	0.6 – 6.375	0.6 – 6.375	0.6 – 6.375	0.6 – 6.375	0.6 – 6.375	0.6 – 6.375
Serial RapidIO	1.25, 2.5, 3.125, 5, 6.25	1.25, 2.5, 3.125, 5, 6.25	1.25, 2.5, 3.125, 5, 6.25	1.25, 2.5, 3.125, 5, 6.25	1.25, 2.5, 3.125	1.25, 2.5, 3.125
SFI-5.1	2.488 – 3.125	2.488 – 3.125	2.488 – 3.125	2.488 – 3.125	2.488 – 3.125	2.488 – 3.125
SFI-S/SFI-5.2	9.9 – 11.3	9.9 – 11.3	-	9.9 – 11.3	-	-
SONET/SDH	0.155, 0.622, 2.488, 9.953	0.155, 0.622, 2.488, 9.953	0.155, 0.622, 2.488, N/A	0.155, 0.622, 2.488, 9.953	0.155, 0.622, 2.488, N/A	0.155, 0.622, 2.488, N/A
V-by-One	3.75	3.75	3.75	3.75	3.75	3.75

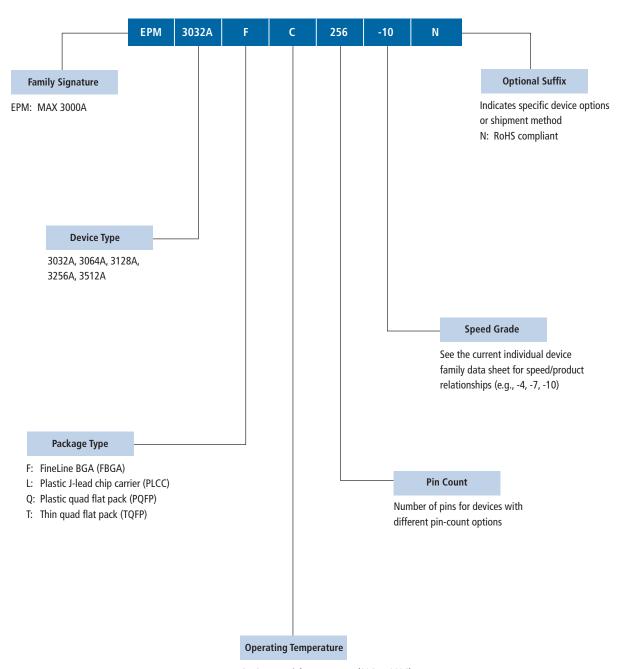
		Proto	cols, Devices, ar	nd Data Rates			
Protocol	Arria V GZ Data Rates (Gbps per Lane)	Arria V GX Data Rates (Gbps per Lane)	Arria V GT Data Rates (Gbps per Lane)	Arria II GX/GT Data Rates (Gbps per Lane)	Cyclone V GX Data Rates (Gbps per Lane)	Cyclone V GT Data Rates (Gbps per Lane)	Cyclone IV GX Data Rates (Gbps per Lane)
HyperTransport 3.0	0.4, 2.4, 2.8, 3.2	0.4, 2.4, 2.8, 3.2	0.4, 2.4, 2.8, 3.2	-	-	-	-
Interlaken	4.976 – 6.375 / 10.6921	3.125 – 6.375	3.125 – 6.375	-	-	-	-
OBSAI	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072, 6.144	0.768, 1.536, 3.072	0.768, 1.536, 3.072	0.768, 1.536, 3.072
PCle Gen1, Gen2, Gen3	2.5, 5, 8	2.5, 5, N/A	2.5, 5, N/A	2.5, 5, N/A	2.5, N/A, N/A	2.5, 5, N/A	2.5, N/A, N/A
SGMII / QSGMII	1.25 / 4 x 1.25	1.25	1.25 / 4 x 1.25	1.25			
RXAUI / DXAUI	6.25 / 4 x 6.25	6.25 / 4 x 6.25	6.25 / 4 x 6.25	-	-	-	-
SPAUI	6.375	-	-	3.125	-	-	-
QDR Infiniband	10	-	-	-	-	-	-
QPI	4, 4, 8, 6.4, 8	-	-	-	-	-	-
SAS	3, 6	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	-	-	-
SATA	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	1.5, 3, 6	1.5, 3	1.5, 3	1.5, 3
SerialLite II	-	0.6 – 6.375	0.6 – 6.375	0.6 – 3.75	-	-	-
Serial RapidIO	1.25, 2.5, 3.125, 5 - 6.25	1.25, 2.5, 3.125, 5, 6.25	1.25, 2.5, 3.125, 5, 6.25	1.25, 2.5, 3.125	1.25, 2.5, 3.125	1.25, 2.5, 3.125	1.25, 2.5, 3.125
SFI-5.1	2.488 – 3.125	2.488 – 3.125	2.488 – 3.125	-	-	-	-
SFI-S/SFI-5.2	9.95 – 11.1	-	-	-	-	-	-
SFP+	8.5 – 11.32	-	-	-	-	-	-
XFP	9.95328 – 11.32	-	-	-	-	-	-
SONET/SDH	0.622 – 2.488, 9.95	0.155, 0.622, 2.488, N/A	0.155, 0.622, 2.488, N/A	0.155, 0.622, 2.488, N/A	-	-	-
V-by-One	-	3.75	3.75	-	3	3.75	3
8G FC	8.5	-	-	-	-	-	-
4G FC	4.25	-	-	-	-	-	-
OTU-2/OUT-3/OUT-4	10.709/ 10.7545/11.2	3.75	3.75	-	3	3.75	3

### **Configuration Devices**

The following is an overview of our configuration devices. To determine the right configuration device for your FPGA, check out our Configuration Handbook or the configuration chapter in the handbook of your selected FPGA.

Altera's serial configuration devices store the configuration file for our SRAM-based FPGAs. We designed our serial configuration devices to minimize cost and board space while providing a dedicated FPGA configuration solution. Serial configuration devices are recommended for new designs. For information on additional configuration devices supporting older products, see our Configuration Handbook.

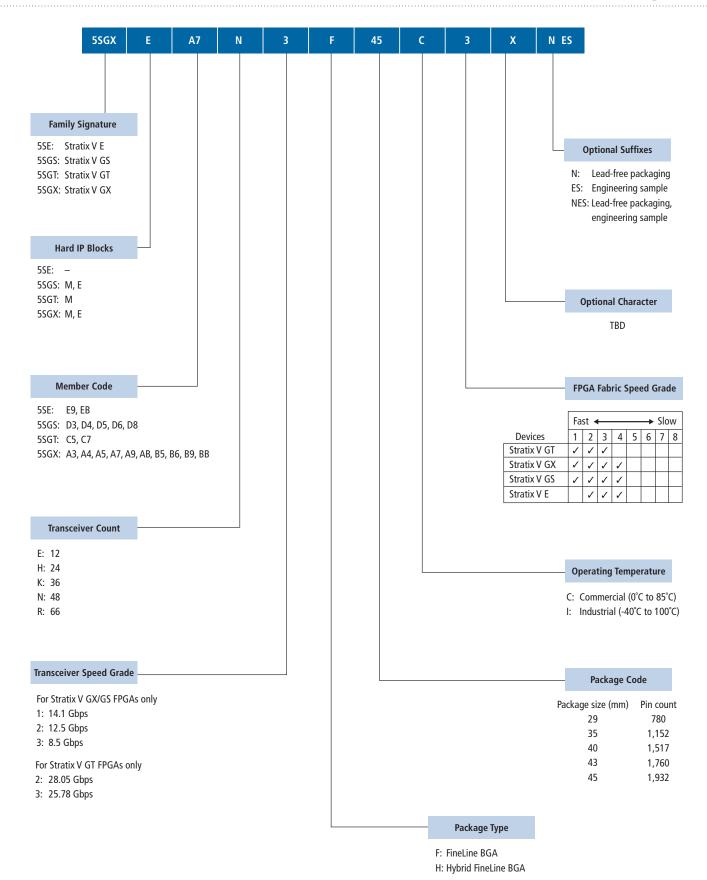
Serial Configuration Device	Memory Size (bits)	Package
EPCS4	4,194,304	SOIC8
EPCS16	16,777,216	SOIC8
EPCS64	67,108,864	SOIC16
EPCS128	134,217,728	SOIC16
EPCQ256	268,435,456	SOIC16

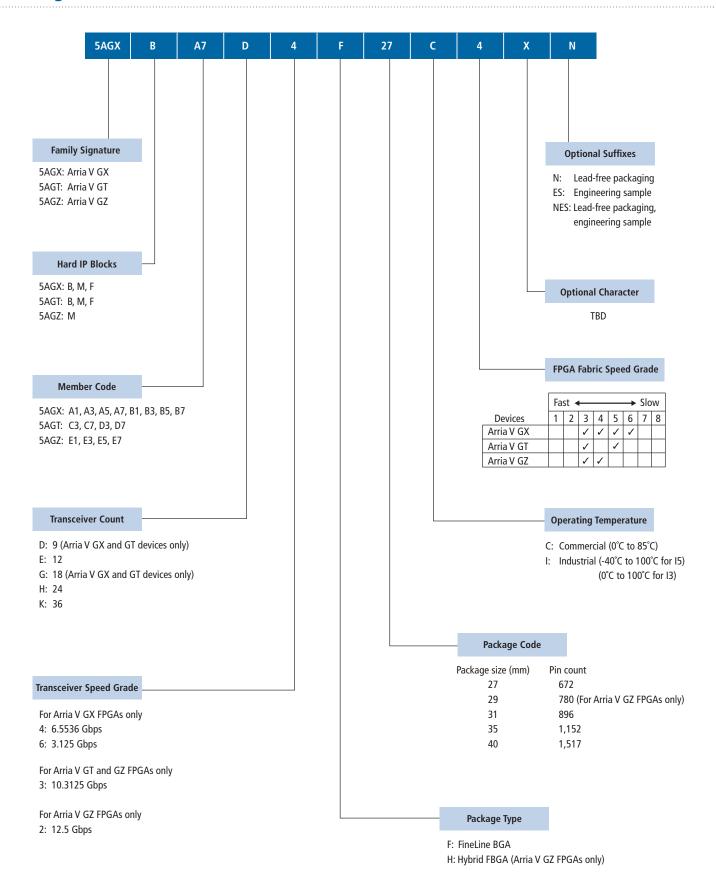


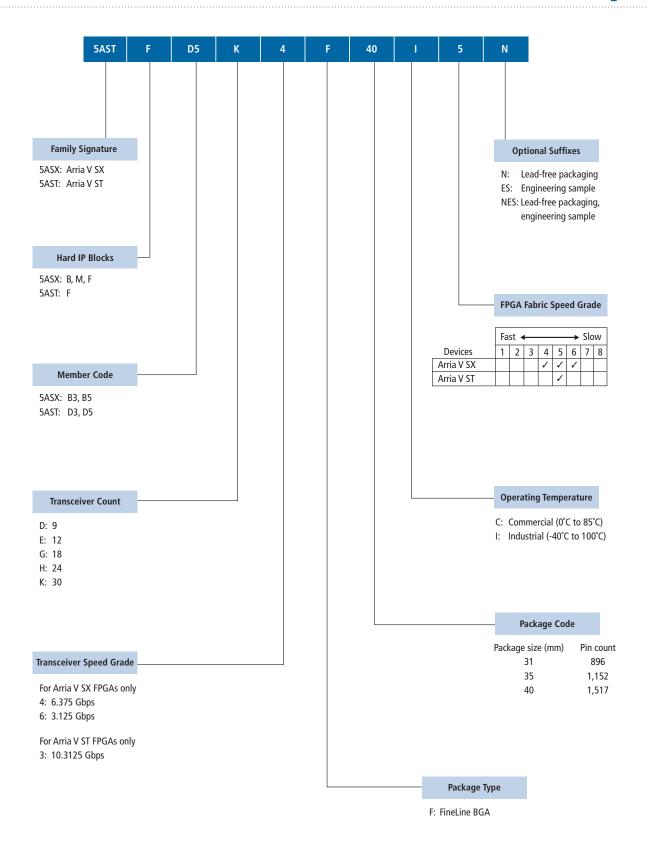
C: Commercial temperature (0°C to 90°C)

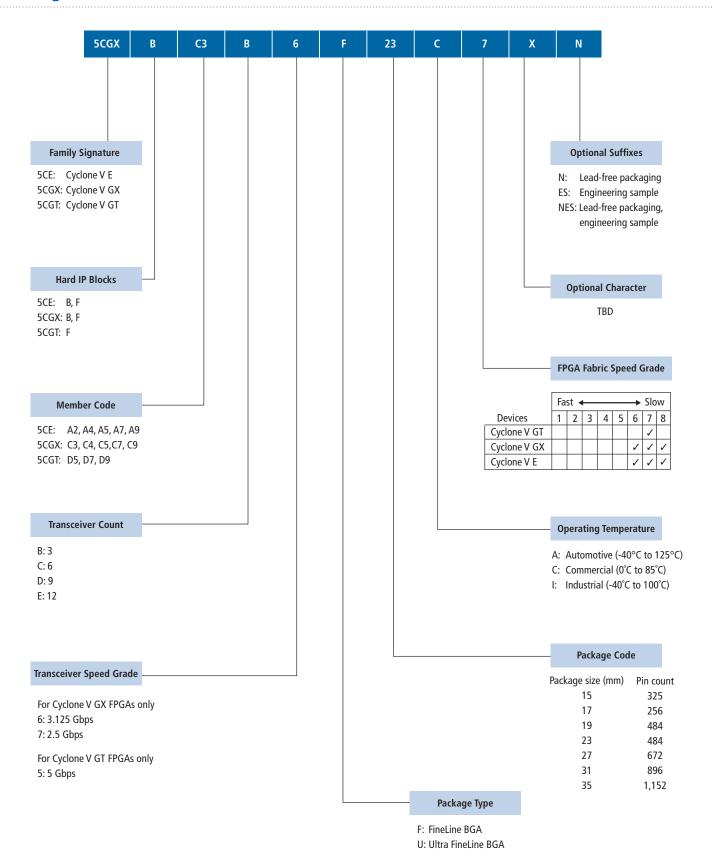
I: Industrial temperature (-40°C to 105°C)

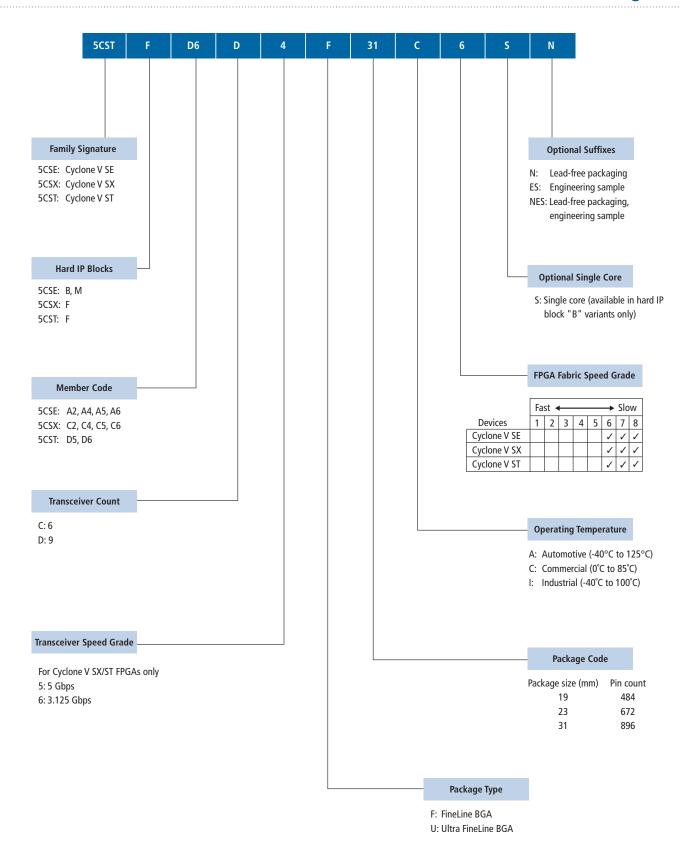
EP1S				EP1S 25 F 780 C					N								
Family Sign	ature										0	ptio	nal	Suf	fix		
M: MAX VERM: MAX VERM: MAX VERM: Cyclor	II ne IV E									or s ES:	shipr Eng	es sp ment inee IS co	t me ring	thod sam	l iple	opt	io:
EP3CLS: Cyclor EP3C: Cyclor	ne III LS									-		Spe	eed	Gra	de		
EP2C: Cyclor	ne II									_							_
P1C: Cyclor										-	ast	<b>+</b>	_			low	_
EP2AGZ: Arria I EP2AGX: Arria I									Devices MAX V	1	2	3	4	5	6	7	8
P1AGX: Arria (									MAX II	+		1	1	1			
P4SE: Stration									Cyclone IV E	+		-	-	-	1	/	1
P4SGX: Strativ									Cyclone IV GX	-					1	$\rightarrow$	_
	(IV GT								Cyclone III LS	-			-		-	/	<b>√</b>
P3SL: Stratio	(III L														/	1	1
P3SE: Stratio	( III E								Cyclone III	+					1	/	Ć
P2S: Stration	( II															$\dashv$	Ĺ
P2SGX: Stration									Cyclone Arria II GZ	+	-	1	1	H	1	/	_
P1S: Stration												-	+	_	,		
P1SGX: Stration									Arria II GX Arria GX			1	1	1	1		_
IC4E: HardC IC4GX: HardC	copy IV E								Stratix IV E		<b>-</b>	_	-		1		_
1C4GX. HardC									Stratix IV GX		1	1	1				_
HC2: HardC									Stratix IV GX	+	1	1	1			$\dashv$	_
									Stratix III L	1	1	_	<u> </u>			+	
									Stratix III E	-	1	1	1			+	_
Device Ty	ype		_						Stratix II		ļ ,	1	1	/		-	
5M: 40, 80	, 160, 240, 570, 127	70, 2210							Stratix II GX			1	1	/			
	70,1270, 2210	,							Stratix			Ť	Ť	1	/	/	
EP4CE: 6, 10,	15, 30, 40, 55, 75, 1	15							Stratix GX					1	1	/	
	, 30, 50, 75, 110, 15	50							Julius Ort					•		•	
	10, 150, 200 16, 25, 40, 55, 80, 1 A, 15A, 20, 20A, 35								Operating Ter	nper	atur	e					
	,12, 20	, 30, 70							A: Automotive	grad	e (-4	40°C	c to	125	°C)		
EP2AGZ: 225, 3									C: Commercial								
EP2AGX: 20, 30	, 45, 65, 95, 125, 19	90, 260							I: Industrial te								
EP1AGX: 20, 35									M: Military tem	pera	ture	(-55	5°C	to 1	25°(	<b>C</b> )	
	30, 290, 360, 530, 8 0, 230, 290, 360, 53							- 1	Pin Count								
EP4S: 40G, 1 EP3SL: 50, 70	00G , 110, 150, 200, 340	)		Packag	је Туре			Number	of pins for device	es w	ith c	diffe	rent	pin	-cou	nt c	op¹
	, 110, 260		R∙ R	all-grid	arrav			Note: Ct	rativ IV F. Ct	N/ C	v	+	., n	· CŦ		١٨	۔: ـ
EP2S: 15, 30 EP2SGX: 30, 60	, 60, 90, 130,180 , 90, 130		E: E	nhanced	d thin quad	flat pack			atix IV E, Stratix use package size							ı Arı	па
	, 25, 30, 40, 60, 80		I	ineLine I				Package	type/size: Pa	ckag	e tv	ne/n	in c	Olin.	t·		
P1SGX: 10, 25			I	•	neLine BGA	١		F29/H29		80/H			C	Juil			
HC4E: 25, 35			I	1icro BG		J.		F35/H35		152/							
HC4GX: 15, 25			I	-	ıad flat pac	.K		F40/H40		517/							
1C3: 25, 35			I		d flat pack			F43		760		.,					
IC2: 10W,	10, 20, 30, 40		U: U	itra Fine	Line BGA			F45		932							
Transceiver C	ount							Prod	uct-Line Suffix								
	nased FPGAs (GX/G7	Z/GT) only															
or transceiver-b								COLIVIA)	( II devices only								
	G: 20									+-~-							
2: 4 D: 8	G: 20 H: 24							Indicate	s device core vo	tage							
For transceiver-b C: 4 D: 8 E: 12 F: 16	G: 20							Indicate G: 1.8V									

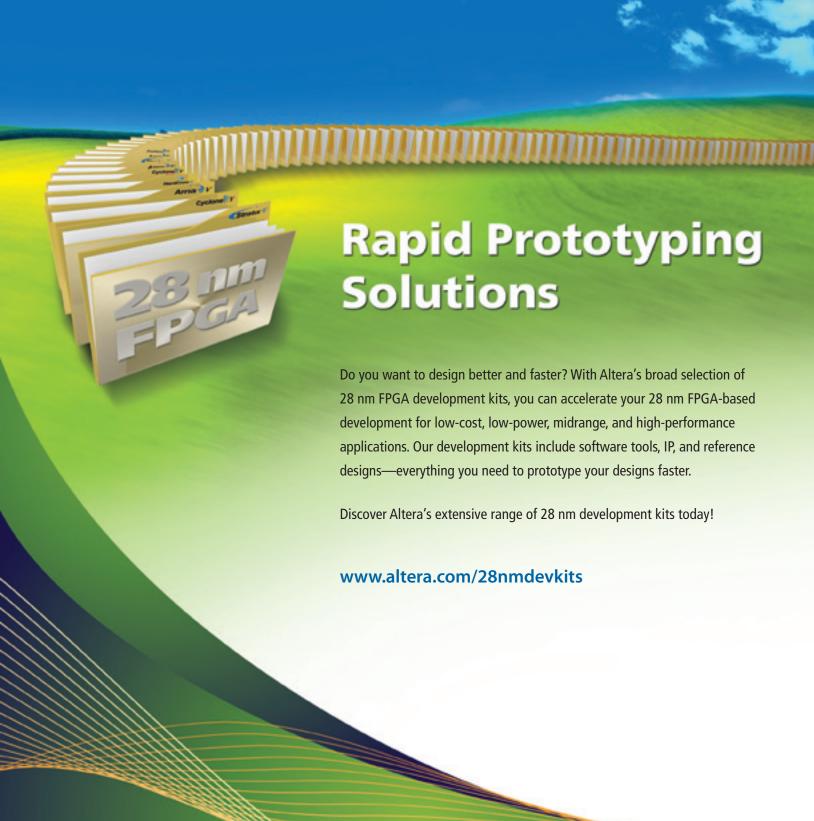




















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